

Selek 15" Schematic

CFL-H refresh

2019/04/03

REV : A00

DY : None Installed
UMA: UMA only installed
OPS: DISCRTE OPTIMUS installed

Selek CFLH N17P



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Cover Page

Size
A4

Document Number

Selek CFL-H

Rev

A00

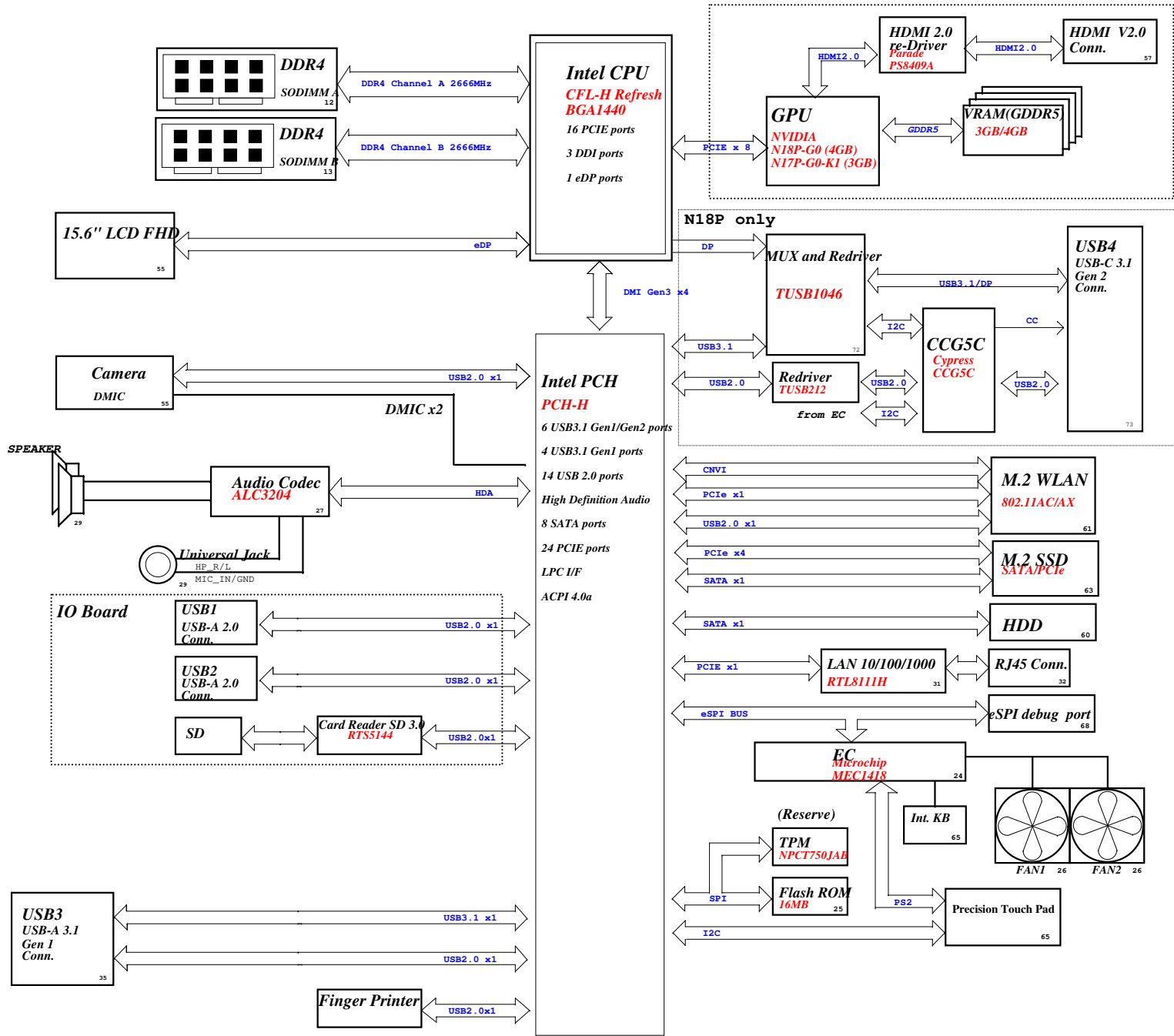
Date: Wednesday, April 03, 2019

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Project Code : 4PD0H7010001
PCB P/N : 18825-1
Revision : A00

Selek CFL-H refresh Block Diagram

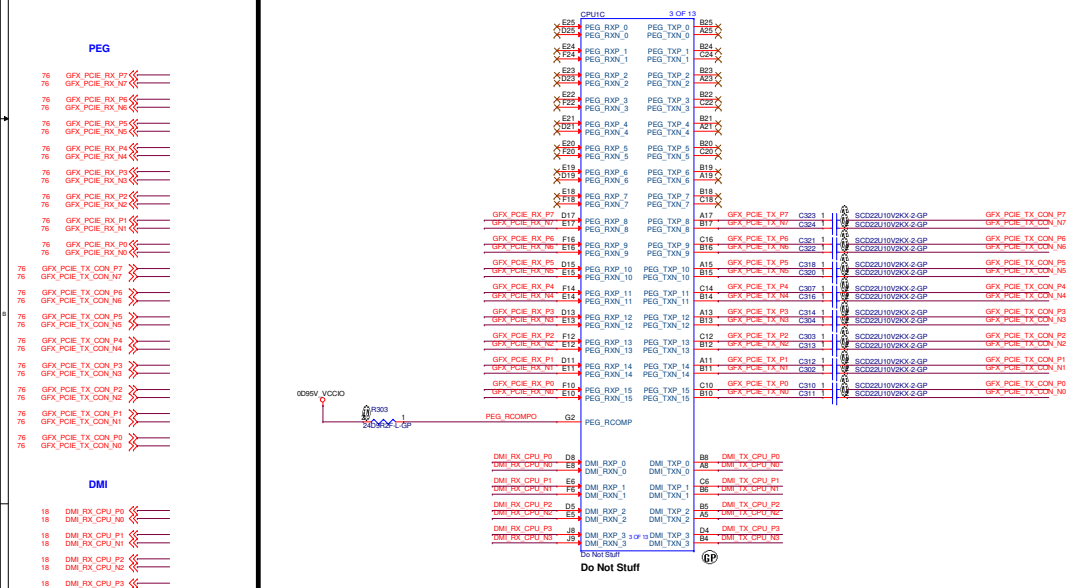
GPU



CHARGER	
ISL88739	44
INPUTS	OUTPUTS
AD+	DCBATOUT
BT+	
SYSTEM DC/DC	
TPS51225RUKR-GP	45
INPUTS	OUTPUTS
3D3V PWR	3D3V S5
5V PWR	5V S5
DCBATOUT	
CPU Core Power	
NCPS1208MNTXG	46-50
NCPS1382MNTXG x 2	
NCPS1382MNTXG (23e)	
NCPS1253MNTBG	
INPUTS	OUTPUTS
DCBATOUT	VCC CORE
DCBATOUT	+VCCGT
DCBATOUT	+VCCGT (23e)
DCBATOUT	+VCCSA
DDR4 SUS	
RT8231AGQW-GP	
AP15930KAI-TRG	51
INPUTS	OUTPUTS
DCBATOUT	1D2V S3
3D3V S5	3D3V S5
2D5V S3	
CPU VCCPRIM_CORE 1V	
	11
INPUTS	OUTPUTS
1D0V S5	+VCCPRIM CORE
CPU DCDC-V1D00A	
AO22262QI-10-GP-U	53
INPUTS	OUTPUTS
DCBATOUT	1D0V S5
LDO-V1D8V	
APL5930KAI-TRG	54
INPUTS	OUTPUTS
3D3V S5	1D8V S5
5V/3V S0	
TPS22966DPUR-GP	40
INPUTS	OUTPUTS
5V_S0	5V_S0
3D3V_S5	3D3V_S0
EOP10/EDRAM (23e)	
TPS22961DNYT	40
INPUTS	OUTPUTS
1D0V_S5	+V_EDRAM_VR
1D0V_S5	+V_EOP10_VR
3D3V VGA	
AO3419L	86
INPUTS	OUTPUTS
3D3V_S0	3D3V_VGA_S0
VGA CORE	
ISL62771HRTZ-GP-U	85
INPUTS	OUTPUTS
DCBATOUT	VGA_CORE
1D5V_VGA_S0	
Y8288RAC-GP	86
INPUTS	OUTPUTS
DCBATOUT	1D5V_VGA_S0

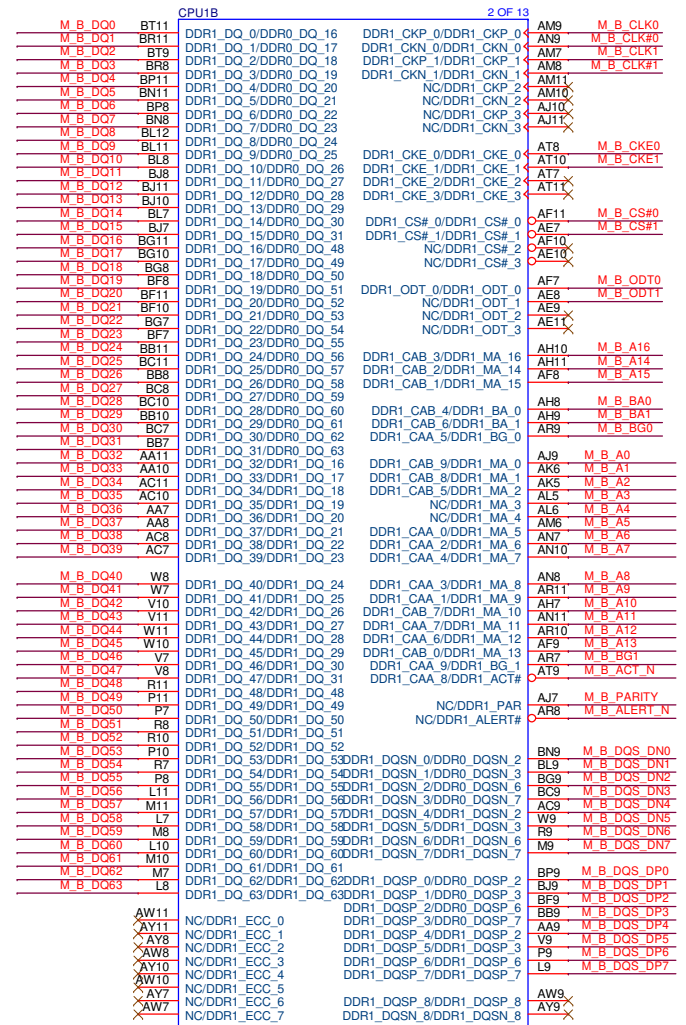
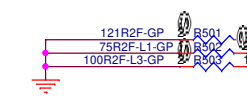
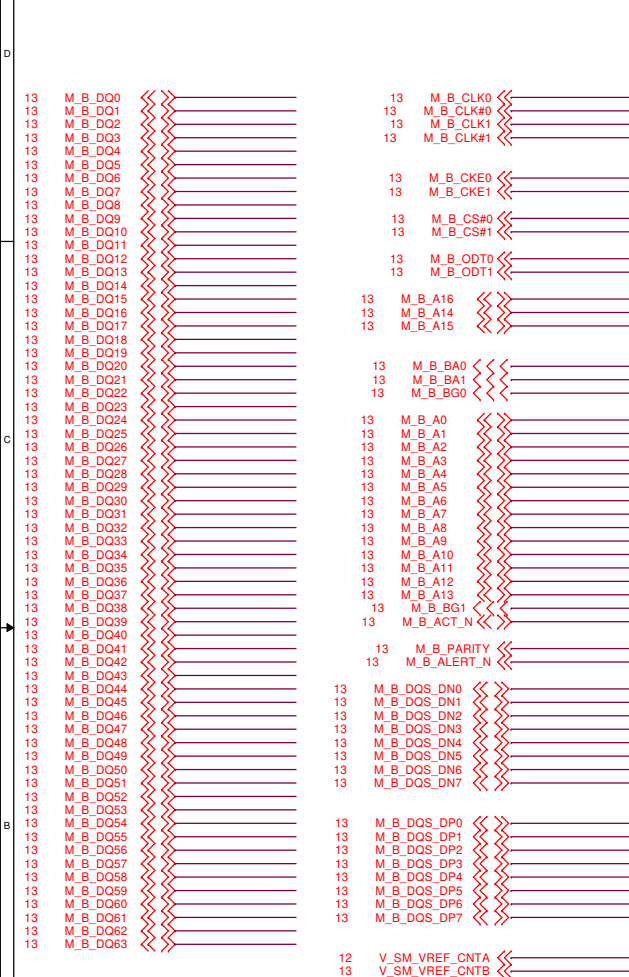
Selek CFL-H N17P

DMI



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SSID = CPU



AROUND_CPU

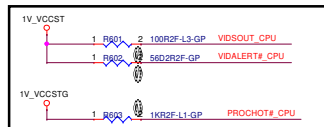
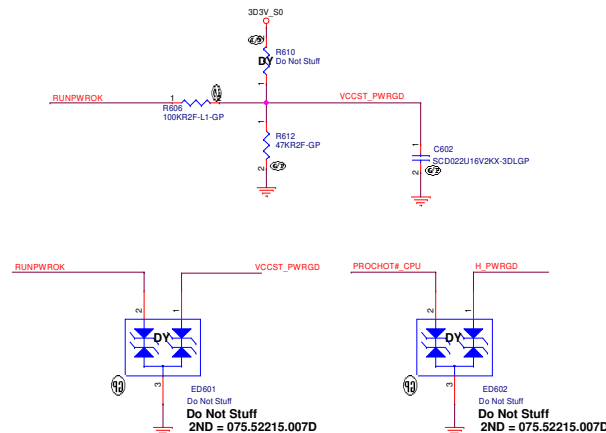


Table 13-14. SVID Bus Routing Guidelines

Signal	W1 [inches]	W2 [inches]	W3/4/5 [inches]	W2+W3+W4+W5 [inches]	W51 [inches]	W52 [inches]	R _{PULL} [Ω]	R _{OUT} [Ω]	R _L [Ω]	R _S [Ω]	V _{CC} [V]
VIDSOUT							100	100	0	10	
VIDSCK	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	Empty	45	0	50	1.0
VIDALERT#							56	Empty	220	0	

Note: For additional information regarding SVID and power management refer to "Power Architecture Guide".



GPD11 pull high by Intel PDG1.3 request

Signal	Value
CFG2	1: Normal Operation; Lane # definition matches socket pin map definition 0: Lane Reversed

Signal	Value
CFG4	1: Disable 0: Enable

Signal	Value
CFG7	1: (default) PEG Train immediately following RESET# de assertion 0 = PEG Wait for BIOS for training.

Signal	Value
CFG4	1: Disable 0: Enable (Set DXF enables bit in debug)

Signal	Value
CFG[6:5]	11: x16 - Device 1 functions 1 and 2 disabled 10: x8, x8 - Device 1 function 1 enabled, function 2 disabled 01: Reserved - (Device 1 function 1 disabled, function 2 enabled) 00: x8, x4, x4 - Device 1 functions 1 and 2 enabled



Processor Internal Pull-Up / Pull-Down Terminations

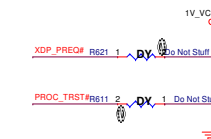
Processor Internal Pull-Up / Pull-Down Terminations

Signal Name	Pull Up/Pull Down	Rail	Value
BPM[3:0]	Pull Up	VCC _{IO}	16-60 Ω
PREQ#	Pull Up	VCC _{ST}	3 kΩ
PROC_TDI	Pull Up	VCC _{STG} ¹	3 kΩ
PROC_TMS	Pull Up	VCC _{STG} ¹	3 kΩ
CFG[19:0]	Pull Up	VCC _{IO}	3 kΩ

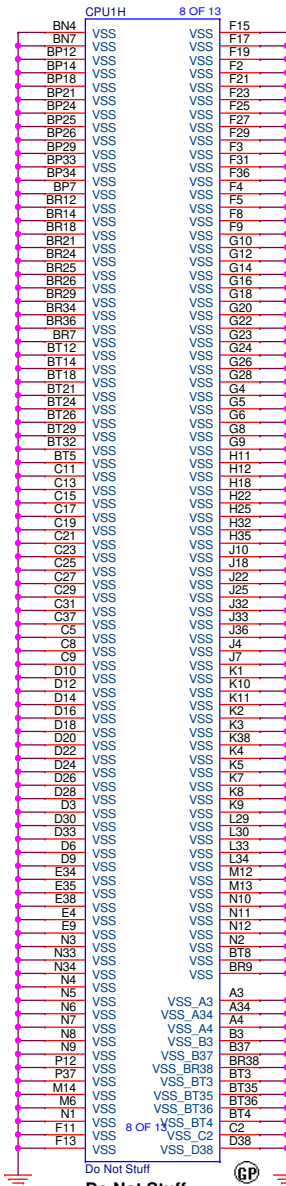
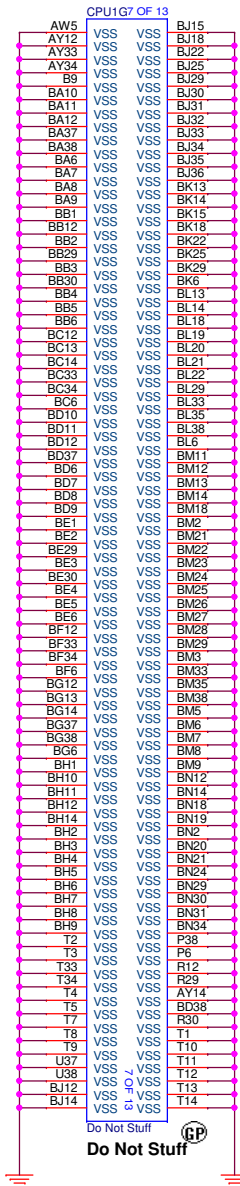
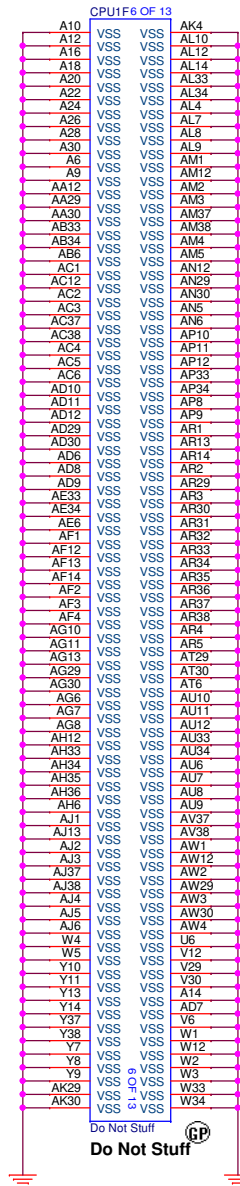
Note:
1. For SKL-S it should be VCC_{ST}

Table 6-8. Reset and Miscellaneous Signals

Signal Name	Description	Dir.	Buffer Type	Link Type	Availability
CFG[19:0]	<p>Configuration Signals: The CFG signals have a default value of '1' if not terminated on the board. Refer to the appropriate platform design guide for pull-down recommendations when a logic low is desired.</p> <p>Intel recommends placing test points on the board for CFG pins.</p> <ul style="list-style-type: none"> CFG[0]: Shall reset sequence after PCU PLL lock until de-asserted. <ul style="list-style-type: none"> 1 = (Default) Normal Operation; 0 = Stall. CFG[1]: Reserved configuration lane. CFG[2]: PCI Express® Static x16 Lane Numbering Reversal. <ul style="list-style-type: none"> 1 = Normal operation 0 = Lane numbers reversed. CFG[3]: Reserved configuration lane. CFG[4]: eDP enable. <ul style="list-style-type: none"> 1 = Disabled. 0 = Enabled. CFG[6:5]: PCI Express® Bifurcation <ul style="list-style-type: none"> 00 = 1 x8, 2 x4 PCI Express* 01 = reserved 10 = 2 x8 PCI Express* 11 = 1 x16 PCI Express* CFG[7]: PEG Training. <ul style="list-style-type: none"> 1 = (default) PEG Train immediately following RESET# de assertion. 0 = PEG Wait for BIOS for training. CFG[19:8]: Reserved configuration lanes. 	I/O	GTL		All processor lanes. CFG[2], CFG[6:5] and CFG[7] are relevant for H and S-processor line only and test point may be placed on the board for them.

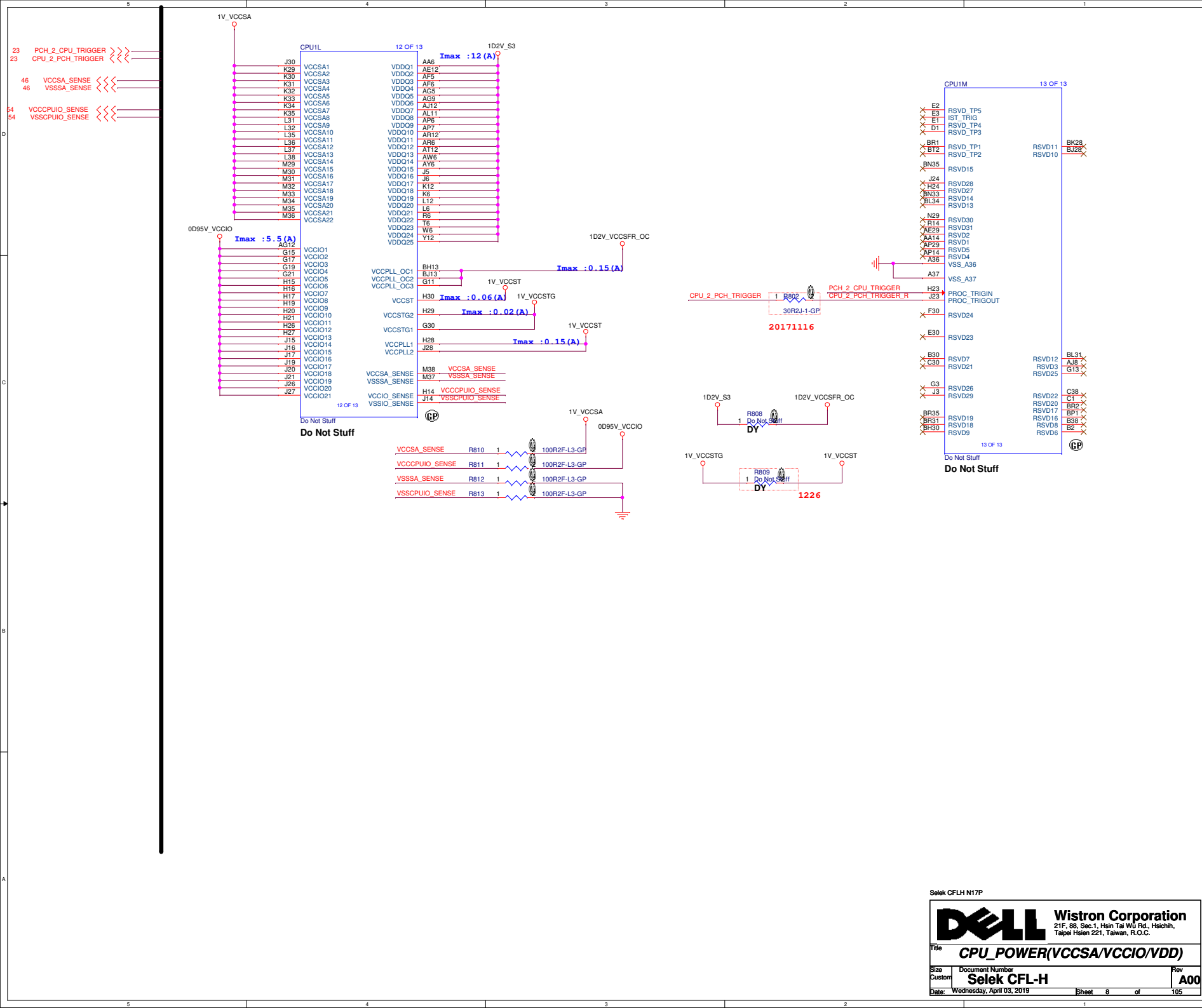


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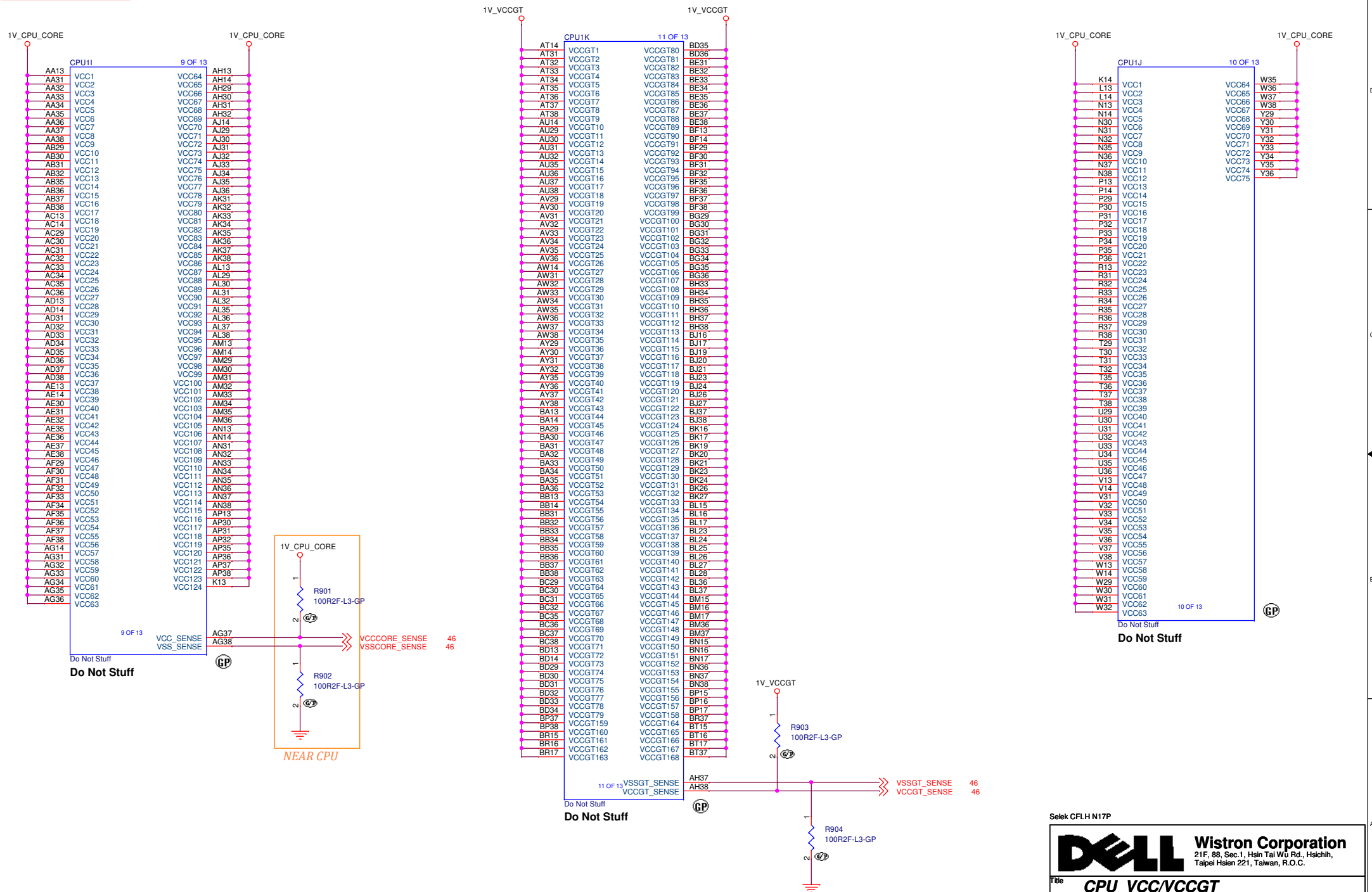


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Title CPU_GND			
Size A3	Document Number	Rev	
Selek CFL-H		A00	
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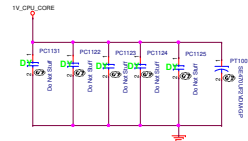
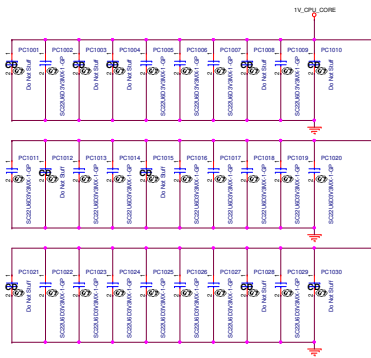
SSID = CPU

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VCORE

CFL-H_45W

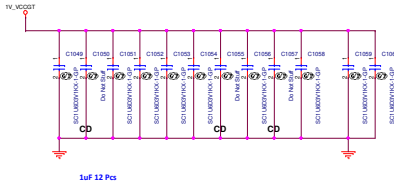
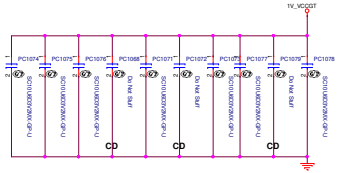
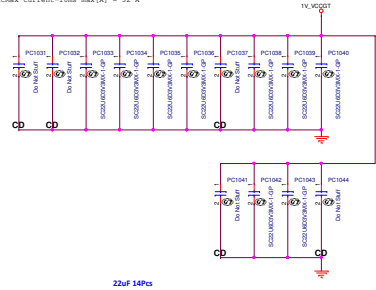
H-Line 45W
IcoMax current=10ma max = 128A



VCCGT

CFL-H_45W

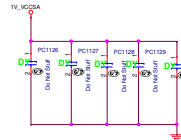
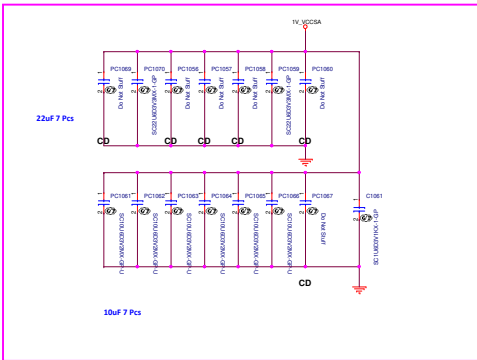
IcoMax current=10ma max(A) = 32 A



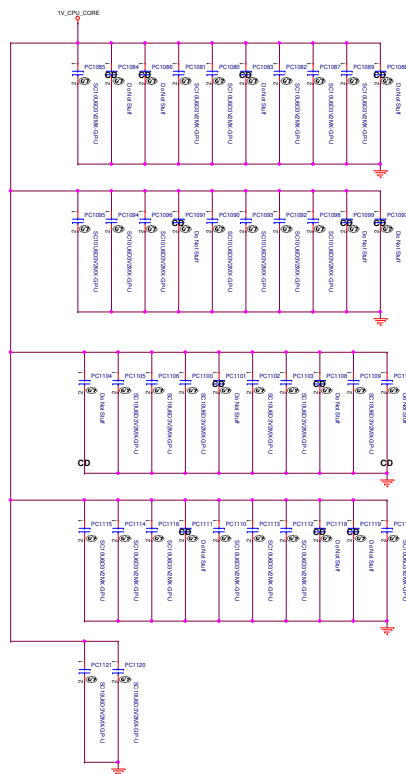
VCCSA

H-Line

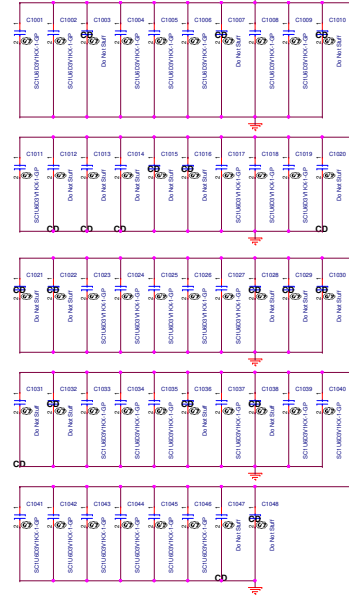
IcoMax current=10ma max(A) = 11.1 A



10uF 42Pcs



1uF 48 Pcs



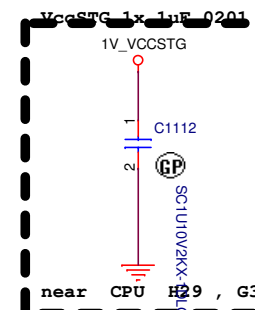
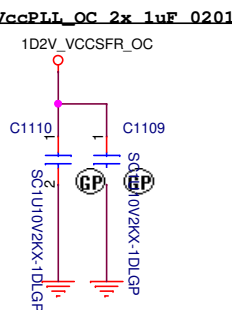
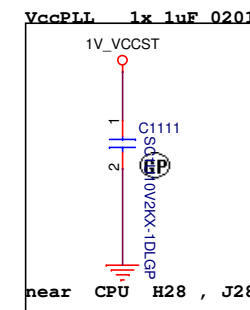
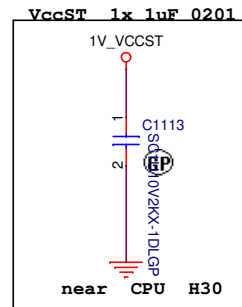
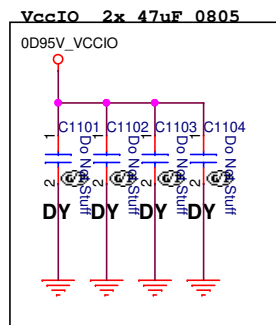
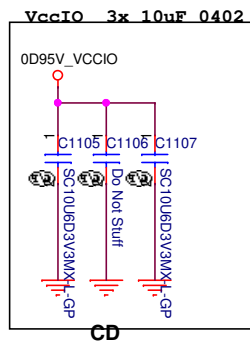
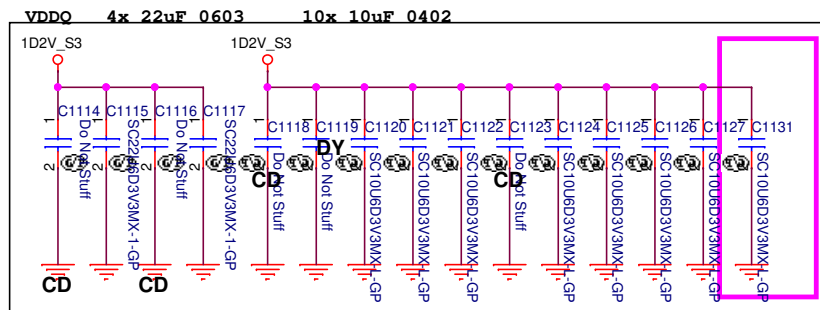


Table 50-5. Decoupling Requirements for CFL H 8+2 Processor (Sheet 1 of 2)

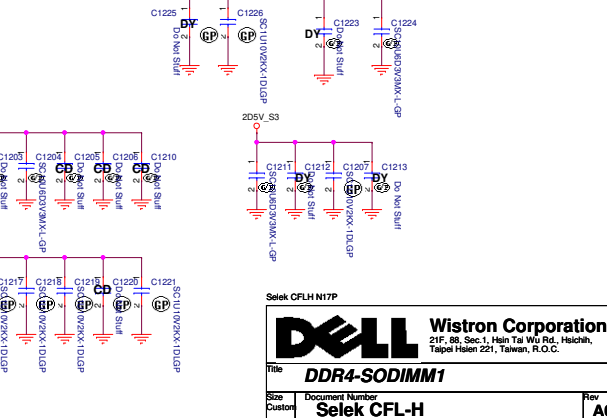
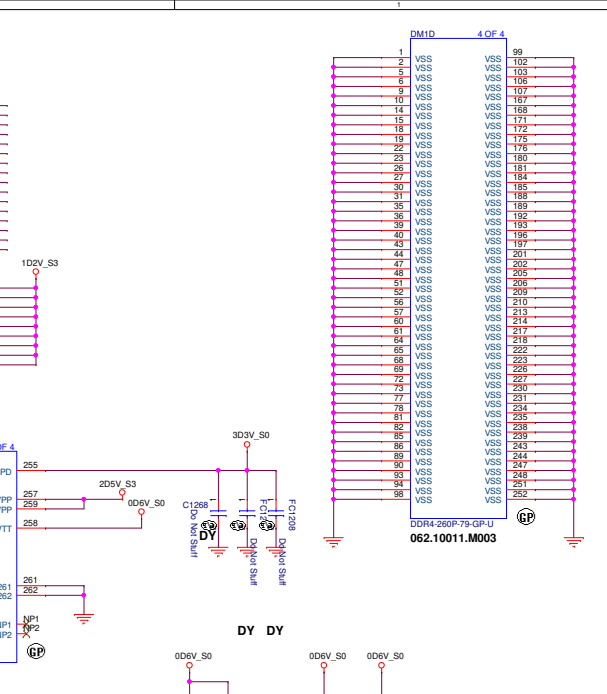
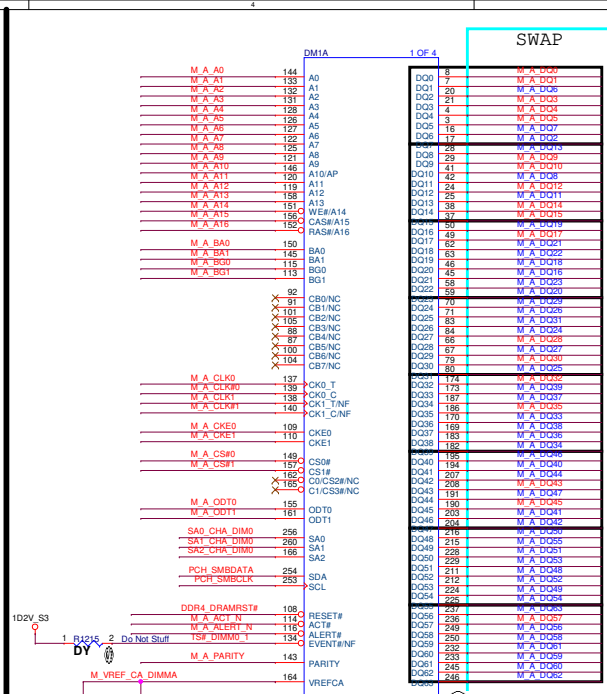
Domain	Board Edge cap	Backside cap	Notes
Vcc	2x 22uF 0603		
	8x 47uF 0805		
		48x 1uF 0201	
		42x 10uF 0402	
		10x 22uF 0603	
VccGT	3x 47uF 0805		Place as close to the BGA as possible
	7x 22uF 0603		
		10x 10uF 0402	
		12x 1uF 0201	
VccSA	2x 47uF 0805		
	2x 22uF 0603		
		7x 10uF 0402	
VDDQ		1x 1uF 0201	
		4x 22uF 0603	
		11x 10uF 0402	
VccIO		3x 10uF 0402	
VccST		1x 1uF 0201	Additional capacitors might be needed if the connectivity from BGAs to capacitors is not adequate.
VccSTG		1x 1uF 0201	Must be Ground referenced. Board routing resistance from BGA to Power gate should be less than 10mOhm. Do not route VccGT closest adjacent layer over any power net other than ground.
VccPLL		1x 1uF 0201	Must be Ground referenced. Share with 1.0V PCH rail. Board resistance from BGA to Power gate should be less than 130mOhm.
		1x 22uF/47uF 0805 (placeholder)	*Placeholder not stuffed. To be placed as close as possible to BGA (H28, J28) and be placed either at board edge or backside.
Domain	Board Edge cap	Backside cap	Notes
VccPLL_OC		2x 1uF 0201	Must be Ground referenced. Share with VDDQ. Board resistance from BGA to Power gate should be less than 86mOhm.

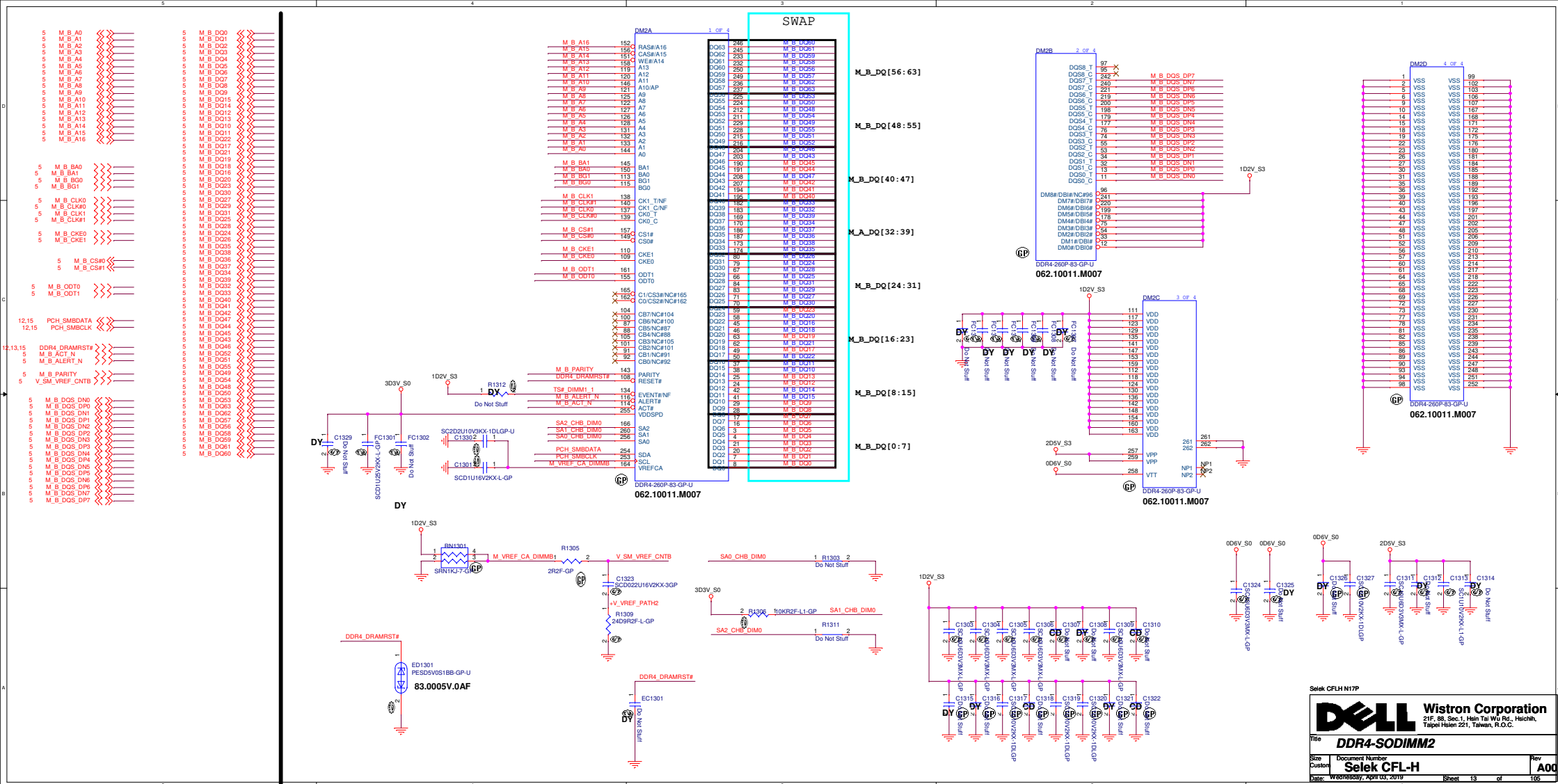
Note: High Current Rail assuming 600KHz for VR bandwidth. Higher VR bandwidth assumptions results in lower quantity of MLCC (0805/0603) to meet the same AC loadline.

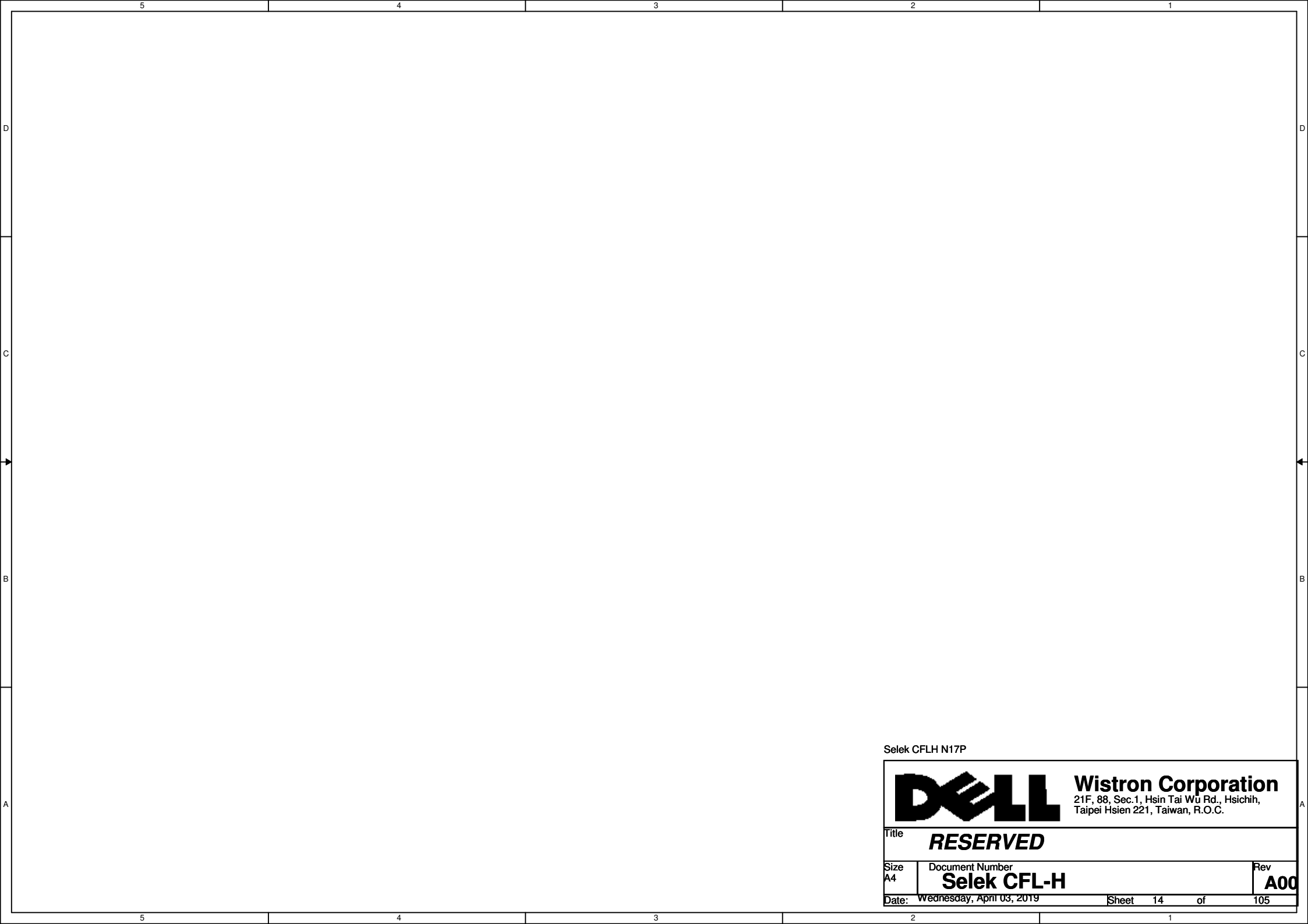
Note: It is important to make sure that the noise on VCCPLL rail must be limited to the +/-5% VR specification below 150KHz - as this will potentially impact the PLL failing to phase lock. Where necessary, the 0805 placeholder can be stuffed with a 22uF or 47uF to assist noise reduction. While stuffing the 0805 cap may reduce noise coupling, one should still route the PLL rail carefully (i.e. to avoid noisy and high current rail) to mitigate any potential issue.

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Title CPU (Power CAP2)			
Size Custom	Document Number Selek CFL-H		Rev A00
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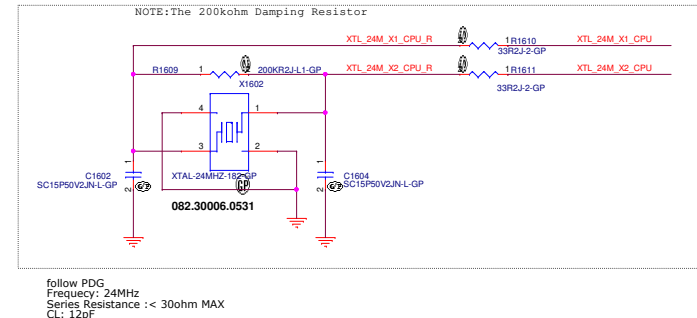
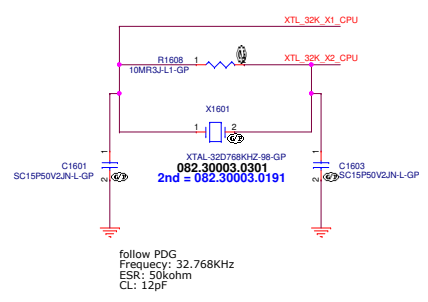
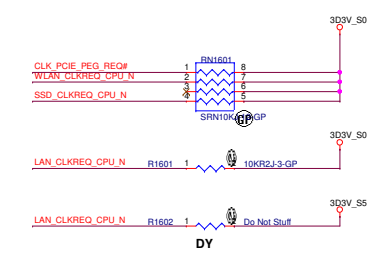
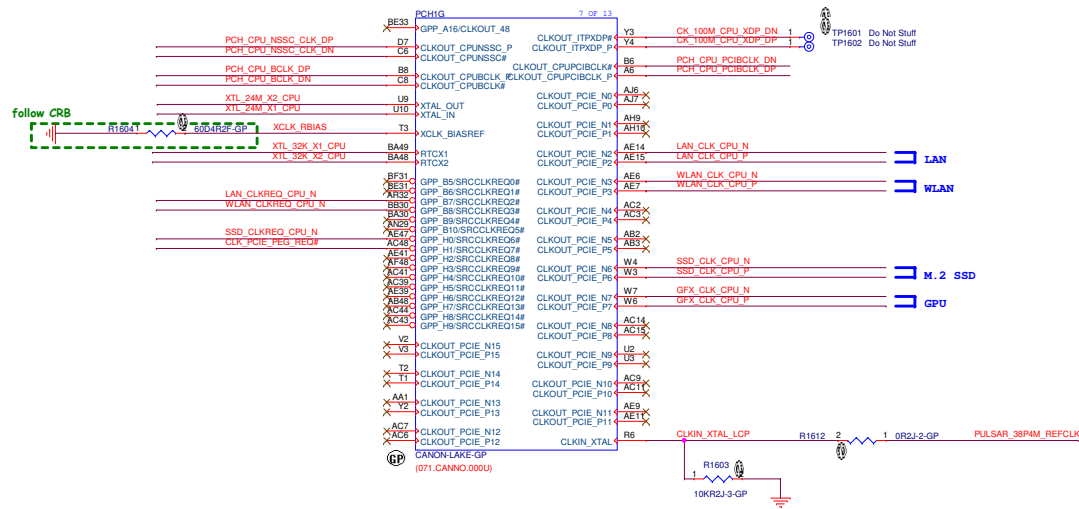
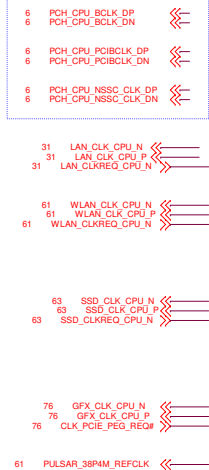




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Size A4	Document Number Selek CFL-H		Rev A00
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TO CPU CLOCK



24 MHz Crystal Specifications (Sheet 1 of 2)

Parameter	Values	Units	Max/Min Range
Frequency	24	MHz	
Frequency Tolerance	± 100	PPM	
Duty Cycle Variation	+/- 5	%	
Pk to Pk jitter	± 150	pS	Includes cycle to cycle and period
Operating Temperature	-40 to 85	°C	

Parameter	Values	Units	Max/Min Range
Series Resistance	≤ 30	Ω	
Aging	±3	PPM	

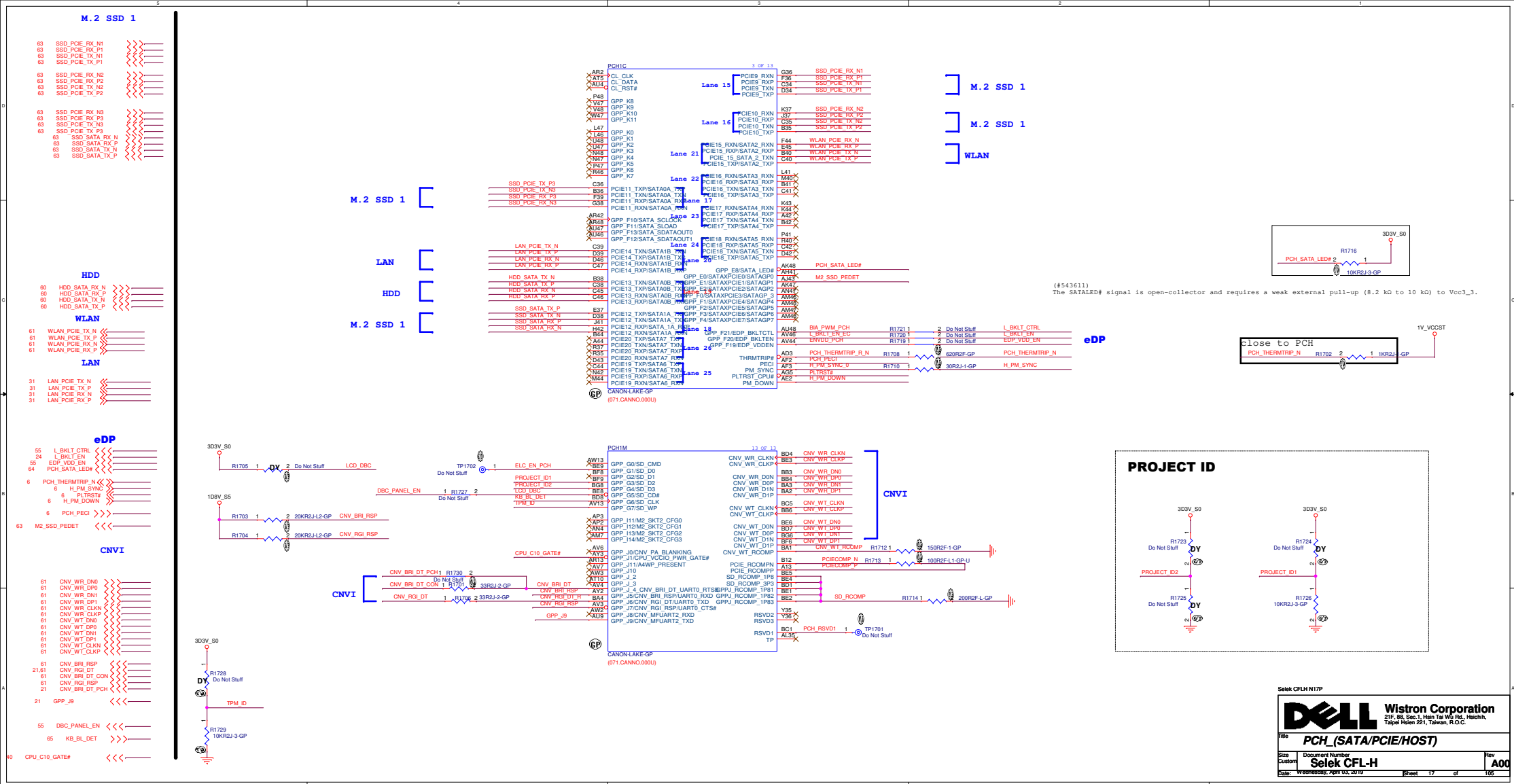
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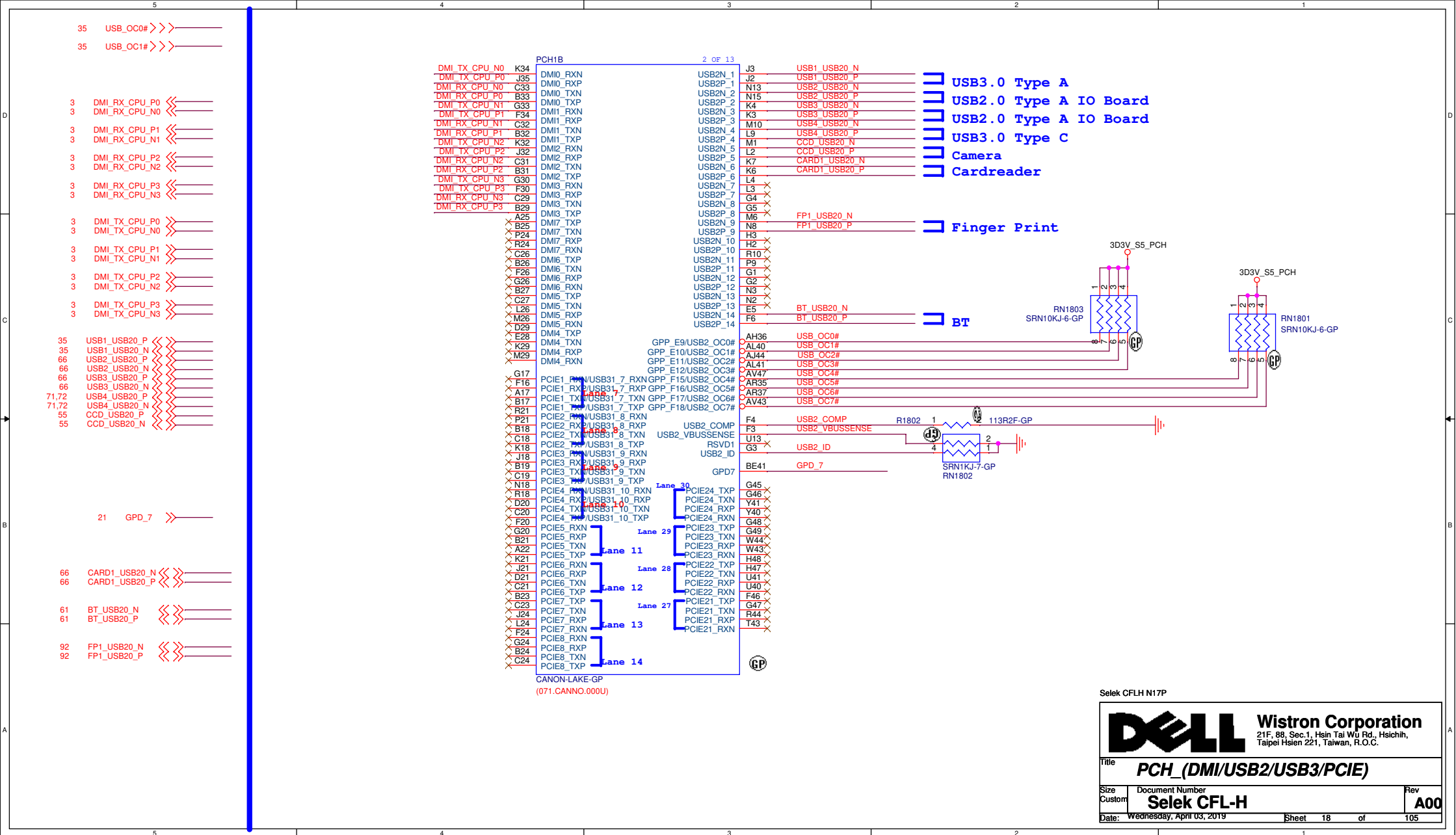
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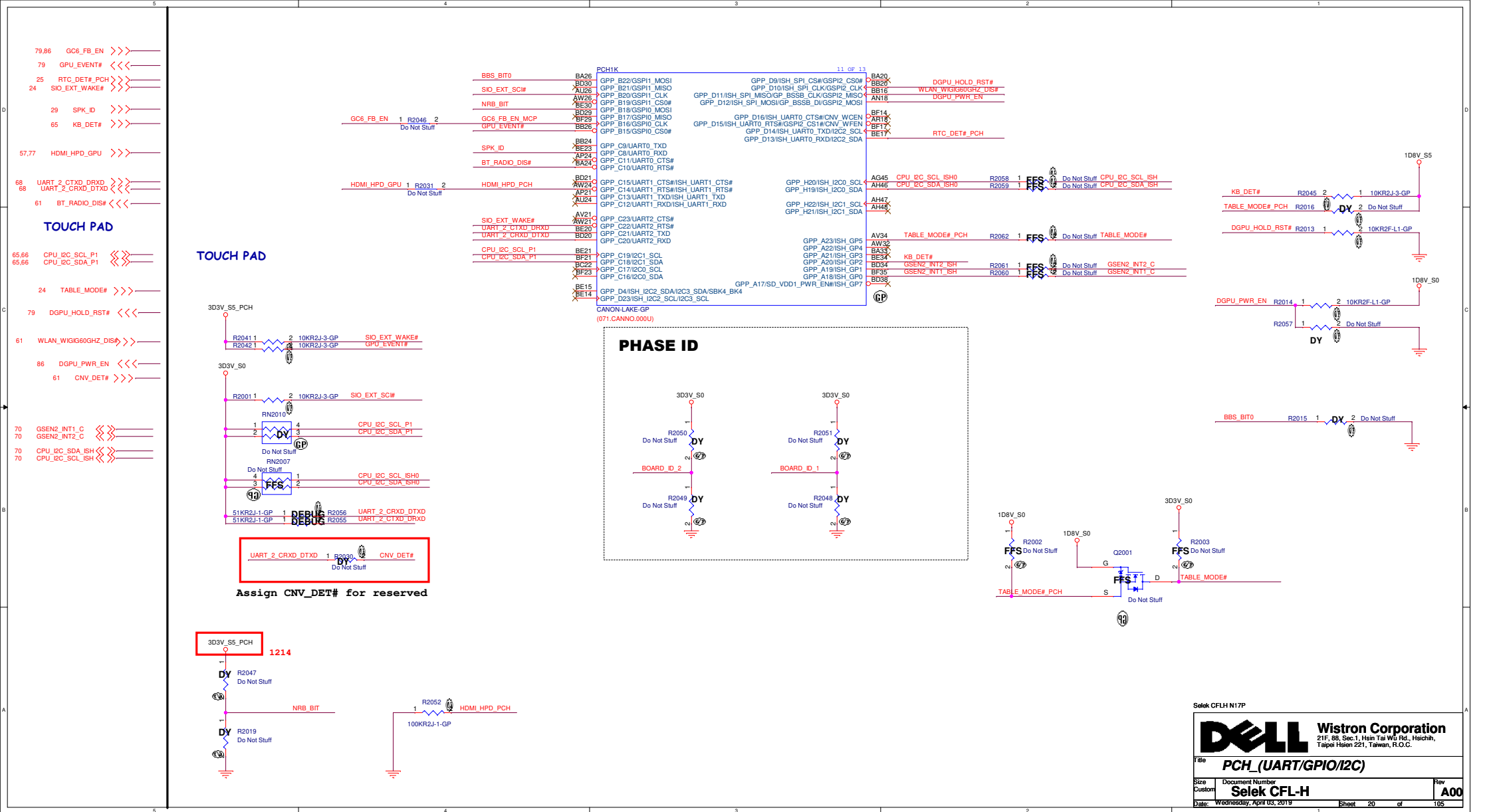
Title **PCH (CLK)**

Size Custom Document Number **Selek CFL-H** Rev **A00**

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GPIO	GPP_B14 SPKR	GPP_B18 GSPIO_MOSI	GPP_C2 SMBALERT#	GPP_B22 GSPII_MOSI	GPP_C5 SMBALERT#	SPIO_MOSI SPIO_MISO	GPP_H15 SML3ALERT#
Schematic		default is internal pull down add TP at PCH side		default is internal pull down add TP at PCH side			

GPIO	GPP_B23 SML1ALERT# PCHHOT#	SPIO_IO2	SPIO_IO3	HDA_SDO/ I2S0_TXD	GPP_H12 SML2ALERT#	GPP_I6 DDPB_CTRLDATA	GPP_I8 DDPC_CTRLDATA
Schematic					internal pull down	Pull high at page 19	internal pull down

need check the latest CRB,PDG

GPIO	GPP_I10	GPP_F23/ DPPF_CTRLDATA	GPP_J4 CNV_BRI_DT UART0_RTS#	GPP_J6 CNV_RGI_DT UART0_TXD	GPP_J9	GPDI7	
Schematic		internal pull down					

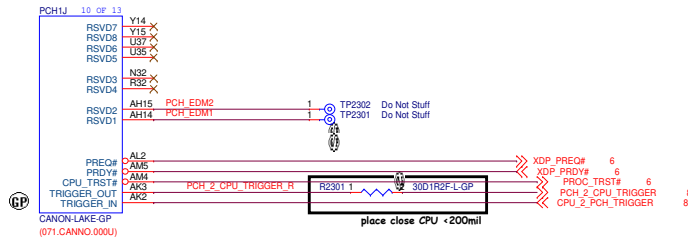
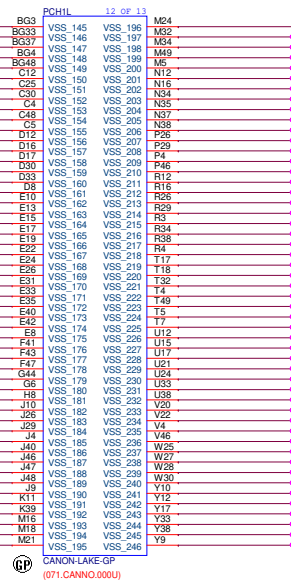
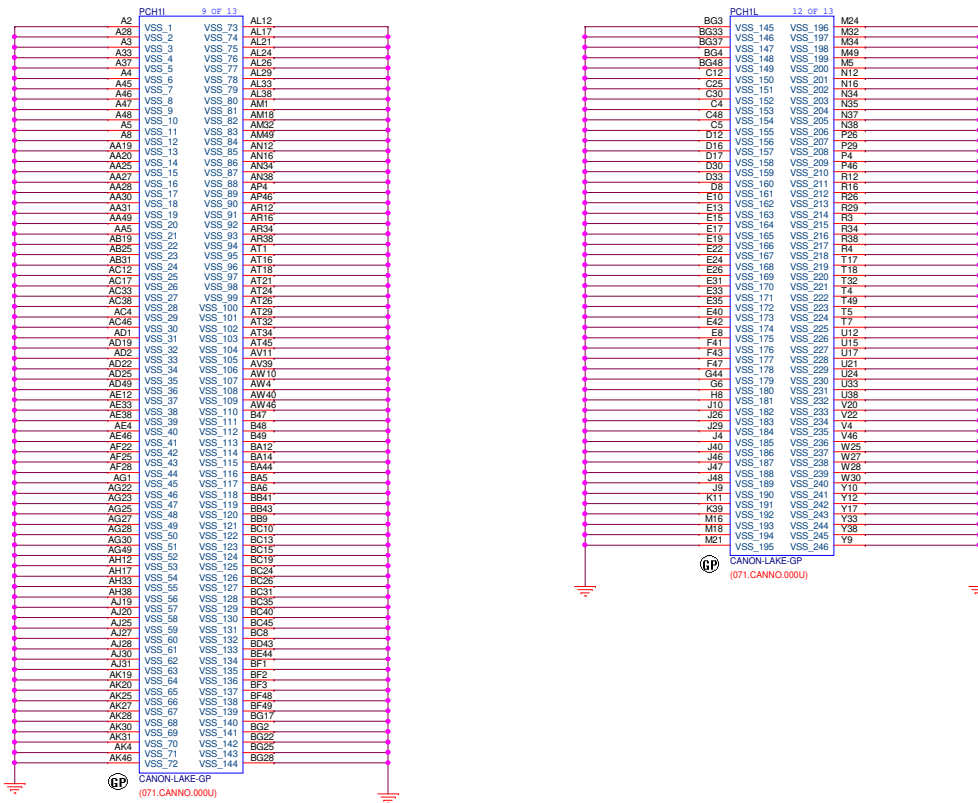
Table 9-1. Pin Straps (Sheet 1 of 4)

Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top Drive Overhaul	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>1 = Disable "Top Drive" mode. This enables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_B18 / GSPIO_MOSI	No Drive	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_C2 / SMBALERT#	1.5V Core Activity	Rising edge of SSM100	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>

Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top Drive Overhaul	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_B18 / GSPIO_MOSI	No Drive	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_C2 / SMBALERT#	1.5V Core Activity	Rising edge of SSM100	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>

Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top Drive Overhaul	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_B18 / GSPIO_MOSI	No Drive	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_C2 / SMBALERT#	1.5V Core Activity	Rising edge of SSM100	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>

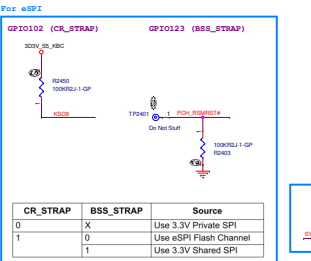
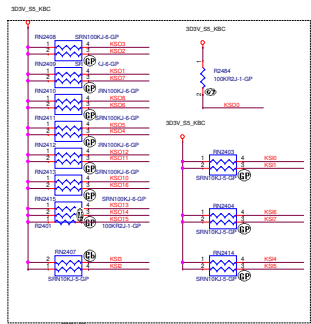
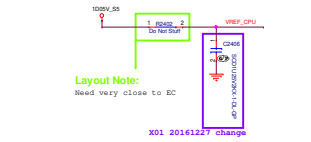
Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top Drive Overhaul	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_B18 / GSPIO_MOSI	No Drive	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>
GPP_C2 / SMBALERT#	1.5V Core Activity	Rising edge of SSM100	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "Top Drive" mode. This enables an address on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p> <p>0 = Enable "Top Drive" mode. This disables the on-chip driver and allows the top drive to be used. The signal is pulled up to VDDIO_1.0 by a 10k resistor.</p>



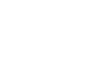
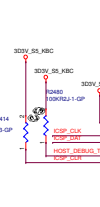
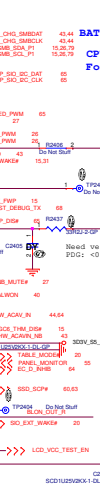
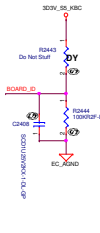
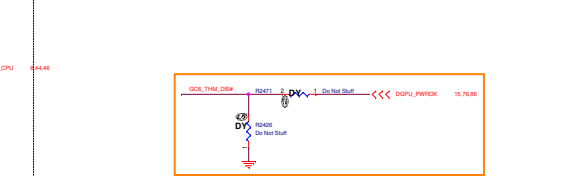
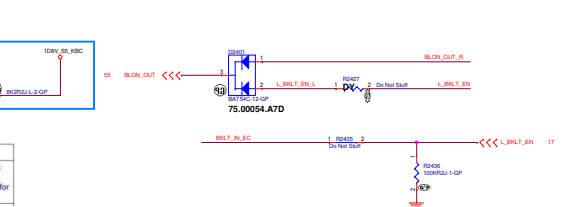
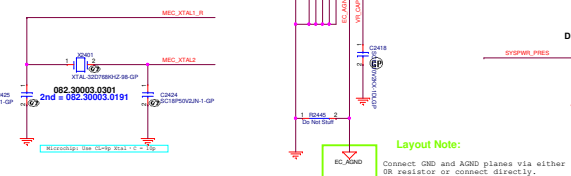
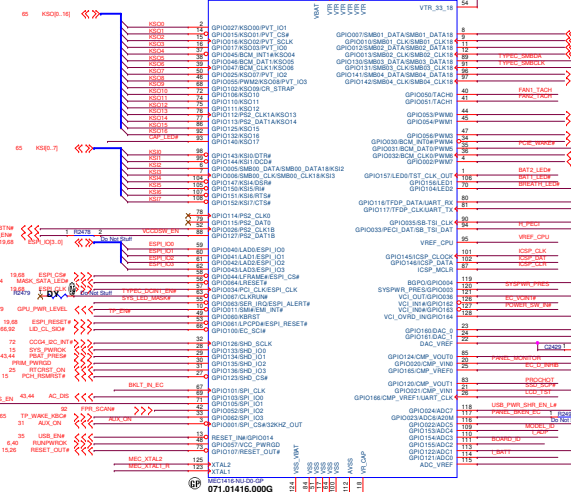
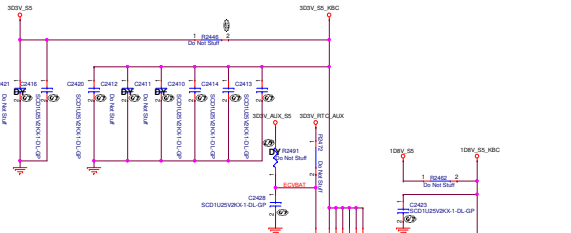
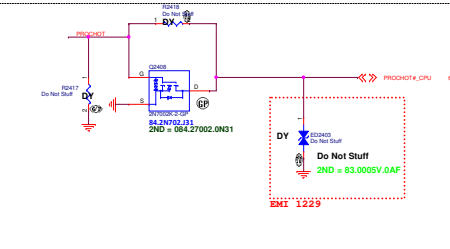
Selek CFLH N17P

DELL		Wistron Corporation	
21F, 8B, Sec. 1, Hsin Tai Wu Rd., Hsinchu, Taipei Hsin 221, Taiwan, R.O.C.			
Title PCH_(VSS/GPIO)			
Size Custom	Document Number Selek CFL-H	Rev A00	
Date: Wednesday, April 03, 2019	Sheet 23	of	105

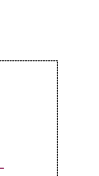
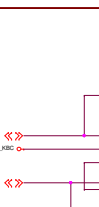
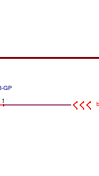
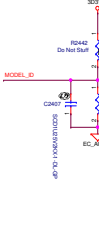
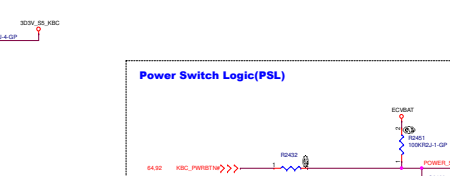
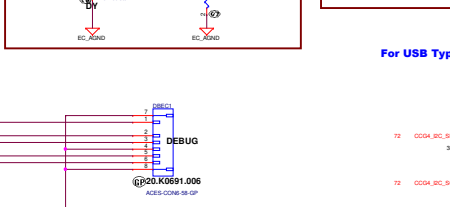
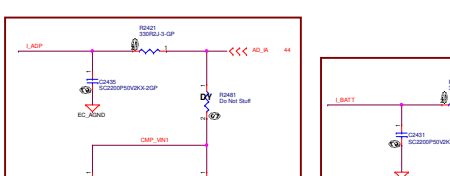
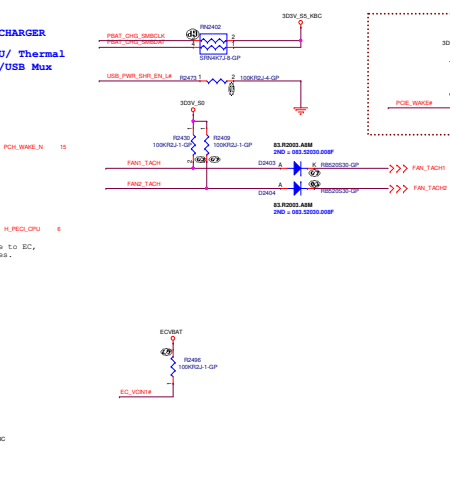
Main Func = KBC



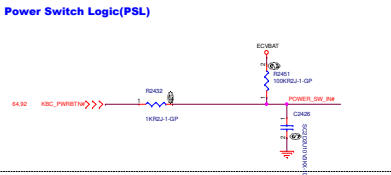
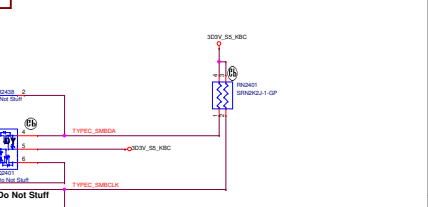
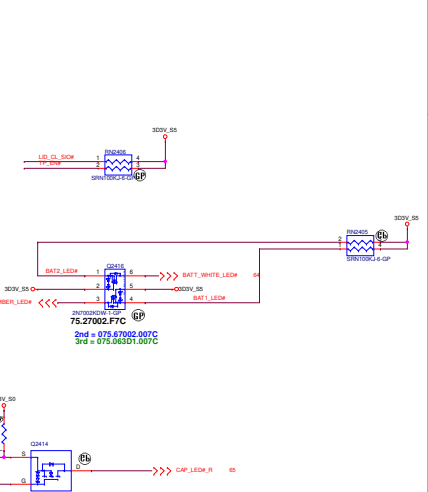
Note	Description
Note 16	If the eSPI Flash Channel is used for booting, the GPIO123/3RD_C58 pin must be used as RSMRST#. This pin will be driven high by the boot ROM code in order to activate the eSPI flash channel. If the SHD_SPI port is used for booting, then any unused GPIO may be used for RSMRST#.



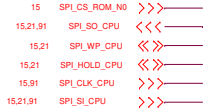
#	Board_ID(GPIO155)	PULL-LOW RESISTOR	PULL-HIGH RESISTOR	VOLTAOE
1	X00	100.0K	10.0K	3
2	X01	100.0K	17.8K	2.801
3	X02	100.0K	27.0K	2.598
4	X03(Reserved)	100.0K	37.4K	2.402
5	A00	100.0K	49.9K	2.201
6	A01	100.0K	64.9K	2.001
7	A02	100.0K	82.5K	1.808
8	A03	100.0K	107K	1.594
9	Reserved	100.0K	154K	1.299
10	Reserved	100.0K	200K	1.1
11	Reserved	100.0K	TBD	0.9
12	Reserved	100.0K	TBD	0.7
13	Reserved	100.0K	TBD	0.5
14	Reserved	100.0K	TBD	0.3



#	MODEL_ID(GPIO153)	PULL-LOW RESISTOR	PULL-HIGH RESISTOR	VOLTAGE
1	Nvidia-N17P-G0-K1	100.0K	10.0K	3
2	Nvidia-N18P-G0	100.0K	17.8K	2.801
3	Nvidia-N18P-G0	100.0K	27.0K	2.598
4	Nvidia-N18P-G0	100.0K	37.4K	2.402
5	Nvidia-N18P-G0	100.0K	49.9K	2.201
6	Nvidia-N18P-G1	100.0K	64.9K	2.001
7	Nvidia-N18P-G1	100.0K	82.5K	1.808
8	Nvidia-N18P-G1	100.0K	107K	1.594
9	Nvidia-N18P-G1	100.0K	154K	1.299
10	Reserved	100.0K	TBD	0.9
11	Reserved	100.0K	TBD	0.7
12	Reserved	100.0K	TBD	0.5
13	Reserved	100.0K	TBD	0.3



SSID = Flash.ROM

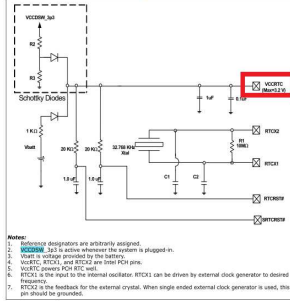


Main Func = RTC

BTY RTC CR2016_30MM KTS 2PIN

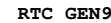
1st= 23.25212.011

-1 20161118



Notes:

1. Reference designators are arbitrarily assigned.
2. **VCC05W**, 3p3 is active whenever the system is plugged-in.
3. **Vall** is voltage provided by the battery.
4. **VoRtc**, **RTCK1**, and **RTCK2** are Intel PCH pins.
5. **VccRtc** powers PCH **RTC** well.
6. **RTCK1** is the input to the internal oscillator. **RTCK2** can be driven by external clock generator to desired frequency.
7. **RTCK2** is the feedback for the external crystal. When single ended external clock generator is used, this pin should be grounded.

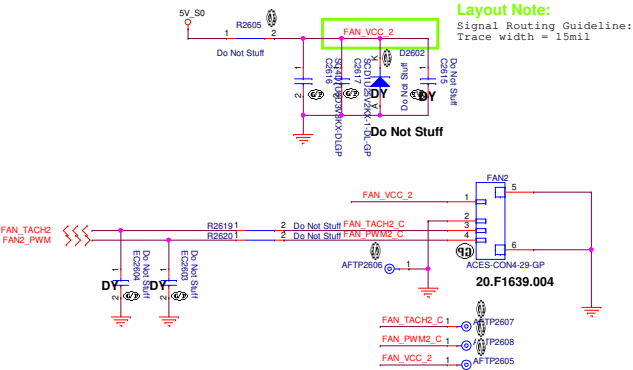
**Selek CFLH N17P**

DELL **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title	Flash(KBC+PCH)/RTC
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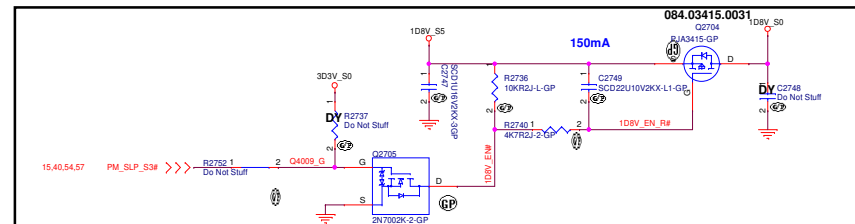
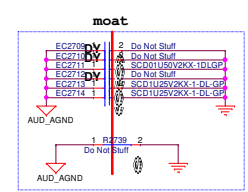
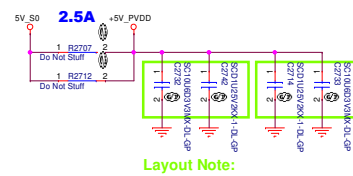
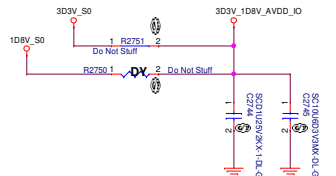
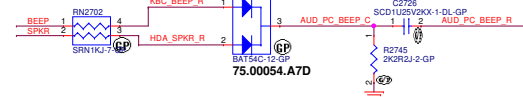
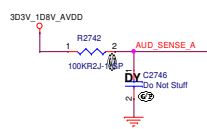
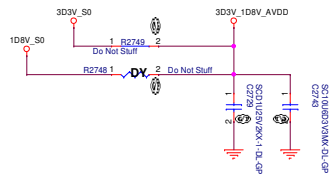
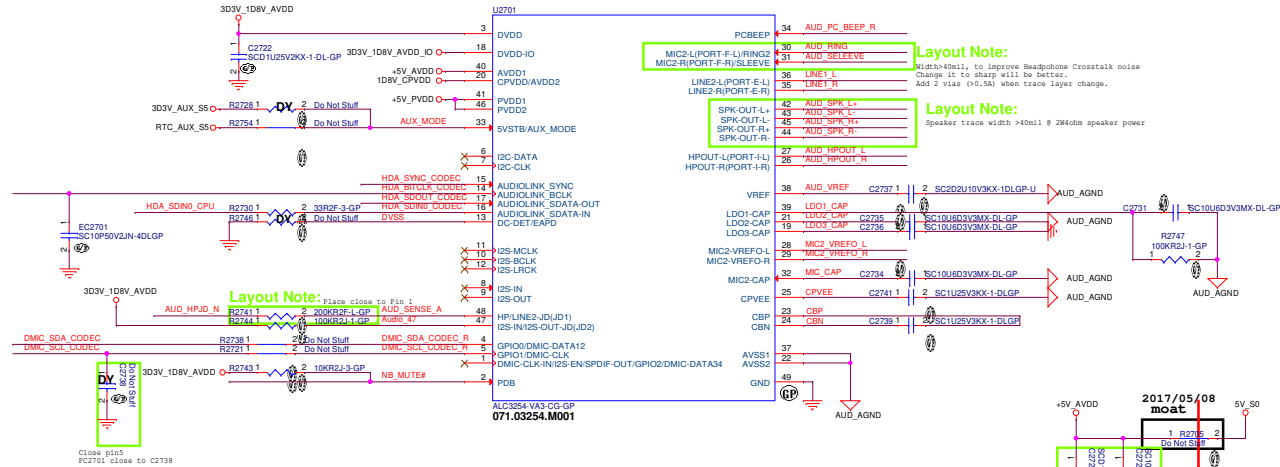
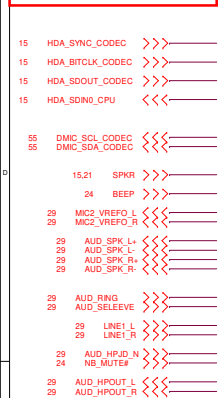
Size A2	Document Number Selek CFL-H	Rev A00
Date: Wednesday, April 03, 2019	Sheet 25 of 105	

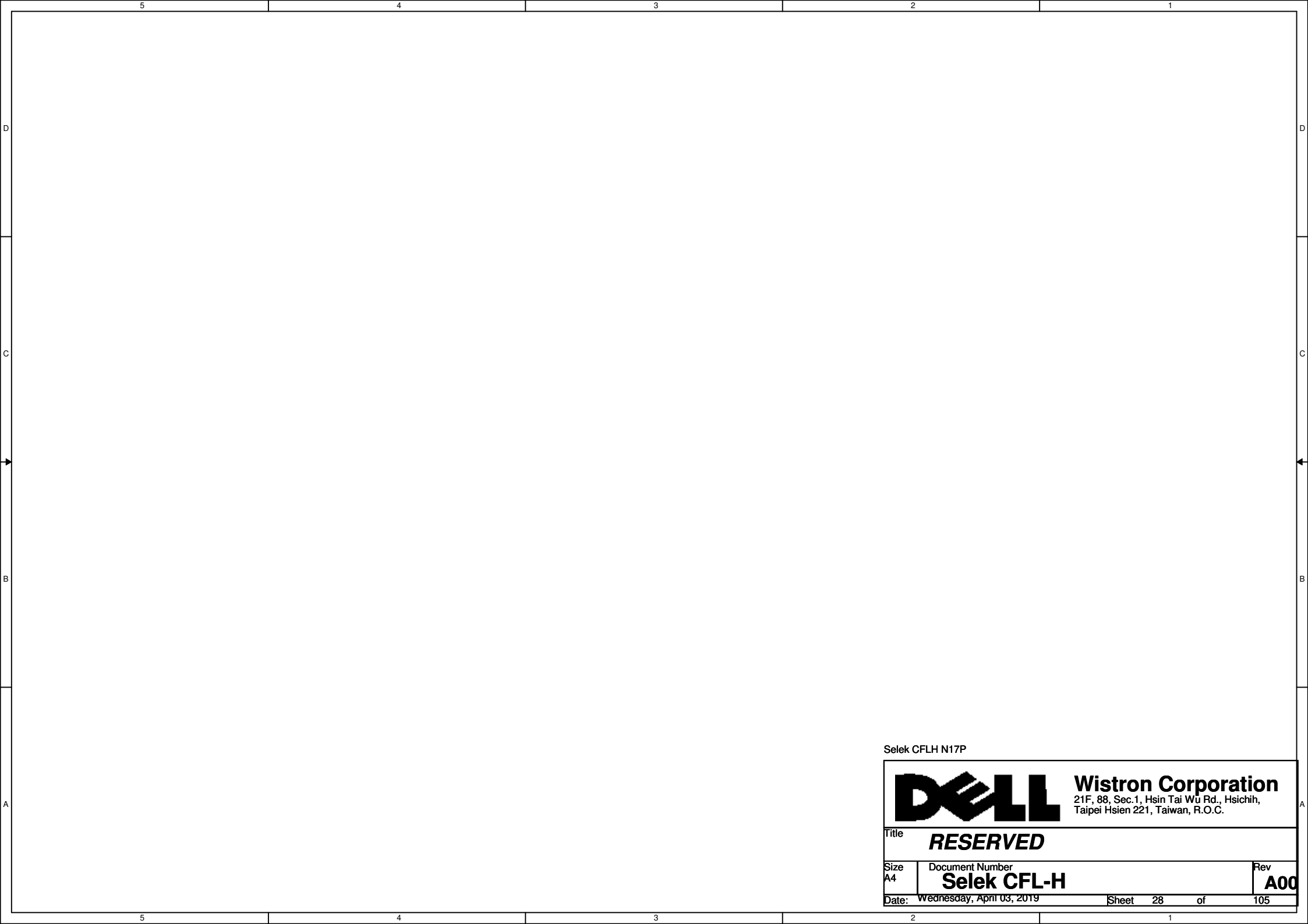
PWM FAN2




TEMPERATURE (°C)		T_CRIT#				
		2KΩ	7.5KΩ	10.5KΩ	14KΩ	18.7KΩ
ALERT#	2KΩ	77	87	97	107	117
	7.5KΩ	79	89	99	109	119
	10.5KΩ	81	91	101	111	121
	14KΩ	83	93	103	113	123
	18.7KΩ	85	95	105	115	125

SSID = Audio






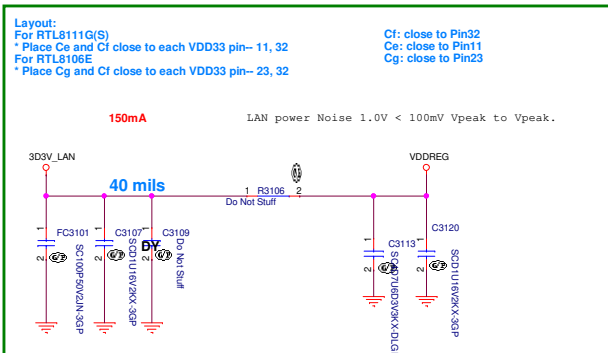
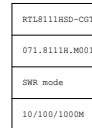
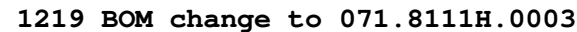
Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title RESERVED			
Size A4	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019		Sheet 28 of	105

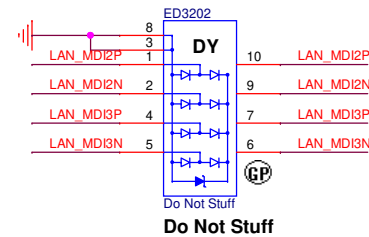
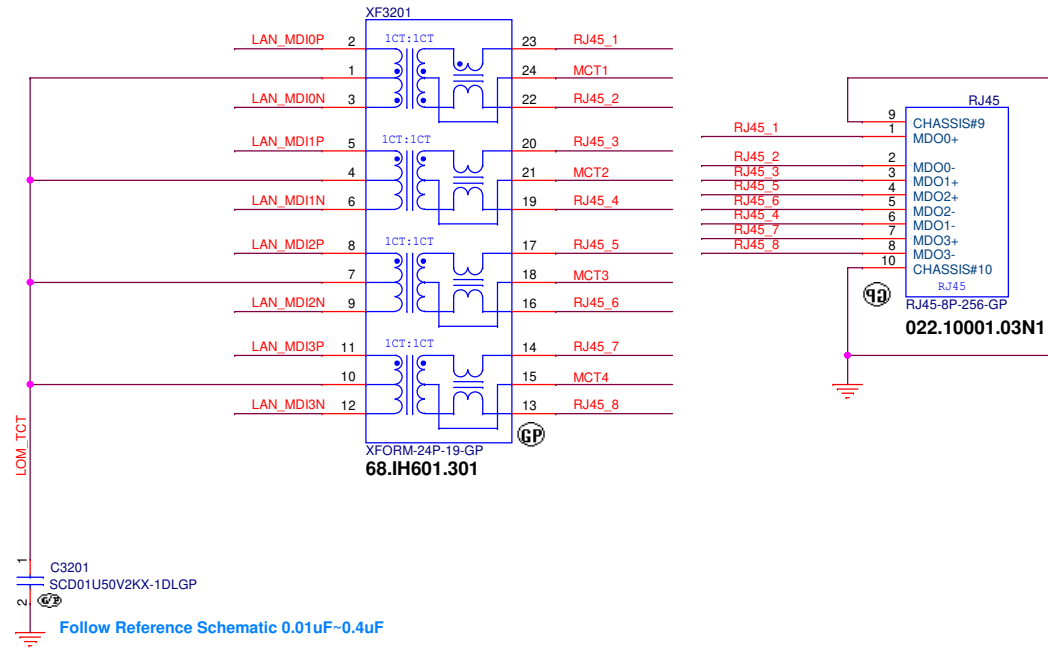
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B				B
A				A
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Selek CFLH N17P

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Title (Reserved)			
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Date:	Wednesday, April 03, 2019	Sheet 30 of	105



SSID = LAN



Title	<i>RJ45+Transformer</i>
-------	--------------------------------

Size B	Document Number Selek CFL-H	Rev A00
Date: Wednesday, April 03, 2019	Sheet 32 of 105	

SSID = Card Reader

Selek CFLH N17P




Title (Reserved)

Size A2	Document Number Selek CFL-H	Rev A00
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Date: Wednesday, April 03, 2019	Sheet 33 of 105
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B				B
A				A
5	4	3	2	1

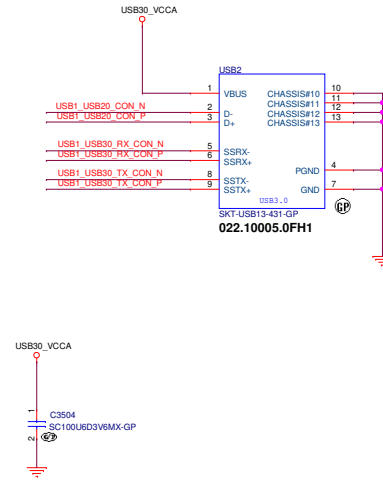
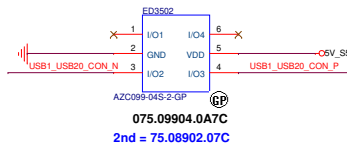
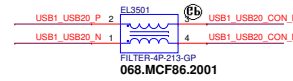
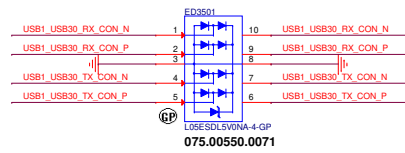
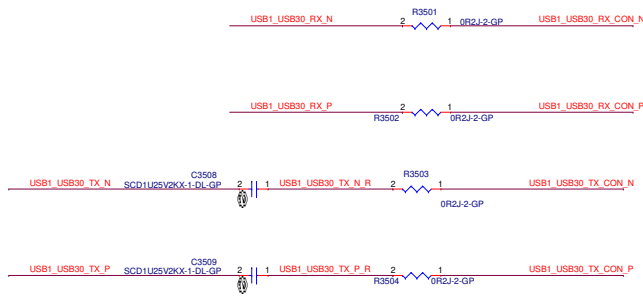
Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
Date:	Wednesday, April 03, 2019	Sheet 34 of	105

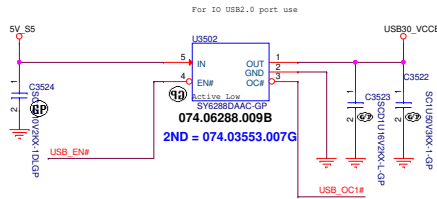
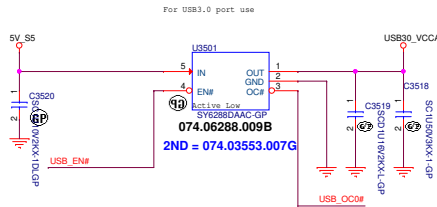
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24,35 USB_EN# >>> >>>
18 USB_OC0# <<< <<<

24,35 USB_EN# >>> >>>
18 USB_OC1# <<< <<<




USB 3.0 Connector Pin definition	
1	POWER
2	USB 2.0 D-
3	USB 2.0 D+
4	GND
5	StdA_SSRX- SuperSpeed RX
6	StdA_SSRX+ SuperSpeed RX
7	GND
8	StdA_SSTX- SuperSpeed TX
9	StdA_SSTX+ SuperSpeed TX



Selek CFLH N17P

DELL Wistron Corporation	
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsinchu, Taipei Hsin 221, Taiwan, P.O.C.	
Title USB3.0*2 CONN	
Size Custom	Document Number Selek CFLH-H
Date: Wednesday, April 03, 2019	Rev A00
Sheet 35	of 105

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C																								
B																								
A																								
Selek CFLH N17P															<div><div></div><div><div>Wistron Corporation</div><div>21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</div></div></div>									
Title															<div>(Reserved)</div>									
Size					Document Number															Rev				
A					Selek CFL-H															A00				
Date:					Wednesday, April 03, 2019										Sheet					37 of 105				
5					4					3					2					1				

SSID = USB3.0 Redrivere

USB 3.0 Re-driver Pull High / Low

Selek CFLH N17P



Wistron Corporation
21F, 8B, Sec.1, Hsin Tai Wu Rd., Hsuehshien,
Taipei Hsien 221, Taiwan, R.O.C.

Title

USB 3.0 Redriver

Size

A2

Document Number

Selek CFL-H

Rev

A00

Date


Wednesday, April 03, 2019

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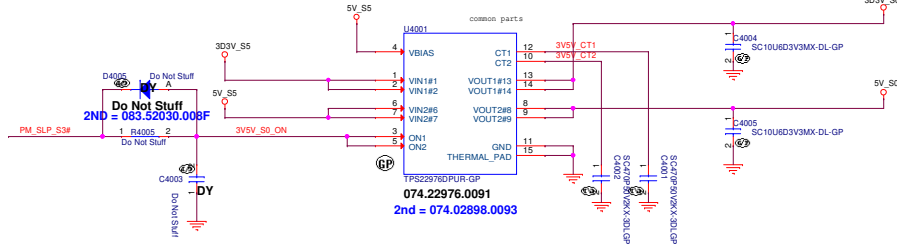
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Title															(Reserved)									
Size					Document Number															Rev				
A					Selek CFL-H															A00				
Date:					Wednesday, April 03, 2019										Sheet					39 of 105				
5					4					3					2					1				

Power Sequence

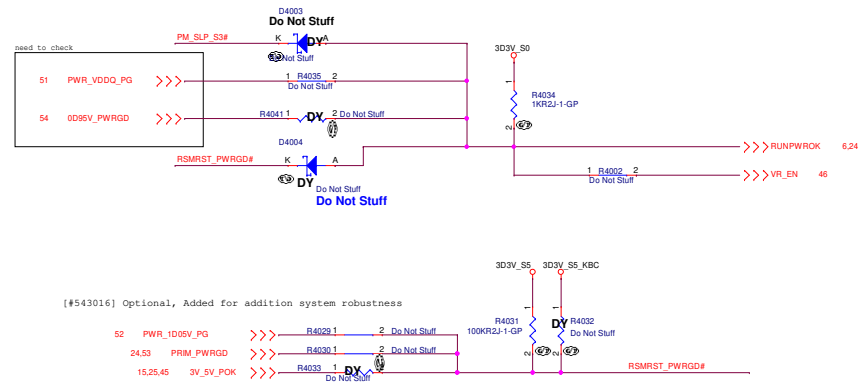
5V_S0 3D3V_S0

5V_S0 Consumption Peak current 5A
3D3V_S0 Consumption Peak current 2.5A

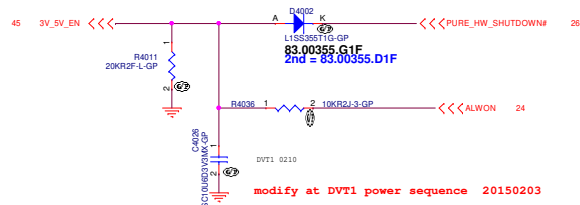
ROSA Run Power



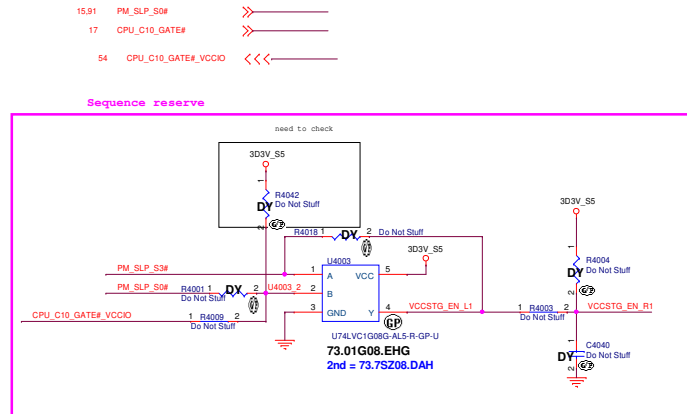
Power Good



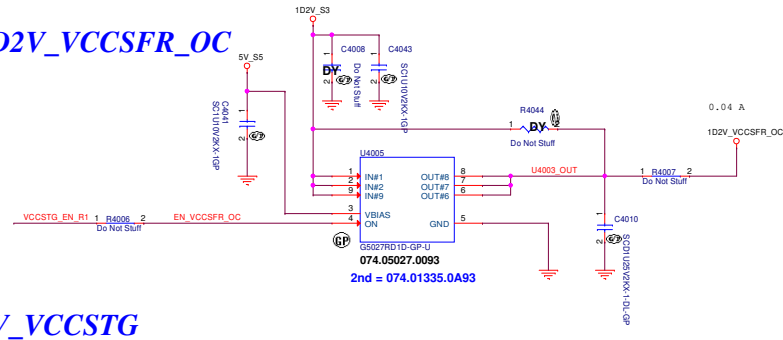
IV_VCCST



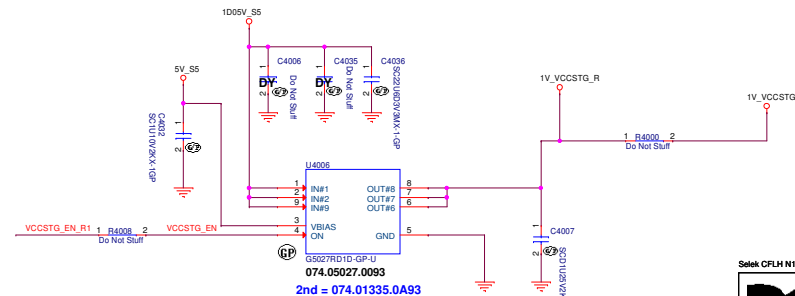
IV_VCCSTG



ID2V_VCCSFR_OC




IV_VCCSTG




Selec CFLH N17P

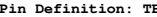
Main Func = Power & Sequence

Selek CFLH N17P

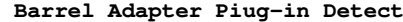
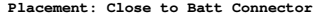
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title		Connected_Standby(1/2)+DS3	
Size A3	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019	Sheet 41	of	105

5					4					3					2					1				
D																								
C																								
B																								
A																								
Selek CFLH N17P															<div><div></div><div><div>Wistron Corporation</div><div>21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.</div></div></div>									
Title															(Reserved)									
Size A					Document Number Selek CFL-H															Rev A00				
Date: Wednesday, April 03, 2019					Sheet					42					of					105				
5					4					3					2					1				

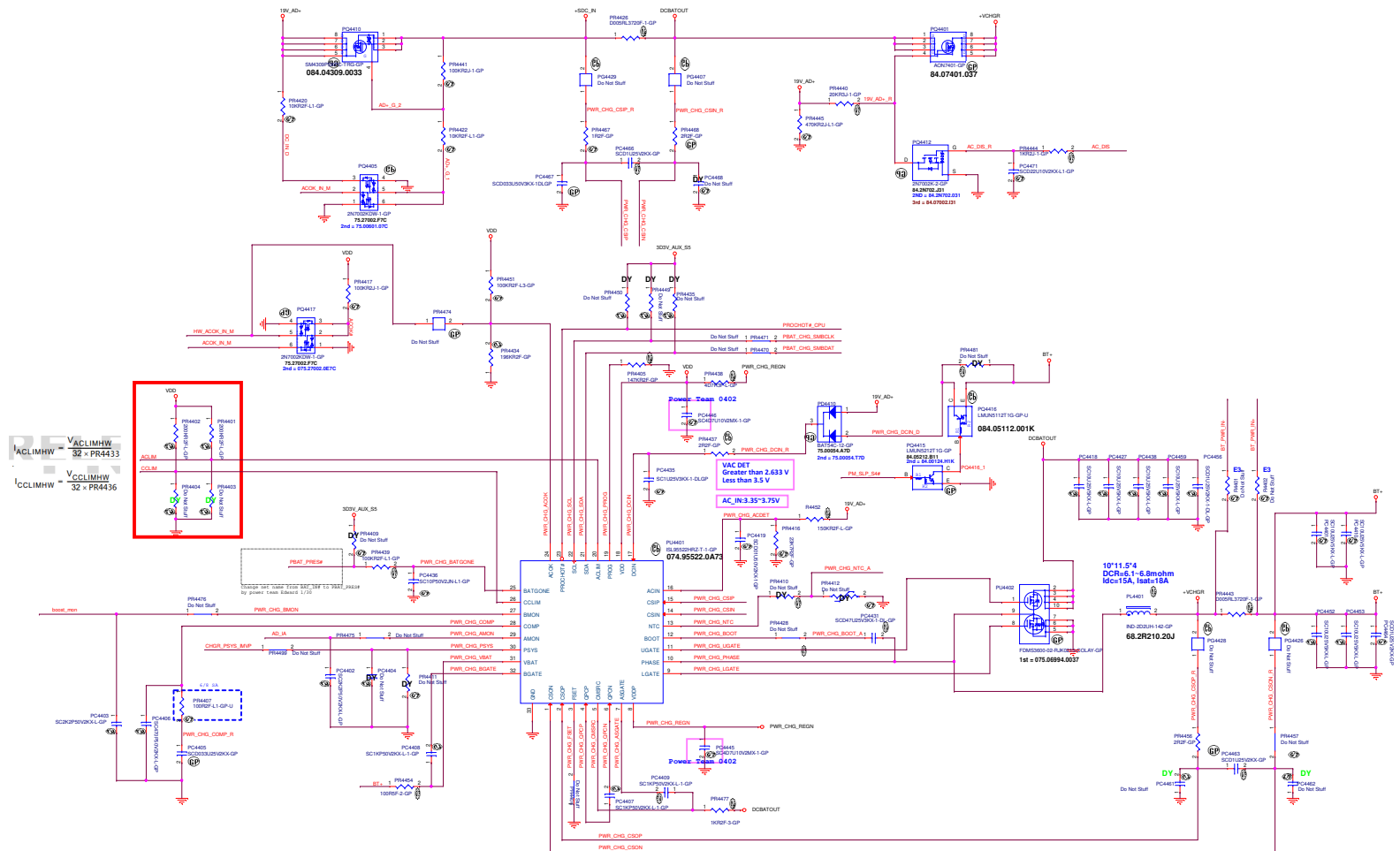
Main Func = ADT Input



Main Func = M-BAT Input



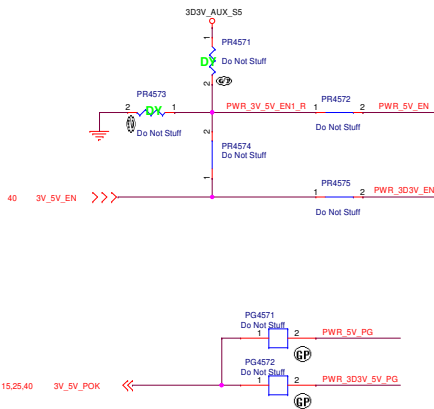
$$I_{ACLIMHW} = \frac{V_{ACLIMHW}}{32 \times PR4433}$$

$$I_{CCLIMHW} = \frac{V_{CCLIMHW}}{32 \times PR4436}$$
[illegible]

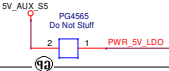
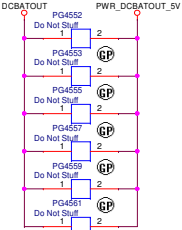
10V AD-
P4040A 1000000.01P
84.0390E.R11
P4040B 84.0390E.R11
P4040C 26202000.1P
P4040D 7.020000.1P
P4040E 26202000.1P
P4040F 7.020000.1P
P4040G 26202000.1P
P4040H 7.020000.1P
P4040I 26202000.1P
P4040J 7.020000.1P
P4040K 26202000.1P
P4040L 7.020000.1P
P4040M 26202000.1P
P4040N 7.020000.1P
P4040O 26202000.1P
P4040P 7.020000.1P
P4040Q 26202000.1P
P4040R 7.020000.1P
P4040S 26202000.1P
P4040T 7.020000.1P
P4040U 26202000.1P
P4040V 7.020000.1P
P4040W 26202000.1P
P4040X 7.020000.1P
P4040Y 26202000.1P
P4040Z 7.020000.1P
CPU PROCBOT# Circuit

```
SSID = PWR.Plane.Regulator_5V
```

OFFPAGE-Signal



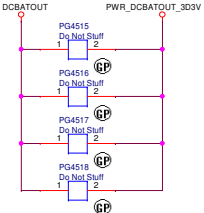
OFFPAGE-GAP



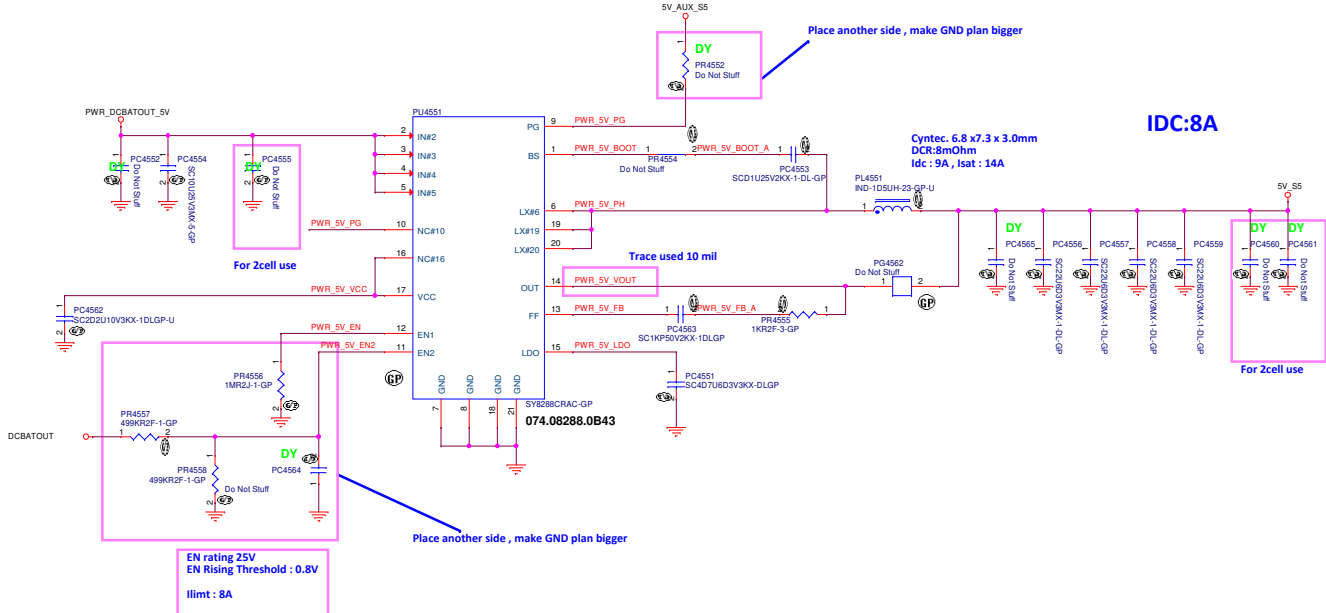
```
SSID = PWR.Plane.Regulator_3D3V
```

OFFPAGE-Signal

OFFPAGE-GAP

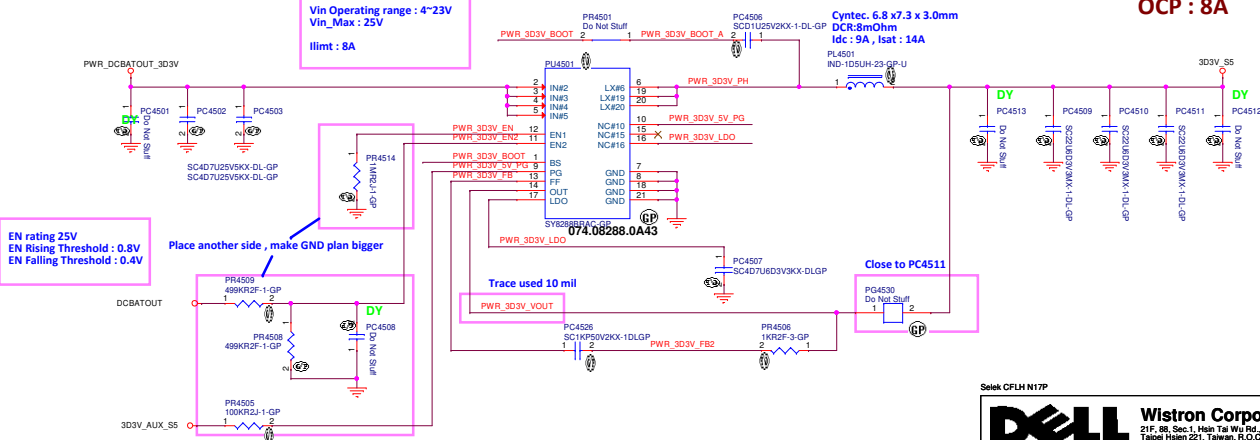


SY8288C For 5V



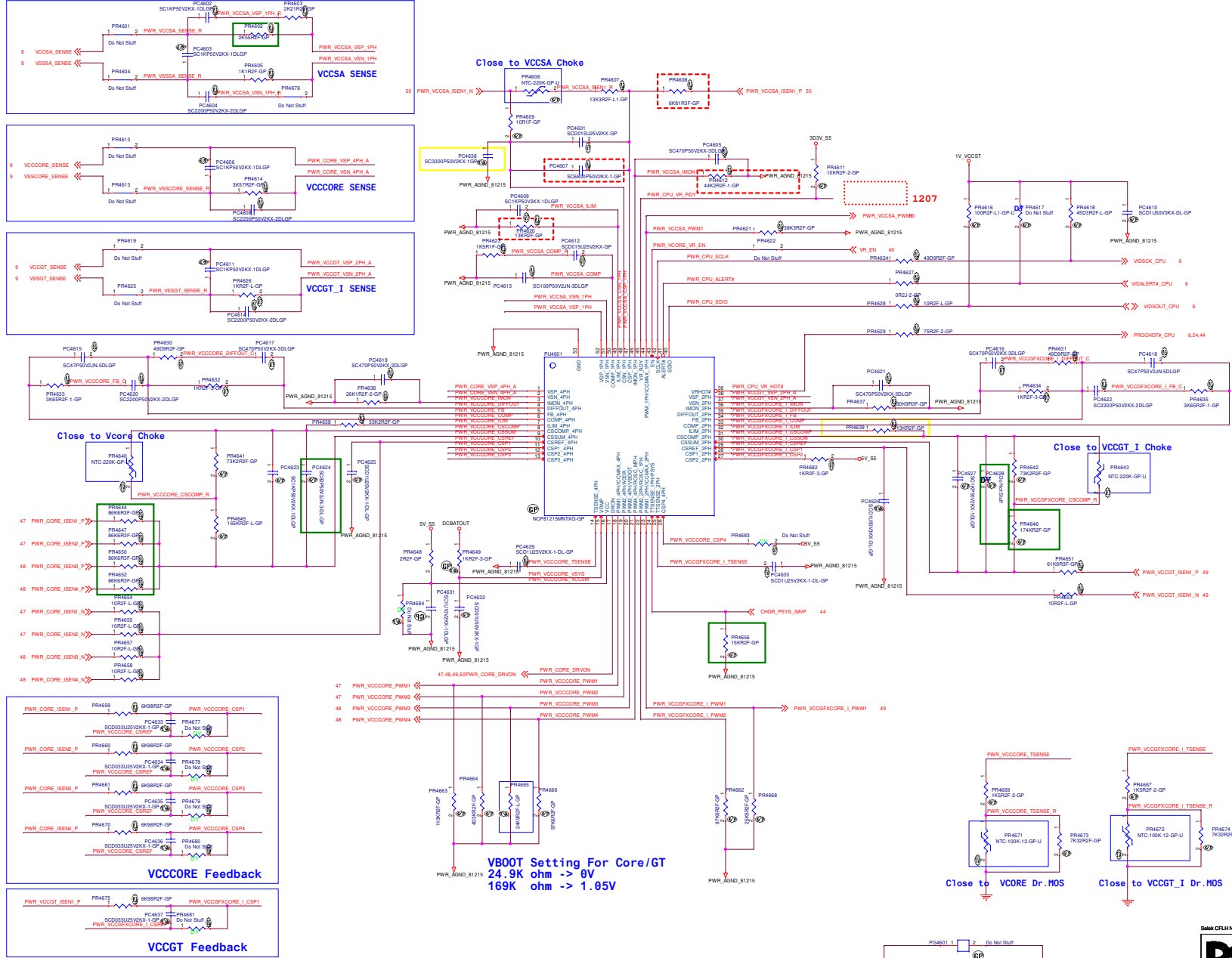
SY8286B For 3D3V

IDC : 6A
OCP : 8A

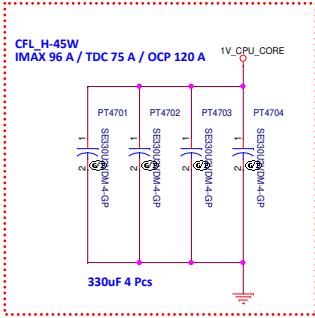
**Selek CFLH N17**

DELL **Wistron Corporation**
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Taipei Hsien 221, Taiwan, R.O.C.

Title POWER (SY8288_5V/3D3V)			
Size A2	Document Number Selek CFL-H	Rev A0	
Date: Wednesday, April 03, 2019	Sheet 45	of	105



Add : PWR GAP
change GND symbol on this page ALL GND



PWR_DCBATOUT_VCCCORE

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

This circuit is for Hexa core.
Please refer to the table in next page.

Selek CFLH N17P

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Taippei Hsien 221, Taiwan, R.O.C.

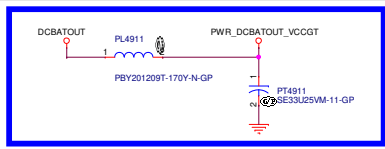
Title
DC/DC VCCCPUCORE (2/2)

Size
C Document Number
Selek CFL-H

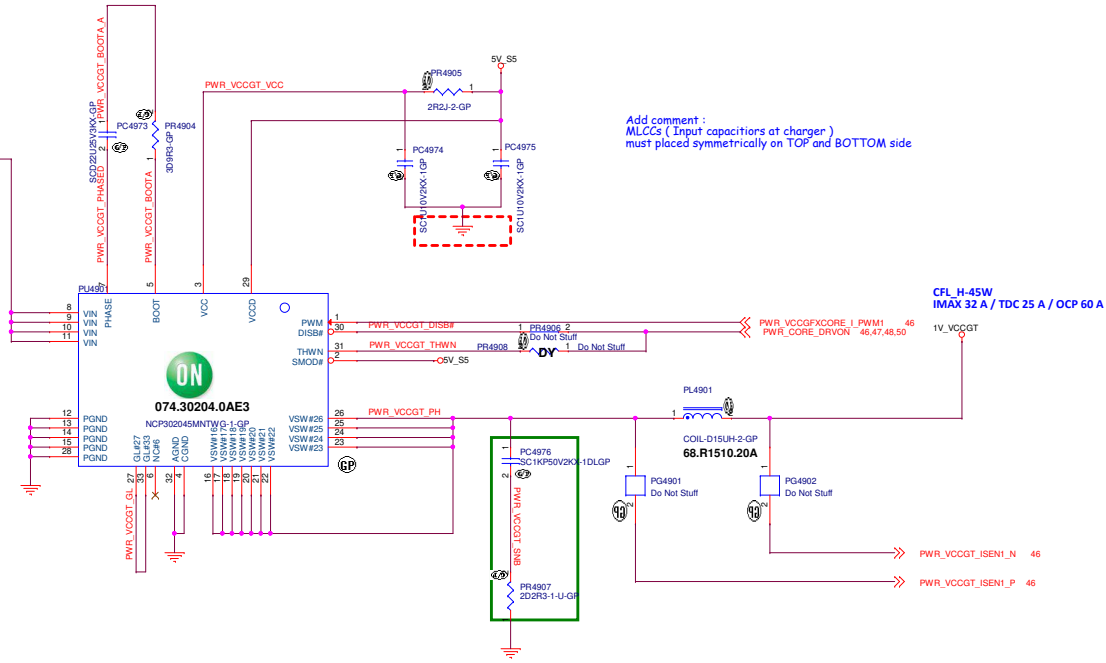
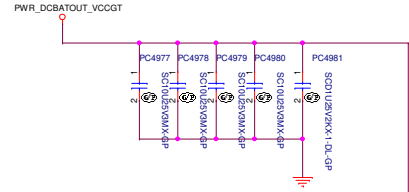
Date: Wednesday, April 03, 2019

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Rev
A00

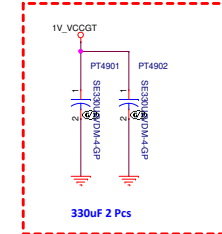


For acousaic noise 1228



Add comment :
MLCCs (Input capacitors at charger)
must placed symmetrically on TOP and BOTTOM side

CFL_H-45W
IMAX 32 A / TDC 25 A / OCP 60 A

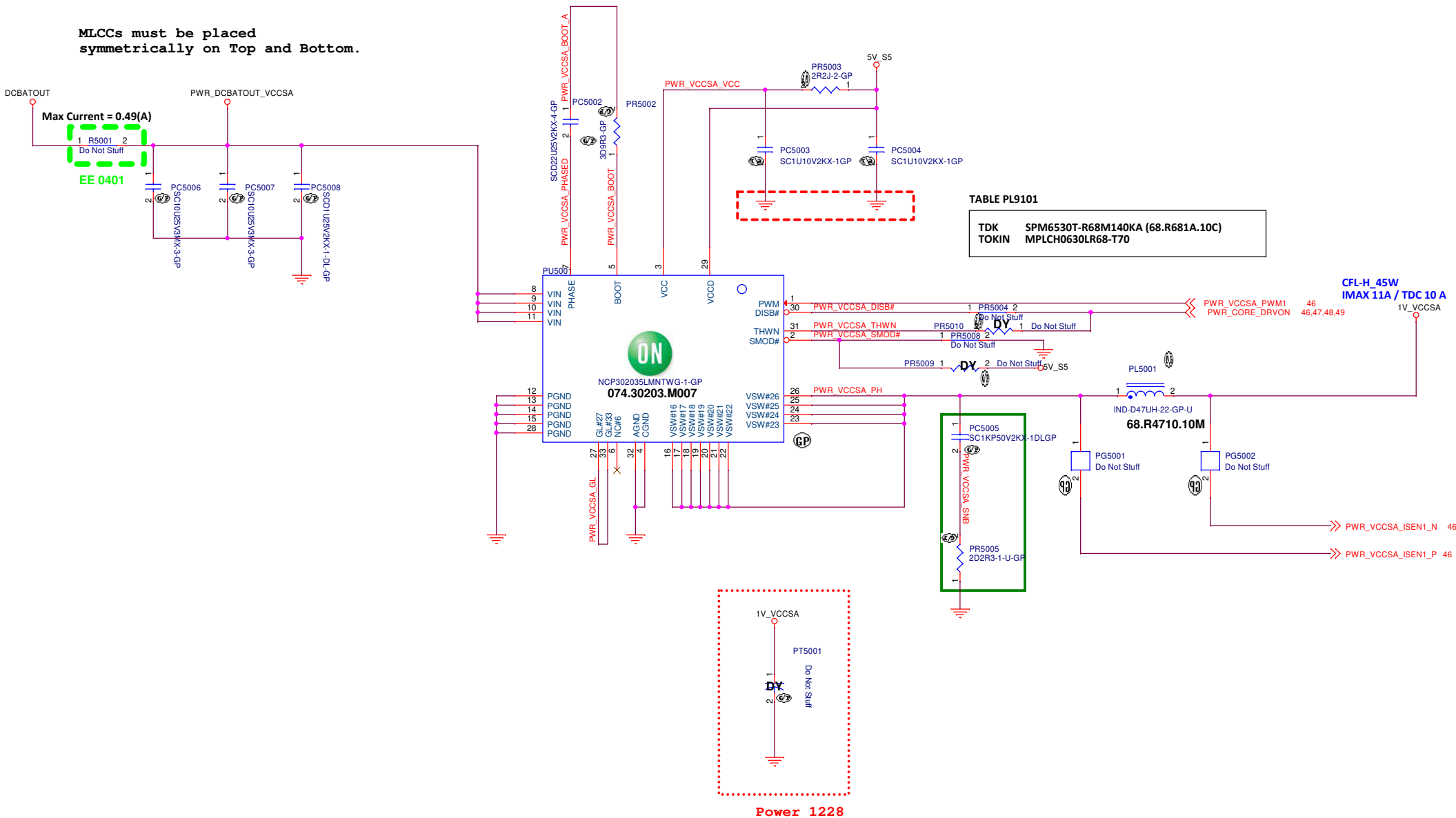


330uF 2 Pcs
Power 0401

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DELL		Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Heishlin, Taipei Hsien 221, Taiwan, R.O.C.	
Title DC/DC VCCGFXCORE_I(NCP302045)			
Size Custom	Document Number Selek CFL-H	Rev A00	
Date: Wednesday, April 03, 2019	Sheet 49	of	105

MLCCs must be placed
symmetrically on Top and Bottom.



Selek CFLH N17P

SSID = PWR.Plane.Regulator_1D05V

OFFPAGE-Signal

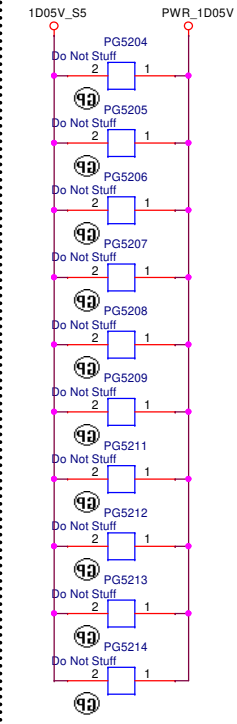
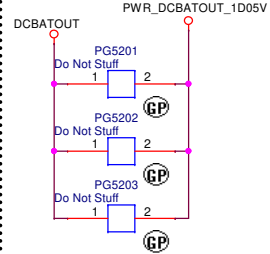
PH on EE Side

PWR_1D05V_PG

3V_5V_DSW_OK

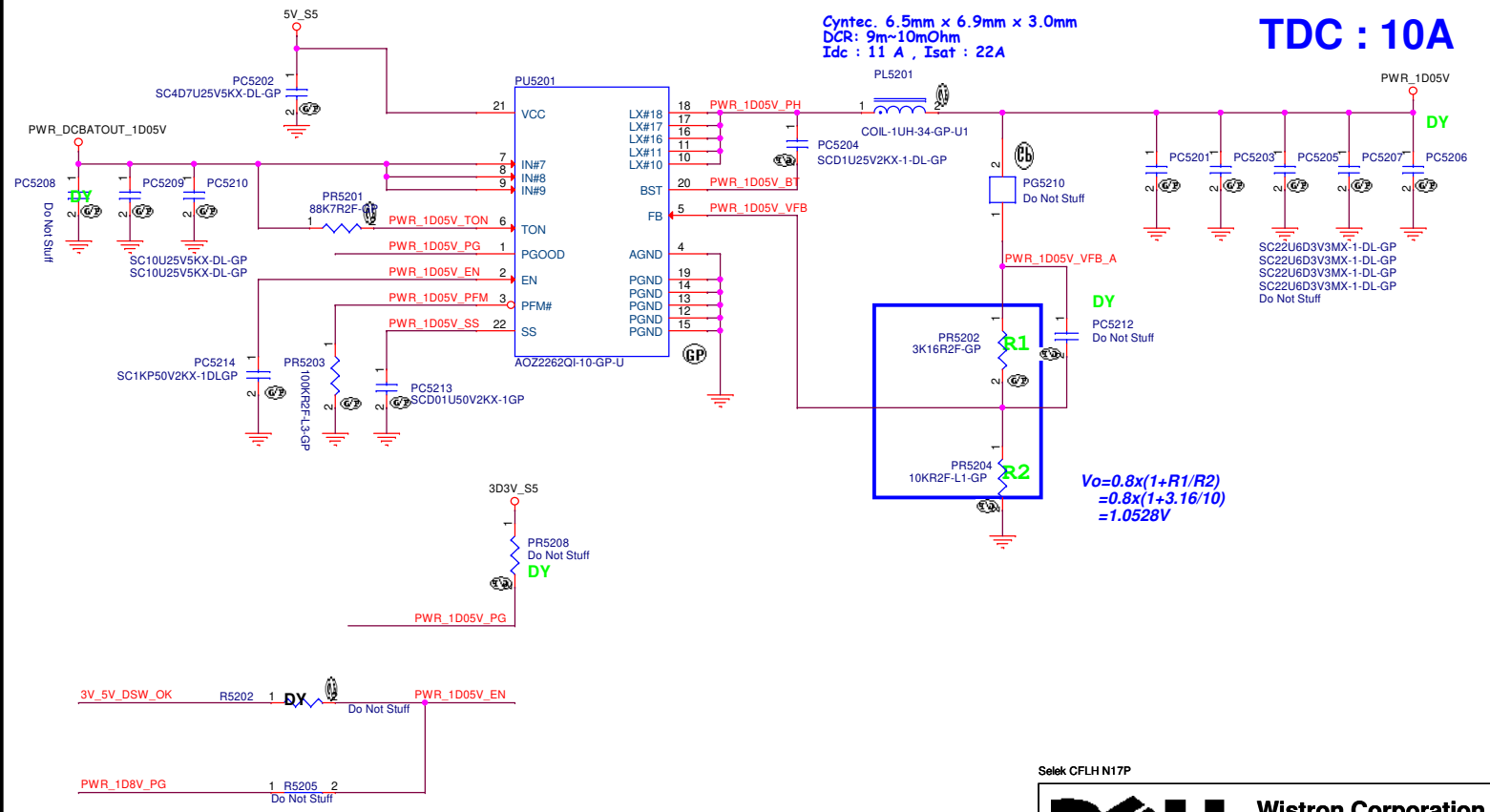
PWR_1D8V_PG

OFFPAGE-GAP



AOZ2262 For 1D05V

COM	IC	AOZ2262 (10A)	AOZ2261 (8A)	AOZ2260 (6A)
		074.02262.0043	074.02261.0A73	074.02260.0043
Chock		68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A
Output CAP		22uF/6.3V * 5pcs DY*1	22uF/6.3V * 4pcs DY*1	22uF/6.3V * 4pcs DY*1



Selek CFLH N17P

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POWER (AOZ2262_1D05V)

Size A3 Document Number **Selek CFL-H** Rev **A00**

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Main Func = 1D8V

OFFPAGE

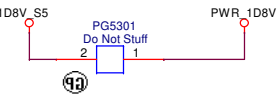
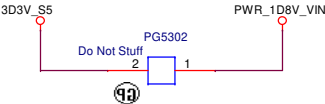
25,52 3V_5V_DSW_OK >>

PH on EE Side



52 PWR_1D8V_PG <<

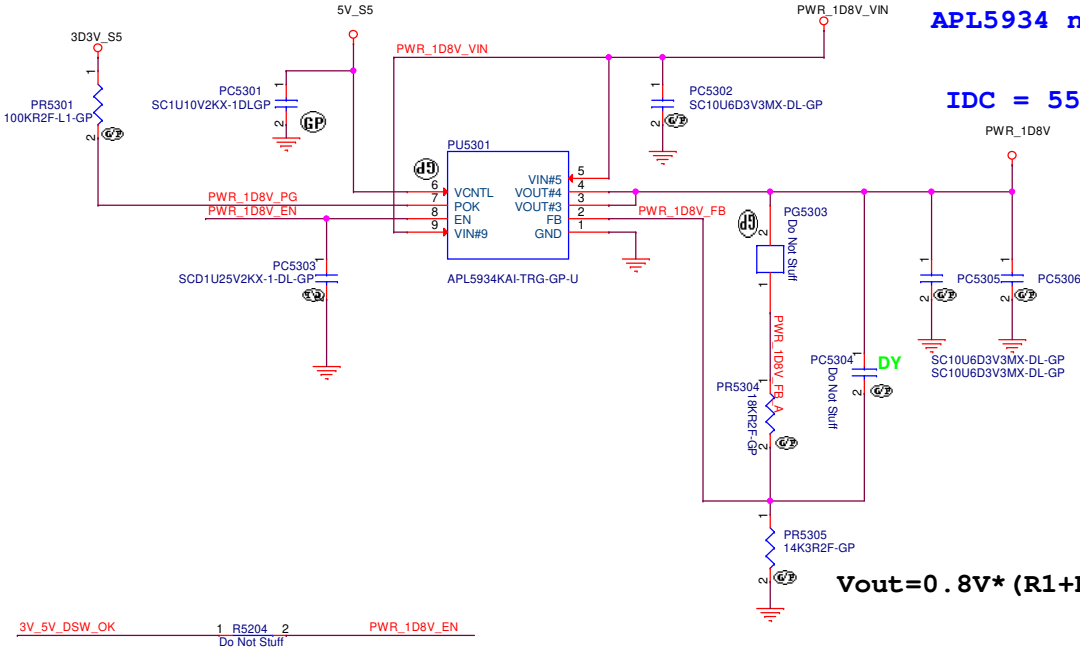
OFFPAGE_GAP



APL5934 for 1D8V

APL5934 need <1.8W

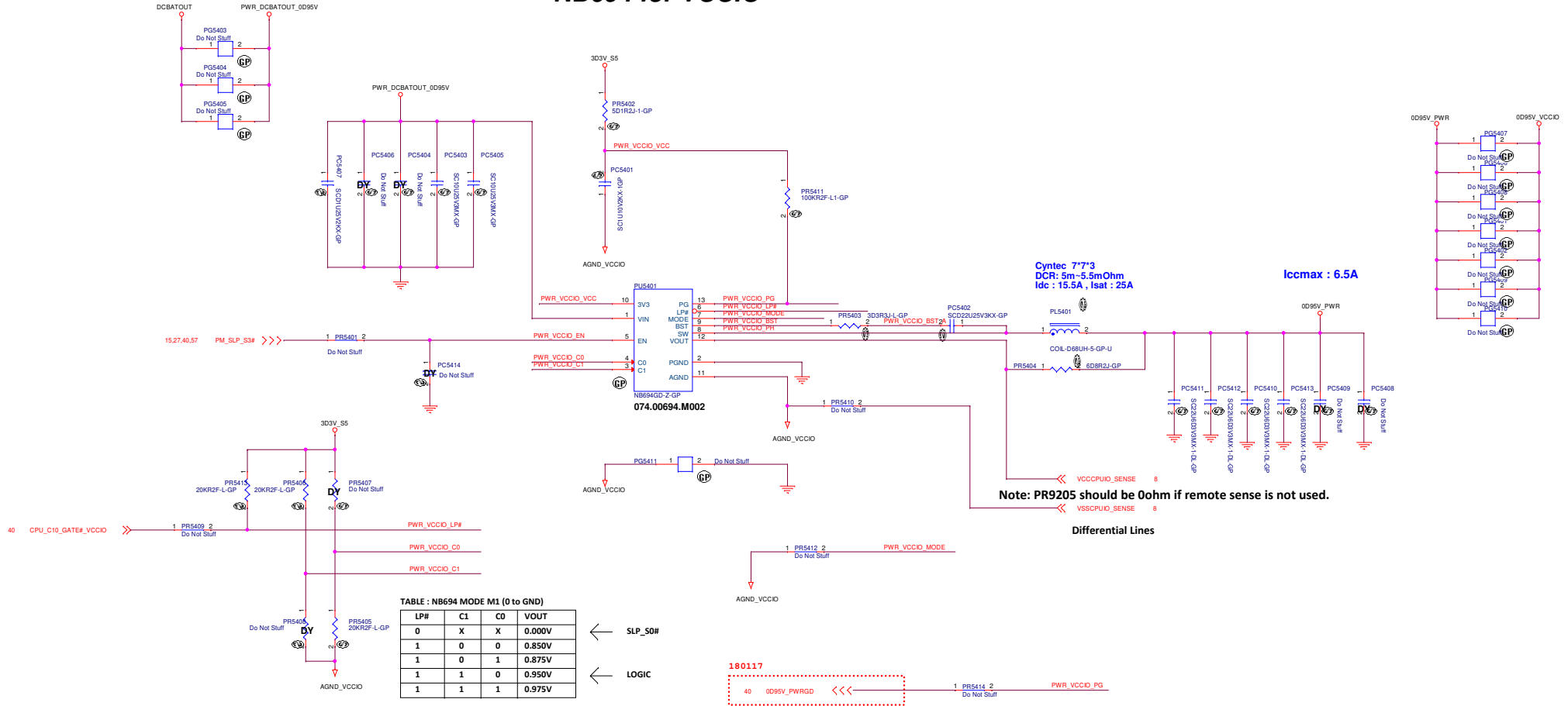
IDC = 550mA



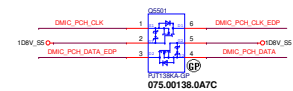
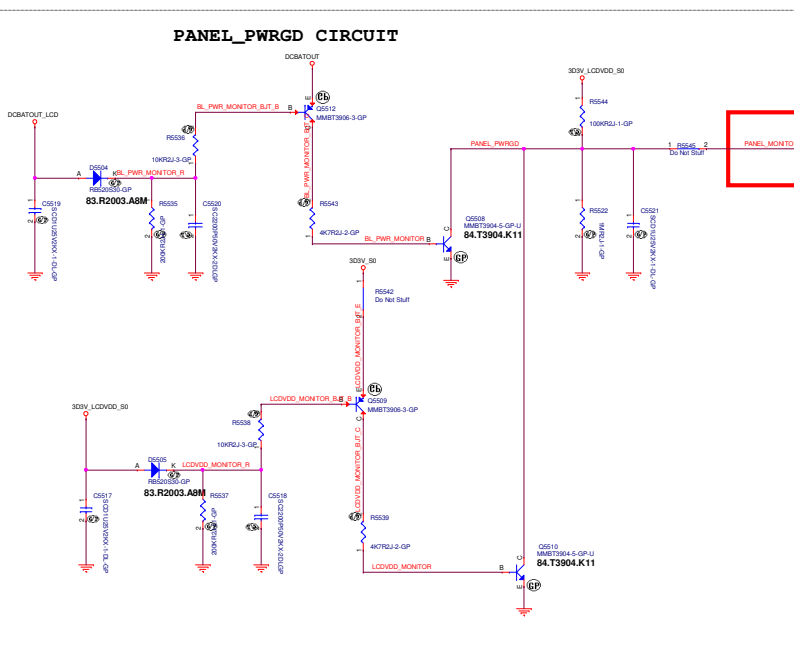
$$V_{out} = 0.8V * (R1 + R2) / R2$$

Selek CFLH N17P

NB694 for VCCIO



Selec CFLH N17P



3

E

C

c

8

E

A

1

5

4

3

2

1

Solek CFLH N17P



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Taipei Hsien 221, Taiwan, R.O.C.

Title **LCD/Inverter Connector**

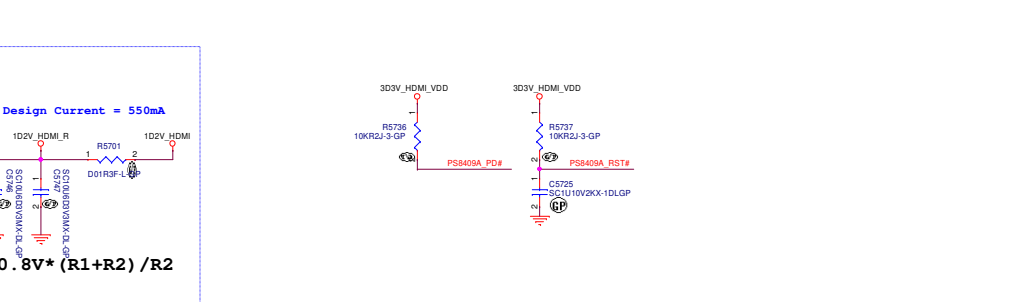
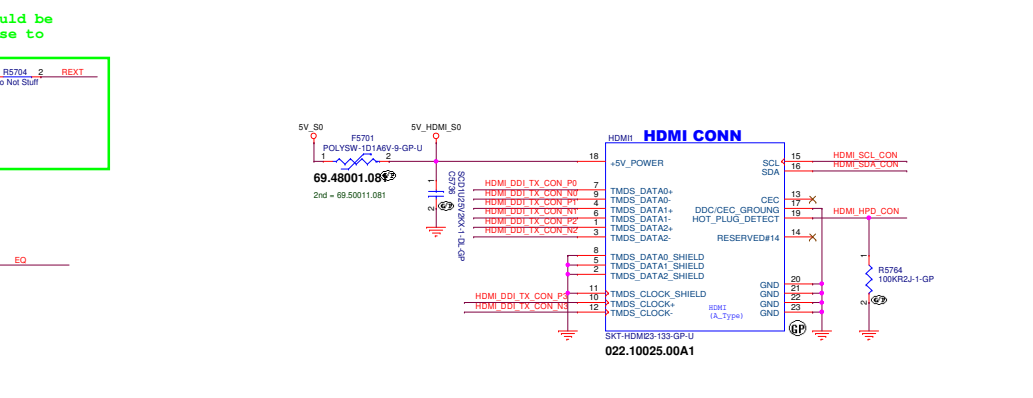
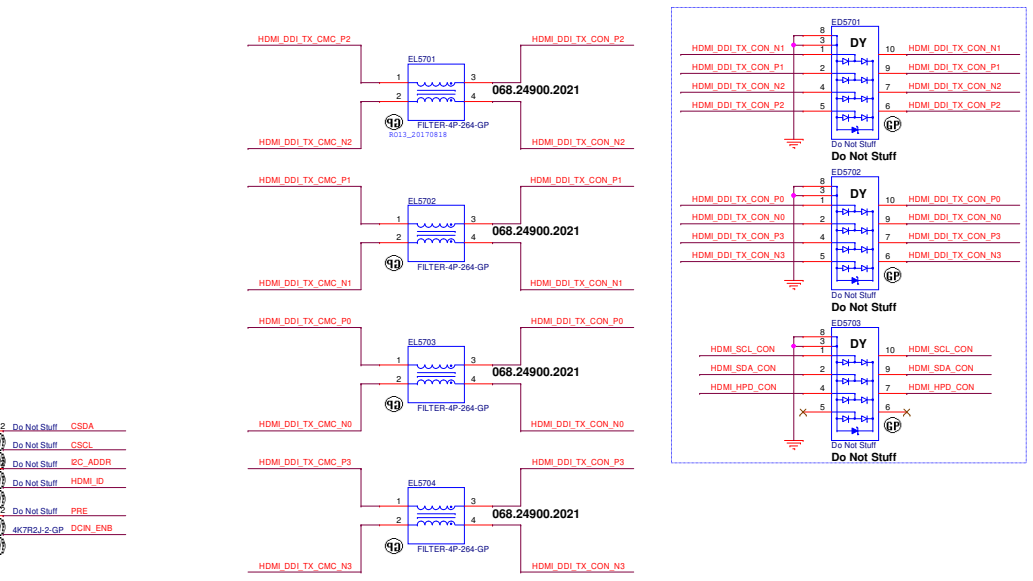
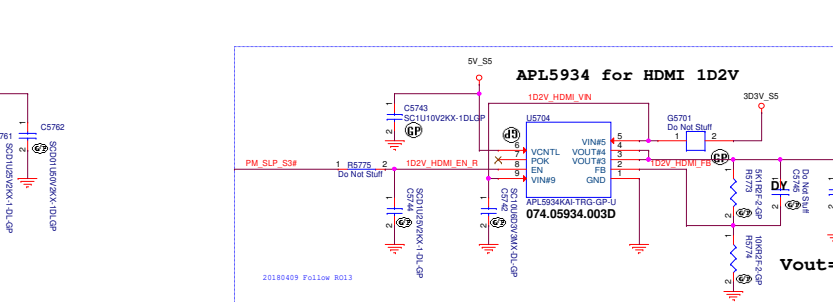
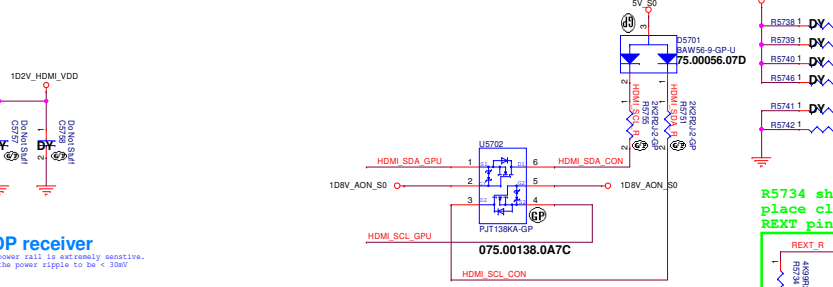
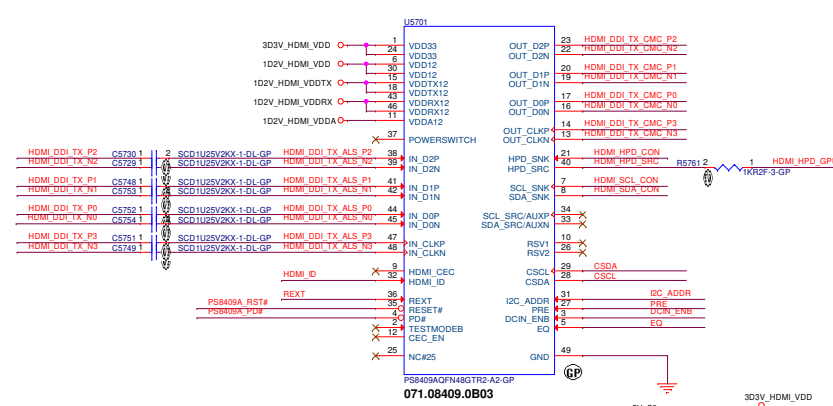
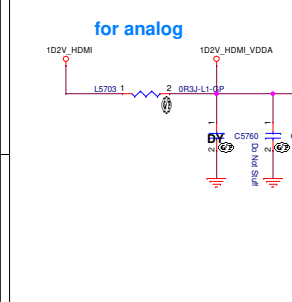
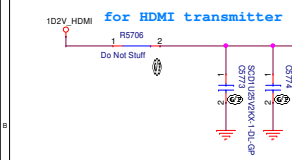
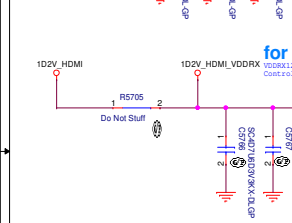
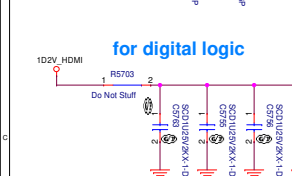
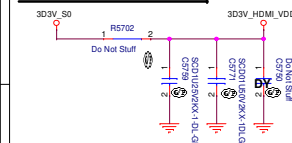
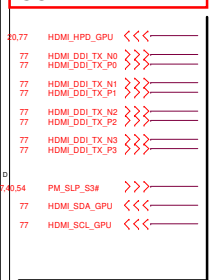
Size	Custom
Date:	

Document Number
Selek CFL-H

Rev
A00


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SSID = HDMI



5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

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Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
Date:	Wednesday, April 03, 2019	Sheet 58 of	105

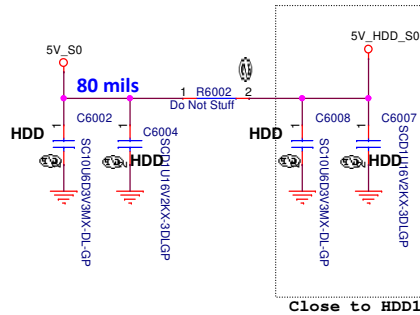
5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

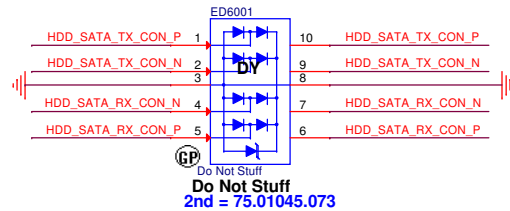
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number Selek CFL-H		Rev A00
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Main Func = HDD

17 HDD_SATA_TX_P >>>
17 HDD_SATA_TX_N <<<
17 HDD_SATA_RX_N <<<
17 HDD_SATA_RX_P >>>
19 HDD_DEVSLP >>>
70 FFS_INT2_Q >>>
24.63 SSD_SCP# >>>



Layout Note:
Place near HDD1



SATA HDD Connector

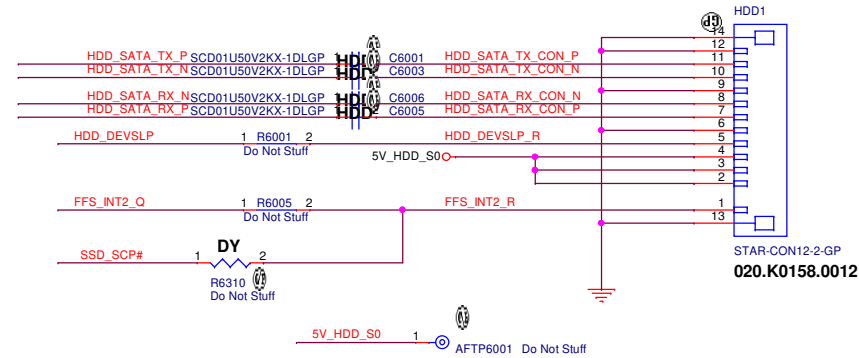


Table 16-5. SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values

Condition	PCI Express* Gen 2 Only	PCI Express* Gen 3 Only	SATA Only	PCI Express* Gen 2/ SATA	PCI Express* Gen 3/ SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ¹	None ²	None ³

Notes:

- This option supports all SATA devices. However, the Rx 10 nF capacitor can be removed if DC coupled ODDs / devices are NOT used.
- For PCIe* Gen 2/ SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- For PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Design Constraint: For PCIe* lane that needs to support either PCIe* Gen2 devices or PCIe* Gen3 devices, follow the PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Use a non-interleaved breakout to isolate Tx and Rx.

Selek CFLH N17P



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Title **SATA HDD**

Size Custom Document Number **Selek CFL-H**

Date: Wednesday, April 03, 2019

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Rev **A00**

Main Func = WLAN

17 WLAN_PCIE_RX_N <<<
17 WLAN_PCIE_RX_P <<<
17 WLAN_PCIE_TX_N <<<
17 WLAN_PCIE_TX_P <<<
16 WLAN_CLK_CPU_P >>>
16 WLAN_CLK_CPU_N >>>
16 WLAN_CLKREQ_CPU_N >>>

18 BT_USB20_N <<<
18 BT_USB20_P <<<

16 PULSAR_38P4M_REFCLK >>>

15,26,31,63,79,91 PLT_RST# >>>

17 CNV_WR_DN1 <<<
17 CNV_WR_DP1 <<<
17 CNV_WR_DN0 <<<
17 CNV_WR_DP0 <<<
17 CNV_WR_CLKN <<<
17 CNV_WR_CLKP <<<
17 CNV_WT_DN1 <<<
17 CNV_WT_DP1 <<<
17 CNV_WT_DN0 <<<
17 CNV_WT_DP0 <<<
17 CNV_WT_CLKN <<<
17 CNV_WT_CLKP <<<

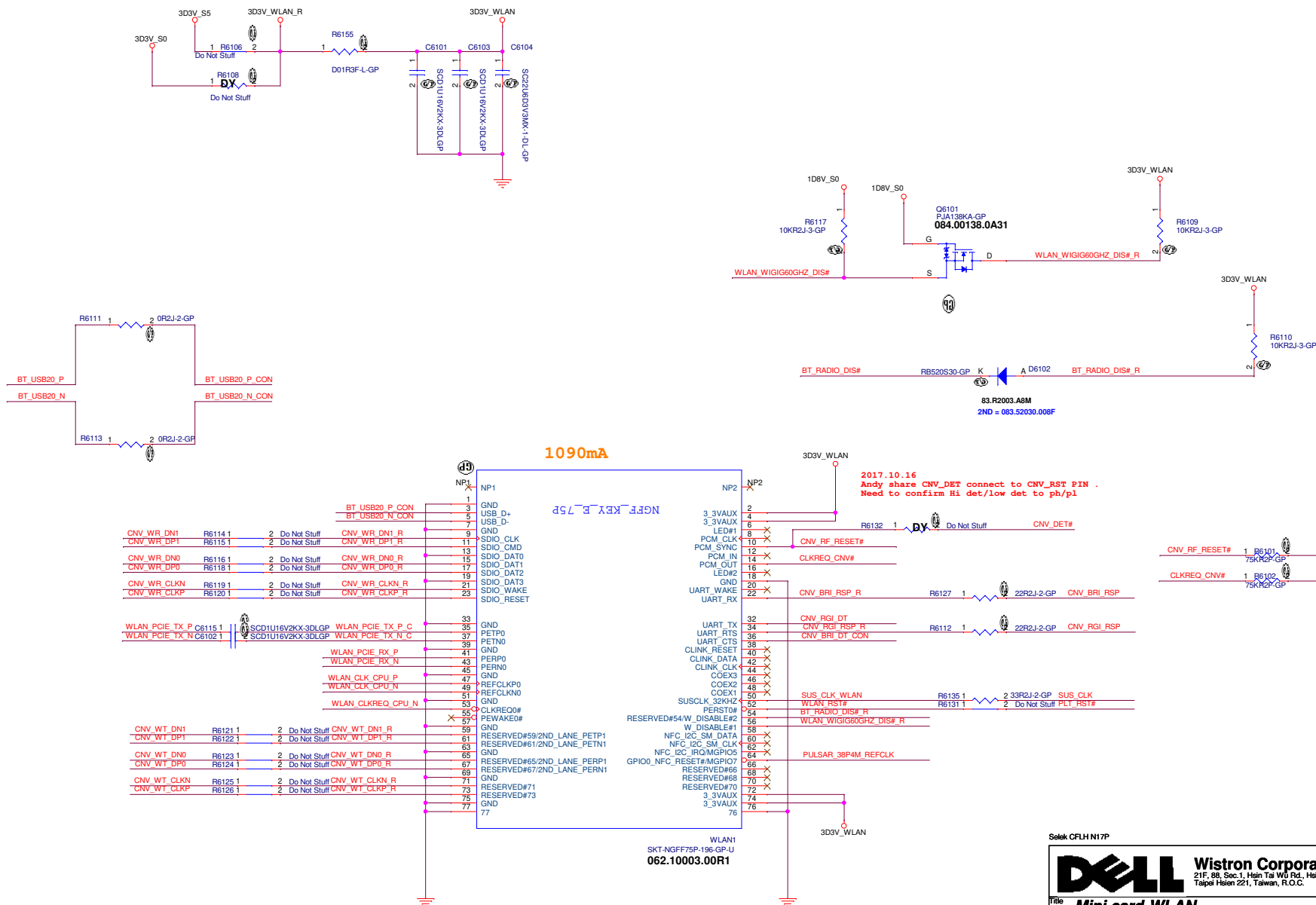
17 CNV_BRI_RSP <<<
17,21 CNV_RGI_DT <<<
17 CNV_BRI_DT_CON <<<
17 CNV_RGI_RSP <<<
15 CNV_RF_RESET# <<<

15 CLKREQ_CNV# >>>

20 WLAN_WIGIG60GHZ_DIS# >>>
20 BT_RADIO_DIS# >>>

15 SUS_CLK >>>

20 CNV_DET# >>>



Selek CFLH N17P

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Title Mini card-WLAN					
Size Custom	Document Number Selek CFL-H				Rev A00
Date: Wednesday, 7 April 2019 Sheet 61 of 105					

SSID = Wireless

Selek CFLH N17P



Wistron Corporation

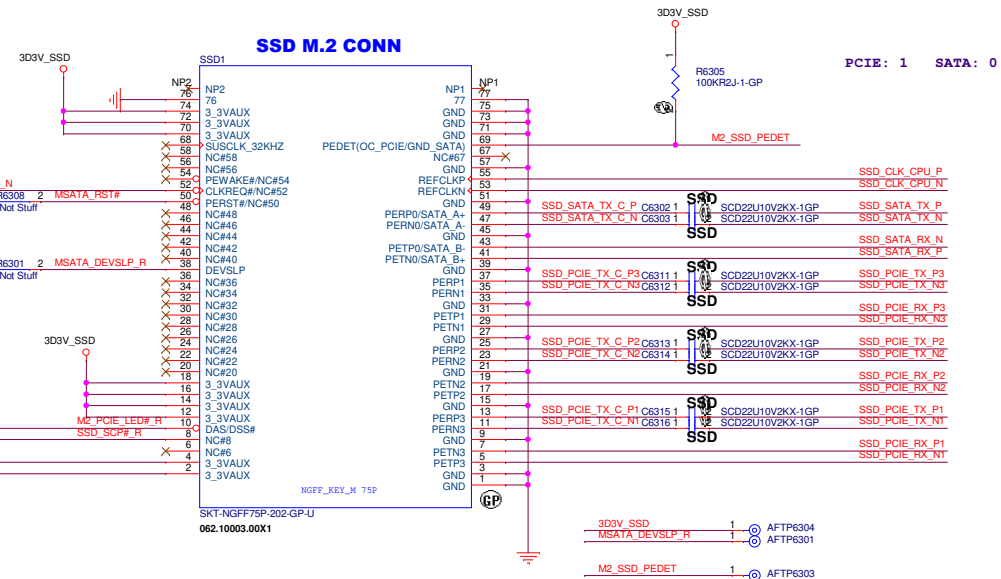
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.


Title **(Reserved)WWAN**

Size A	Document Number Selek CFL-H	Rev A00
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Mini Card Connector (NGFF m-SATA)

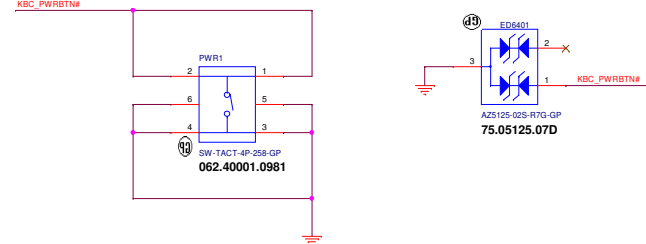


		Wistron Corporation 21F, 38, Sec.1, Hsin Tai Wu Rd., Hsuehshih, Taipei Hsien 221, Taiwan, R.O.C.	
Title SSD-NGFF			
Size Custom	Document Number Selek CFL-H		Rev A000
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SSID = User.Interface

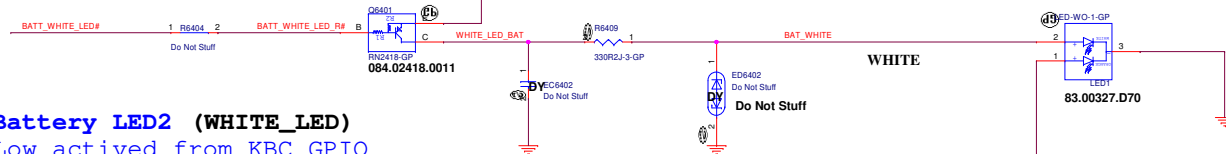
Power button

NONE FINGER PRINT 才會上件



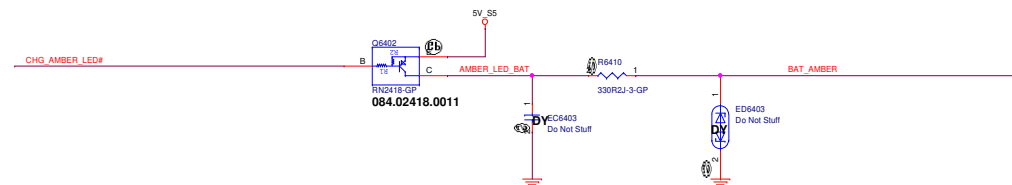
Battery LED1 (AMBER_LED)

Low activated from KBC GPIO

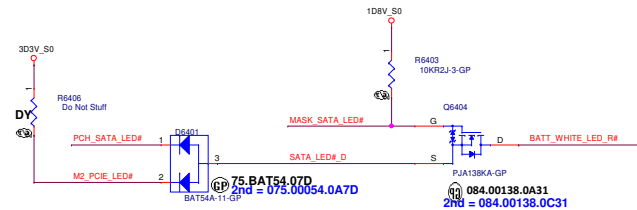


Battery LED2 (WHITE_LED)

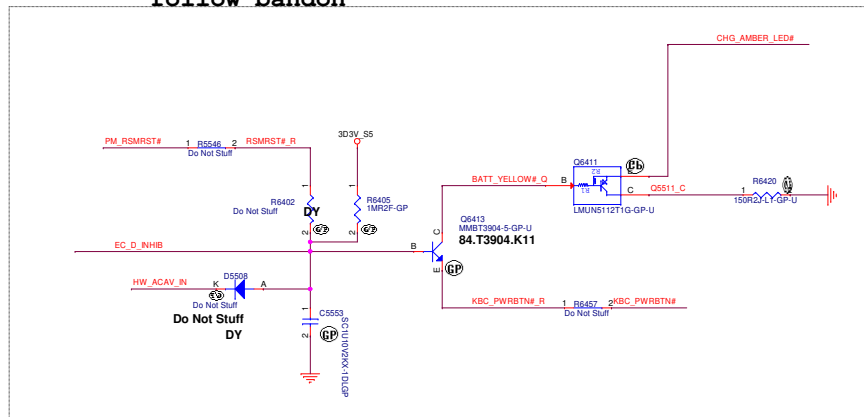
Low activated from KBC GPIO



SATA LED

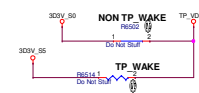
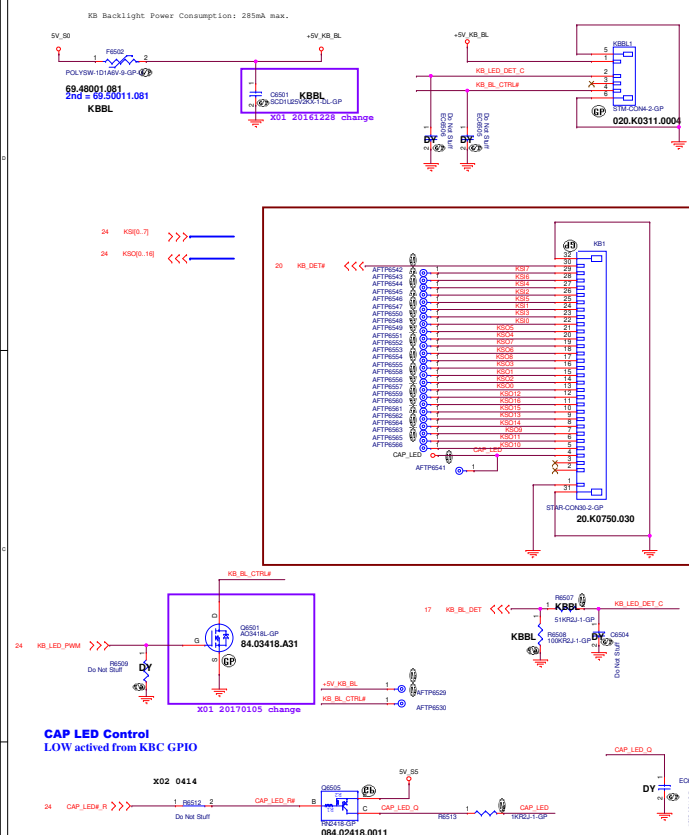


M-BIST for G10 (Proposed schematic) follow bandon

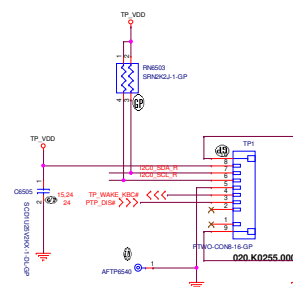
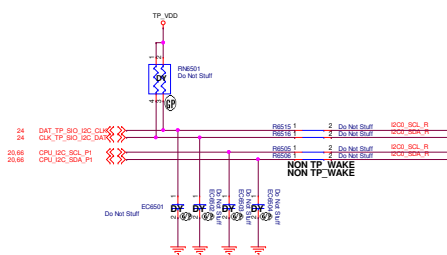


Selek CFLH N17P

Main Func = TPAD

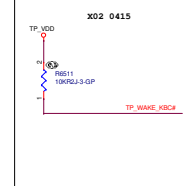


GPIO_TPAD: TBD
(Touch pad wake# for S3 wake up @ PCH GPIO??)



Change pindefine DVT1 0210 1330

Need to check if it is Active High or Active Low
~~and check if there is PH on TPAD side.~~



Pin number	Pin name
1	VDD
2	DAT (I2C)
3	CLK (I2C)
4	GND
5	ATTN
6	GPIO
7	DAT (PS2)
8	CLK (PS2)

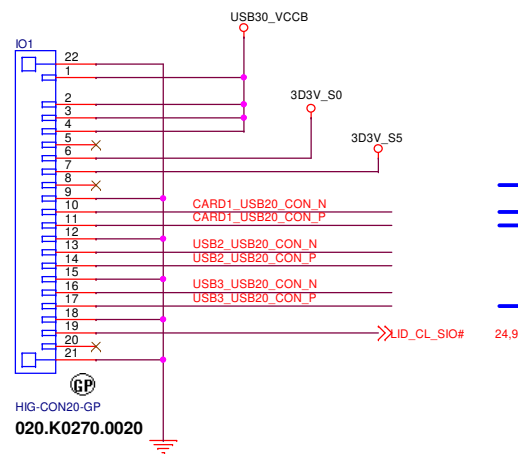


18 USB3_USB20_P
18 USB3_USB20_N
18 USB2_USB20_P
18 USB2_USB20_N

18 CARD1_USB20_N
18 CARD1_USB20_P

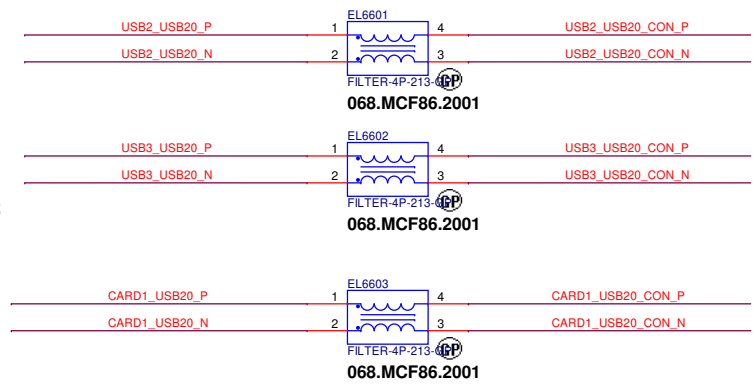
20.65 CPU_I2C_SCL_P1
20.65 CPU_I2C_SDA_P1

44 BT_PWR_IN-
44 BT_PWR_IN+

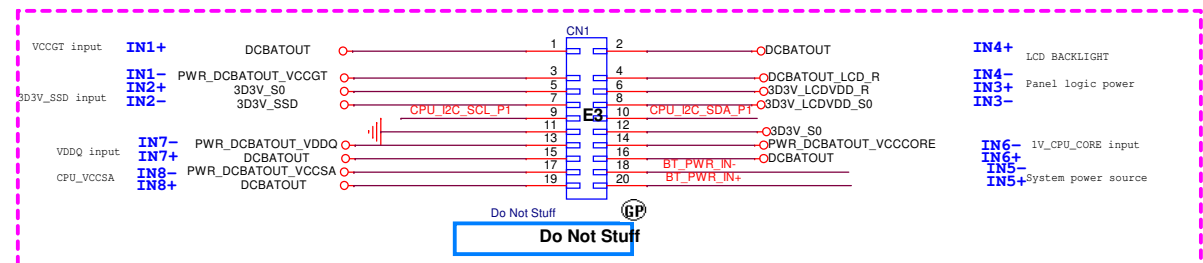


Cardreader

USB 2.0 Gen1 *2



E3 reserve



Selek CFLH N17P

DELL Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title **IO Board Connector**

Size A3 Document Number **Selek CFL-H** Rev **A00**

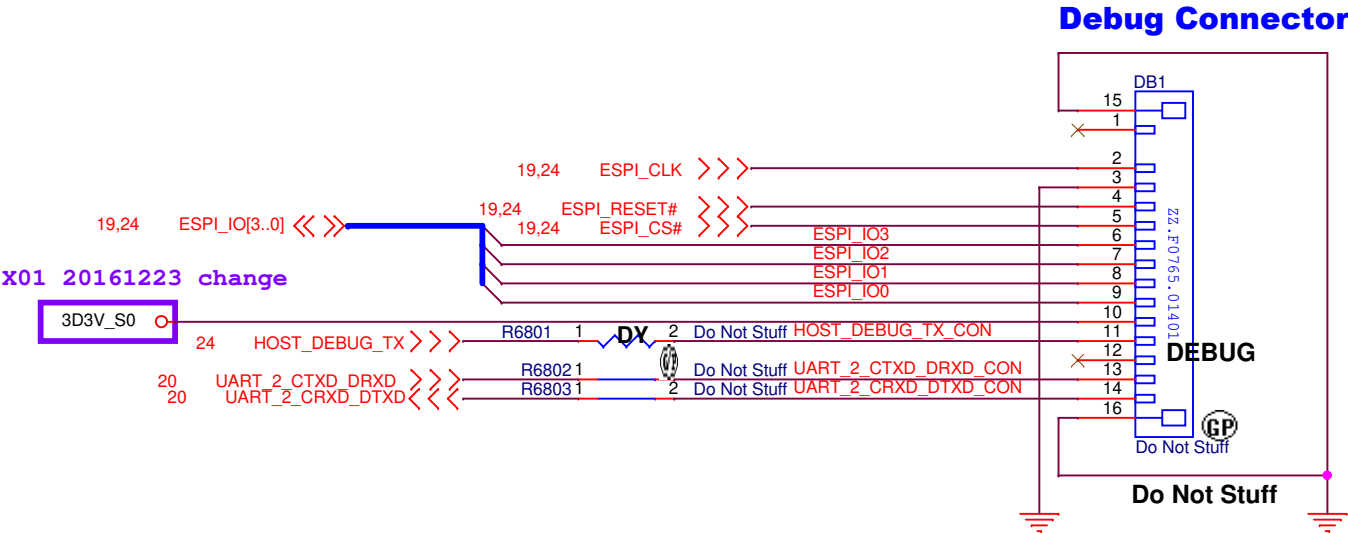
Date: Wednesday, April 03, 2019 Sheet 66 of 105

Main Func = Hall Sensor


Selek CFLH N17P

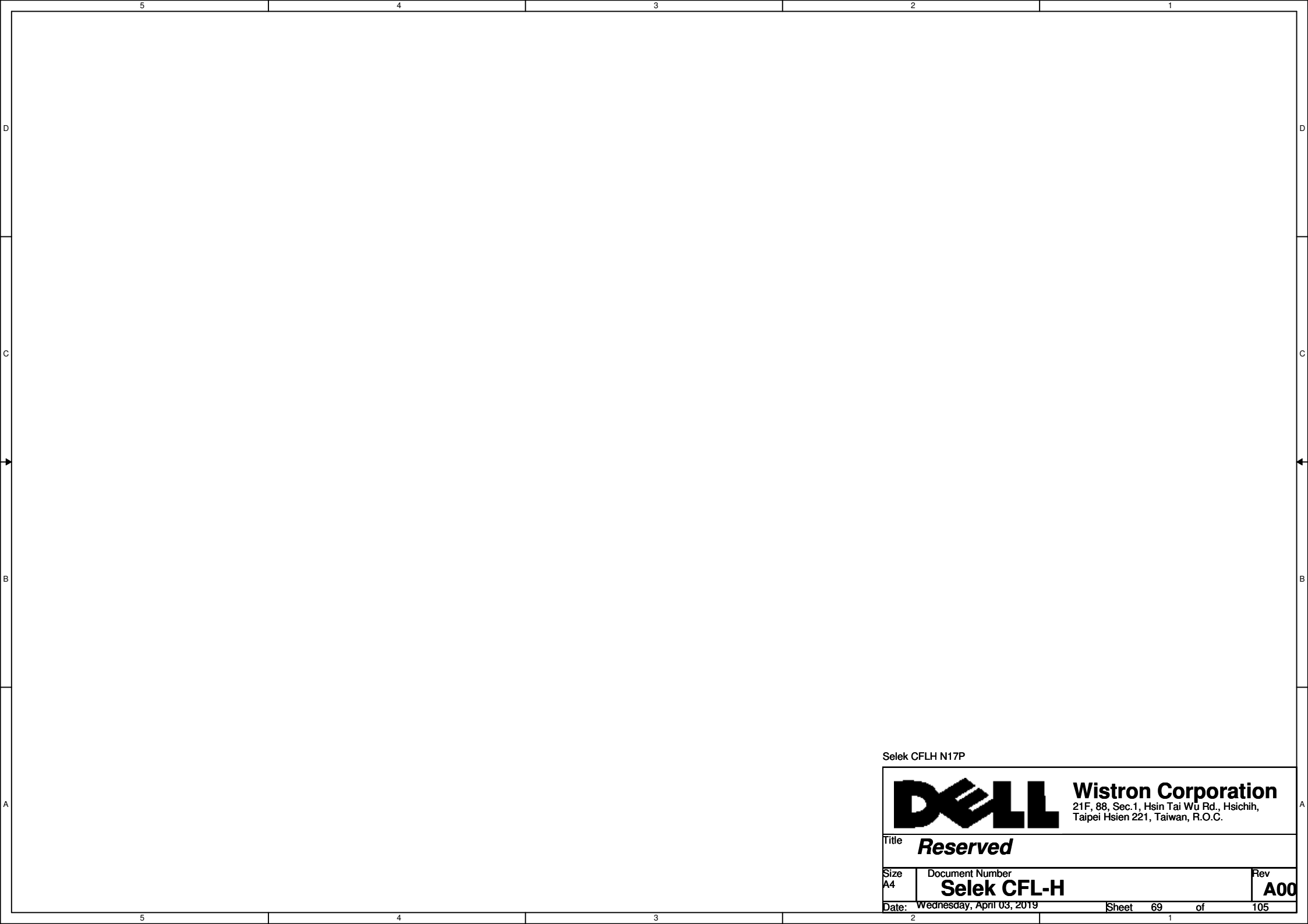
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Title Hall Sensor			
Size A	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019		Sheet 67 of	105

Main Func = Debug



Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title Dubug connector			
Size A4	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019		Sheet 68 of	105



Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title Reserved			
Size A4	Document Number Selek CFL-H		Rev A00
Date: Wednesday, April 03, 2019	Sheet 69	of	105

```

20      GSEN2_INT1_C  <<<=====
20      GSEN2_INT2_C  <<<=====

20  CPU_I2C_SDA_ISH  <<<=====
20  CPU_I2C_SCL_ISH  <<<=====

60      FFS_INT2_Q  <<<=====

```

[illegible][illegible]

3D3V_S0

R7018
100KR2J-1-GP

FALL_INT2

Q7001

Do Not Stuff

Do Not Stuff

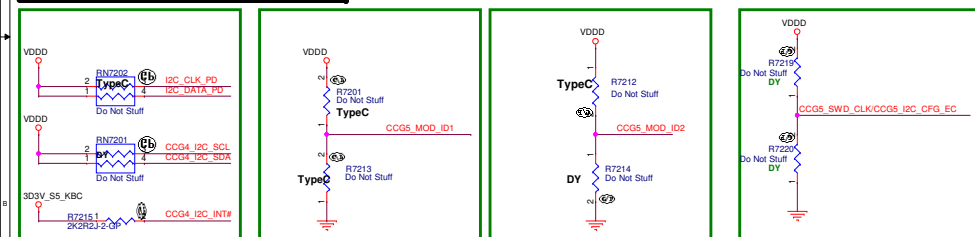
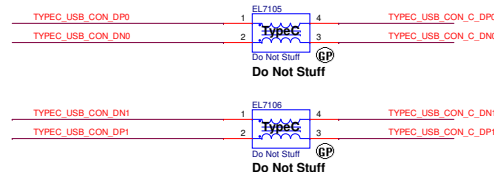
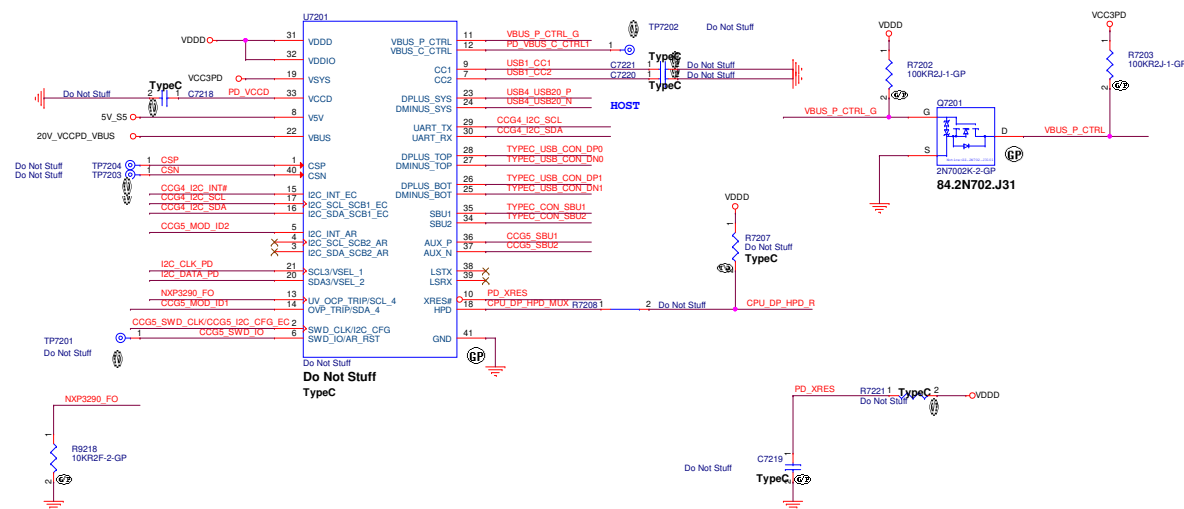
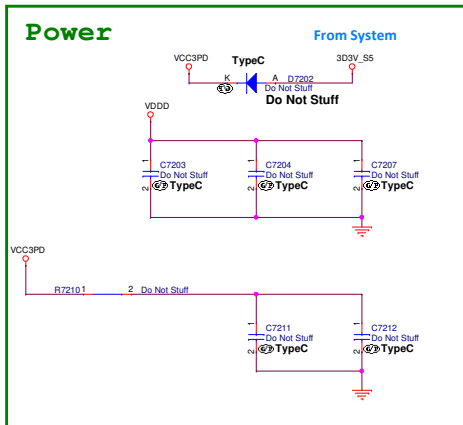
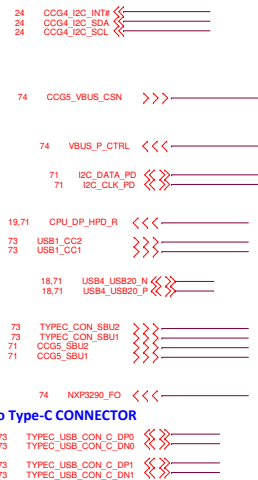
2nd = 075.67002.00%

INT2_SELECT

FFS

FFS_INT2_Q

Main Func = TYPEC CONTROLLER



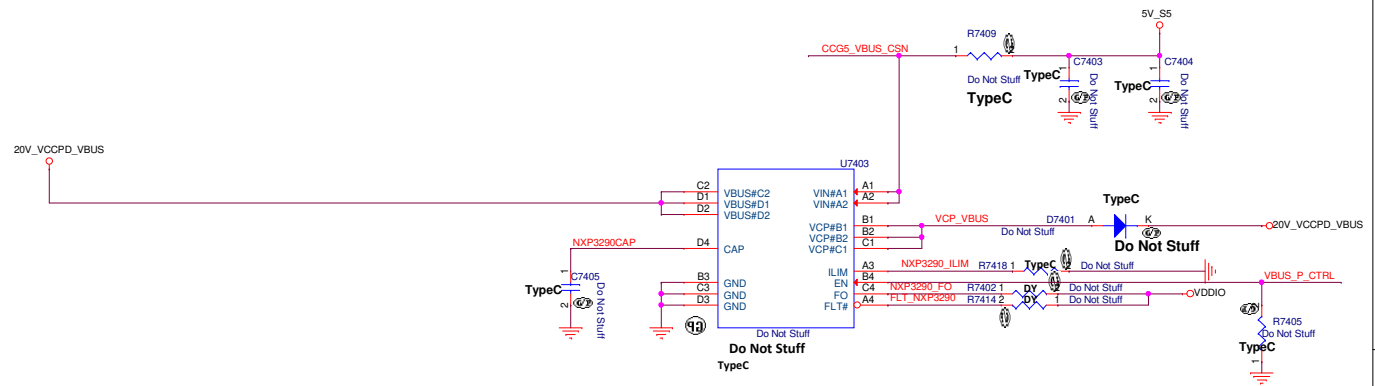
Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title				USB3.0 PORT			
Size	Custom	Document Number	Rev				
		Selek CFL-H	A00				
Date:	Wednesday, April 03, 2019		Sheet	72	of	105	

Sheet 73 of 105

Main Func = LPS

72 VBUS_P_CTRL >>>—
72 NXP3290_FO <<<—
72 CCG5_VBUS_CSN <<<—




Selek CFLH N17P

DELL Wistron Corporation 21F, 88, Sec.1, Hsin Tai W6 Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
File LPS		
Size Custom	Document Number Selek CFL-H	Rev A00
Date Wednesday, April 03, 2019	Sheet 74	of 105

	5	4	3	2	1
D					D
C					C
B					B
A					A
	5	4	3	2	1

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <i>(Reserved)Thunderbolt (5/5)</i>			
Size A	Document Number Selek CFL-H		Rev A00
Date:	Wednesday, April 03, 2019	Sheet 75 of	105

• PEX_HVDD and PEX_PLL_HVDD rails must be shared with 1V8_AON for GC6 2.1

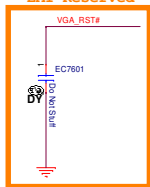
GPU	Capacitor Type	Footprint	N18	N17	Location
PEX_DVDD Supply Rail					
GB4C-128, GB4D-128	1.0 μ F	X65	0402 or 0201W	0	Under GPU
	0.47 μ F	X65	0201W	12	Under GPU
	4.7 μ F	X65	0603	0	Near GPU
	4.7 μ F	X65	0603	3	Under GPU
	10 μ F	X5R	0805	0	Midway between GPU and power supply
	10 μ F	X65	0805	3	Near GPU
	22 μ F	X5R	0805	0	Midway between GPU and power supply
	22 μ F	X65	0805	2	Near GPU

PEX_HVDD Supply Rail									
GB4C-128, GB4D-128	1.0 μ F	X65	0402 or 0201W	0	4	Under GPU			
	0.47 μ F	X65	0201W	13	0	Under GPU			
	4.7 μ F	X65	0603	0	2	Near GPU			
	4.7 μ F	X65	0603	3	0	Under GPU			
	10 μ F	X5R	0805	0	2	Midway between GPU and power supply			
	10 μ F	X5S	0805	3	0	Near GPU			
	22 μ F	X5R	0805	0	1	Midway between GPU and power supply			
	22 μ F	X65	0805	2	0	Near GPU			

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

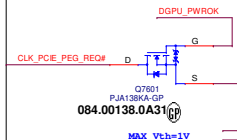
EMI Reserved

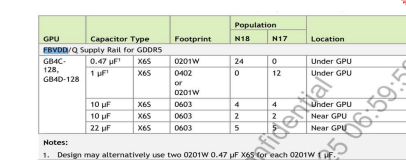
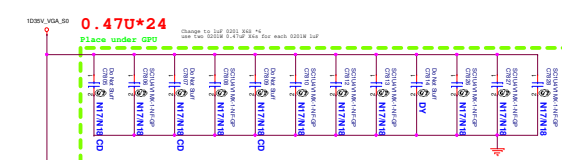
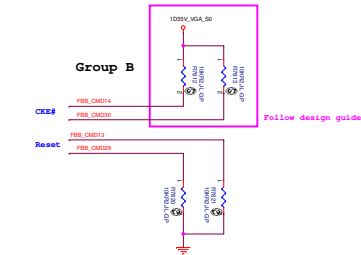
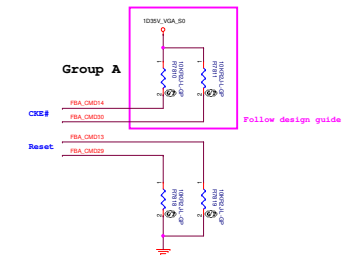
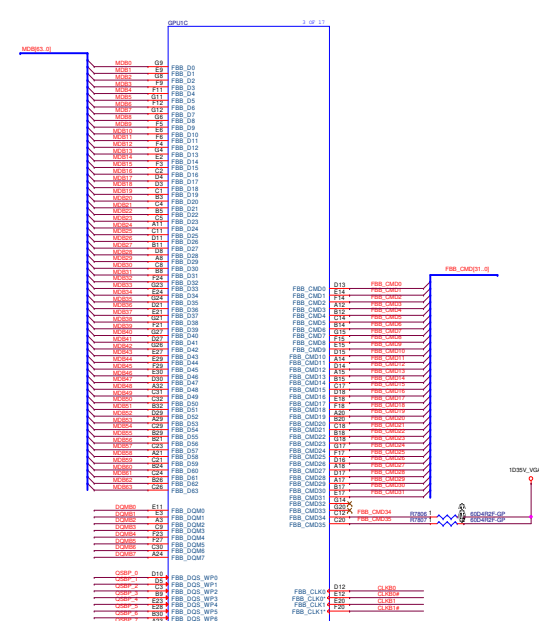


15,24,86 DGPU_PWROK
16 CLK_PCIE_PEG_REQ#
79 VGA_RST#

3 GFX_PCIE_RX_P7
3 GFX_PCIE_RX_N7
3 GFX_PCIE_RX_P8
3 GFX_PCIE_RX_N8
3 GFX_PCIE_RX_P9
3 GFX_PCIE_RX_N9
3 GFX_PCIE_RX_P10
3 GFX_PCIE_RX_N10
3 GFX_PCIE_RX_P11
3 GFX_PCIE_RX_N11
3 GFX_PCIE_RX_P12
3 GFX_PCIE_RX_N12
3 GFX_PCIE_RX_P13
3 GFX_PCIE_RX_N13
3 GFX_PCIE_RX_P14
3 GFX_PCIE_RX_N14
3 GFX_PCIE_RX_P15
3 GFX_PCIE_RX_N15
3 GFX_PCIE_RX_P16
3 GFX_PCIE_RX_N16
3 GFX_PCIE_RX_P17
3 GFX_PCIE_RX_N17

3 GFX_PCIE_TX_CON_P7
3 GFX_PCIE_TX_CON_N7
3 GFX_PCIE_TX_CON_P8
3 GFX_PCIE_TX_CON_N8
3 GFX_PCIE_TX_CON_P9
3 GFX_PCIE_TX_CON_N9
3 GFX_PCIE_TX_CON_P10
3 GFX_PCIE_TX_CON_N10
3 GFX_PCIE_TX_CON_P11
3 GFX_PCIE_TX_CON_N11
3 GFX_PCIE_TX_CON_P12
3 GFX_PCIE_TX_CON_N12
3 GFX_PCIE_TX_CON_P13
3 GFX_PCIE_TX_CON_N13
3 GFX_PCIE_TX_CON_P14
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3 GFX_PCIE_TX_CON_P15
3 GFX_PCIE_TX_CON_N15
3 GFX_PCIE_TX_CON_P16
3 GFX_PCIE_TX_CON_N16
3 GFX_PCIE_TX_CON_P17
3 GFX_PCIE_TX_CON_N17





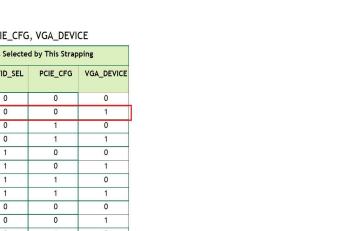
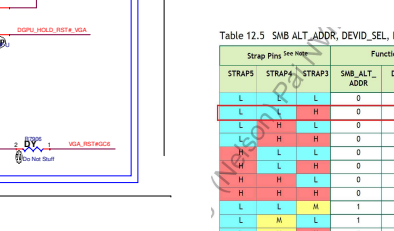
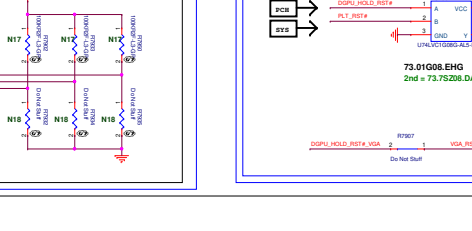
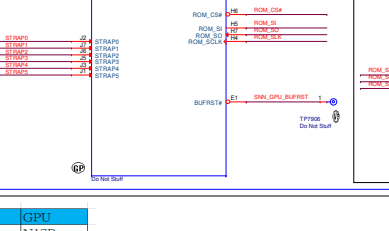
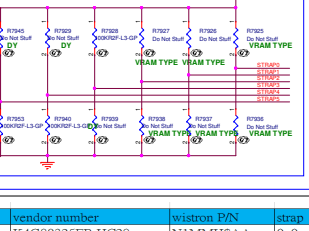
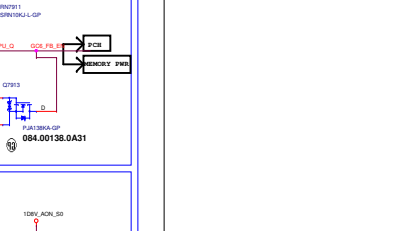
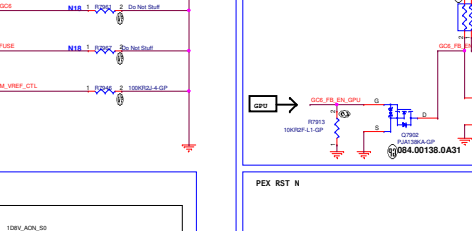
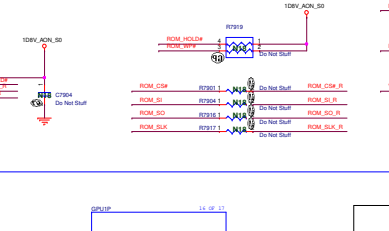
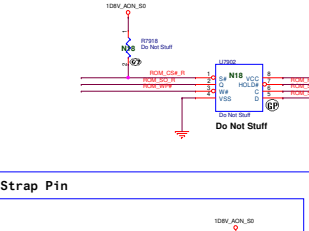
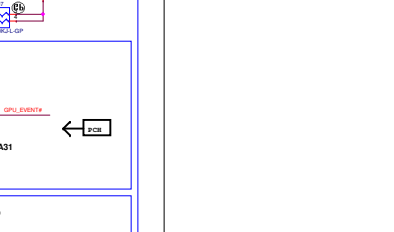
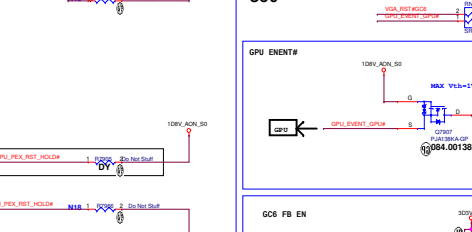
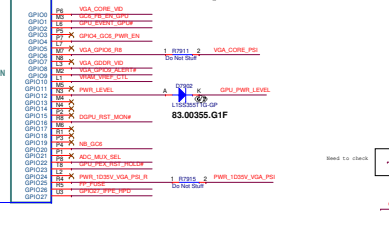
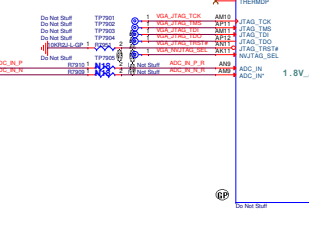
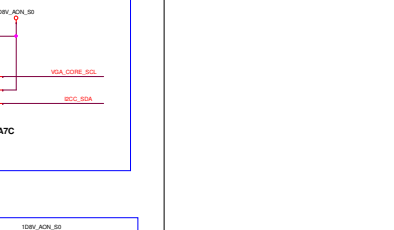
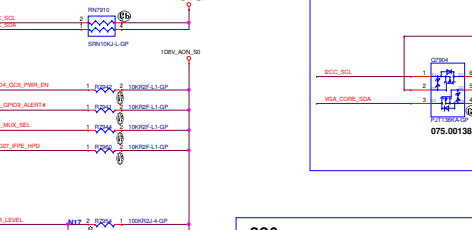
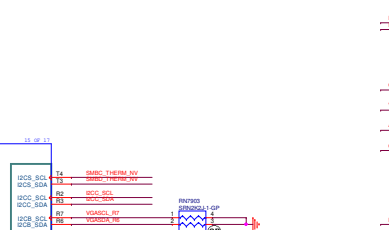
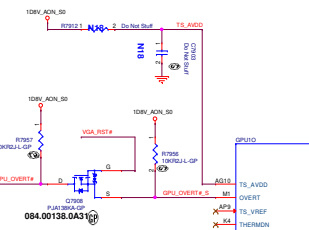
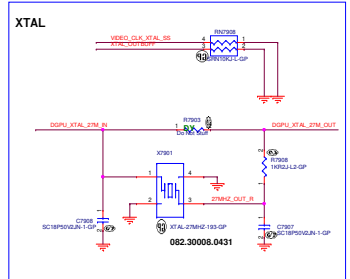
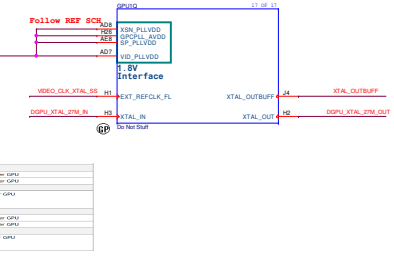
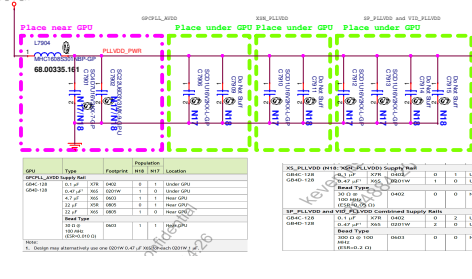
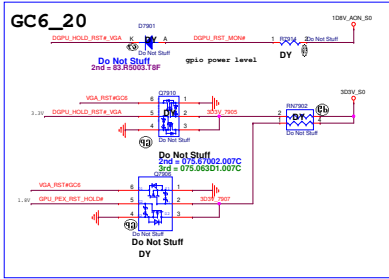
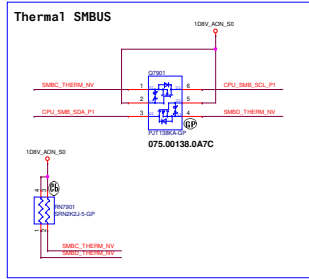
GPU	Capacitor Type	Footprint	Population		Location
			N18	N17	
RV800/Q Supply Rail for GDDR5					
GB4C-128,	0.47 μ F	X65	0201W	24	0
GB4D-128	1 μ F	X65	0402 or 0201W	0	12
	10 μ F	X65	0603	4	4
	10 μ F	X65	0603	2	2
	22 μ F	X65	0603	5	5

Notes:

- Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

Notes:

- Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.



Strap2	Strap1	Strap0	Vendor	Vendor number	wistron P/N	Strap	GPU
L	L	L	Samsung	K4G80325FB-HC28	N1MMHSA	0x0	N17P
L	L	H	Micron	MT51J256M32HF-80-B	MHVDSAA	0x1	N18P
L	H	L	Hynix	H5GCS824AJR-R2C	GVK6KSA	0x2	N18P
L	L	L	Samsung	K4G80325FC-HC25	J62CNSAA	0x0	N18P

Strap2	Strap1	Strap0	Vendor	Vendor number	wistron P/N	Strap	GPU
L	L	L	Samsung	K4G80325FB-HC28	N1MMHSA	0x0	N17P
L	L	H	Micron	MT51J256M32HF-80-B	MHVDSAA	0x1	N18P
L	H	L	Hynix	H5GCS824AJR-R2C	GVK6KSA	0x2	N18P
L	L	L	Samsung	K4G80325FC-HC25	J62CNSAA	0x0	N18P

Table 4. N18P-G0 GDDR5 Recommended Memories

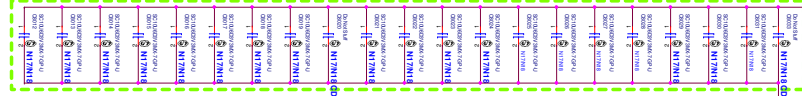
Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Speed Grade	Date Code	Alert	Qual Plan	Status
8 Gb	256Mx32	1.35V and 1.5V ¹	Micron	MT51J256M32HF-80-B	B-die	0x1	8 Gbps	N/A		Full	Production candidate
			Hynix	H5GCB24AJR-R2C	A-die	0x2	8 Gbps	N/A		Full	Production candidate
			Samsung	K4G80325FC-HC25	C-die	0x0	8 Gbps	N/A		Full	Production candidate

Strap2	Strap1	Strap0	Vendor	Vendor number	wistron P/N	Strap	GPU
L	L	L	Samsung	K4G80325FB-HC28	N1MMHSA	0x0	N17P
L	L	H	Micron	MT51J256M32HF-80-B	MHVDSAA	0x1	N18P
L	H	L	Hynix	H5GCS824AJR-R2C	GVK6KSA	0x2	N18P
L	L	L	Samsung	K4G80325FC-HC25	J62CNSAA	0x0	N18P

Table 12.5 SMB_ALT_ADOR, DEVID_SEL, PCIE_CFG, VGA_DEVICE

Strap2	Strap1	Strap0	Vendor	Vendor number	wistron P/N	Strap	GPU
L	L	L	Samsung	K4G80325FB-HC28	N1MMHSA	0x0	N17P
L	L	H	Micron	MT51J256M32HF-80-B	MHVDSAA	0x1	N18P
L	H	L	Hynix	H5GCS824AJR-R2C	GVK6KSA	0x2	N18P
L	L	L	Samsung	K4G80325FC-HC25	J62CNSAA	0x0	N18P

10U*21
Place under GPU



10U*13
Place under GPU



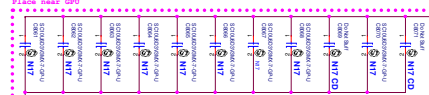
1U*13
Place under GPU



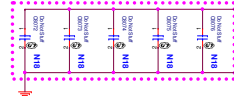
0.47U*26
Place under GPU



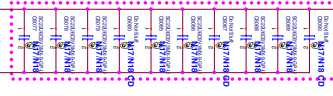
10U*11
Place near GPU



22U*5
Place near GPU



22U*10
Place near GPU



330U*1 4.7U*2
Place near GPU

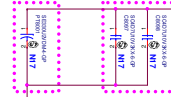


Table 2. NVDD Decoupling and Filtering

GPU	Capacitor Type	Footprint	Population	N18	N17	Location
NVDD Supply Net						
GB4C-128, GB4D-128	10 μ F	X65	0603	34	21	Under GPU
	1 μ F ¹	X65	0402 or 0201W	0	13	Under GPU
	0.47 μ F ¹	X65	0402 or 0201W	26	0	Under GPU
	10 μ F	X65	0603	0	11	Near GPU
	22 μ F	X65	0805	15	10	Near GPU
	4.7 μ F	X65	0603	0	2	Near GPU
	330 μ F	POS	7343	0	1	Near GPU

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

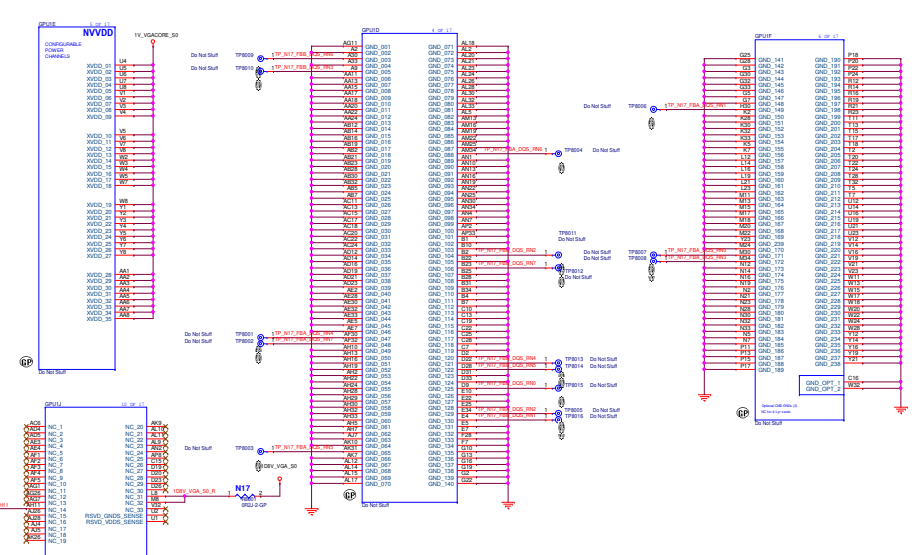
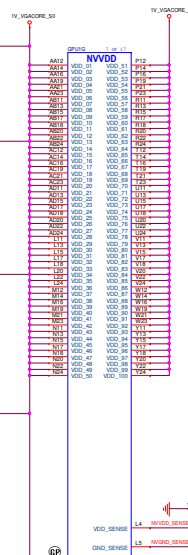


Table 9. VDD_AON and VDD_MAIN Decoupling

GPU	Capacitor Type	Footprint	Population	N18	N17	Location
N17 VDD18 (N18 NC) Supply Rail						
GB4C-128, GB4D-128	0.1 μ F	X78	0402	N/A	2	Under GPU
	1.0 μ F	X65	0603	N/A	1	Near GPU
	4.7 μ F	X65	0603	N/A	1	Near GPU
1V8_AON Supply Rail						
GB4C-128, GB4D-128	0.1 μ F	X78	0402	0	2	Under GPU
	0.47 μ F	X65	0201W	4	0	Under GPU
	1.0 μ F	X65	0402 or 0201W	0	1	Near GPU
	0.47 μ F ¹	X65	0201W	6	0	Near GPU
	4.7 μ F	X65	0603	3	1	Near GPU

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

78 MDA[63..0] << >>
78 FBA_CMD[31..0] << >>

78 DQMA0 <>
78 DQMA1 <>
78 DQMA2 <>
78 DQMA3 <>
78 DQMA4 <>
78 DQMA5 <>
78 DQMA6 <>
78 DQMA7 <>

78 QSAP_0 <>
78 QSAP_1 <>
78 QSAP_2 <>
78 QSAP_3 <>
78 QSAP_4 <>
78 QSAP_5 <>
78 QSAP_6 <>
78 QSAP_7 <>

78 FBA_WCK01 <>
78 -FBA_WCK01 <>
78 FBA_WCK23 <>
78 -FBA_WCK23 <>
78 FBA_WCK45 <>
78 -FBA_WCK45 <>
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78 -FBA_WCK67 <>

78 CLKA0 <>
78 CLKA0# <>
78 CLKA1 <>
78 CLKA1# <>

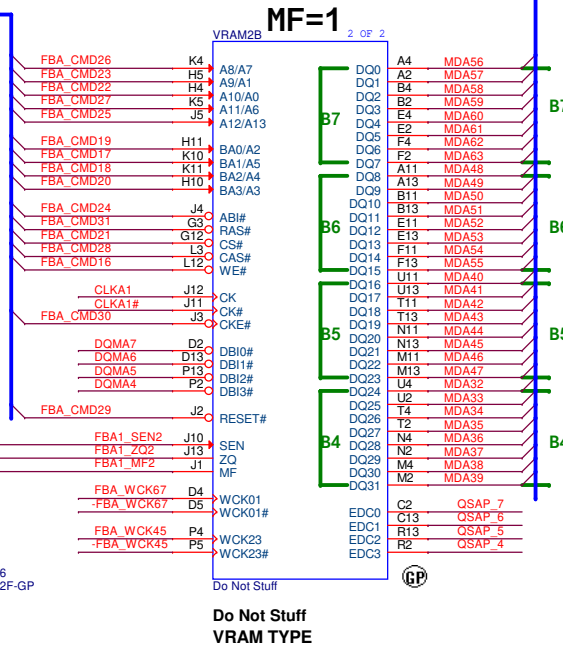
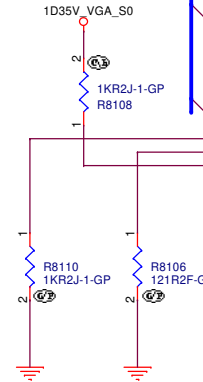
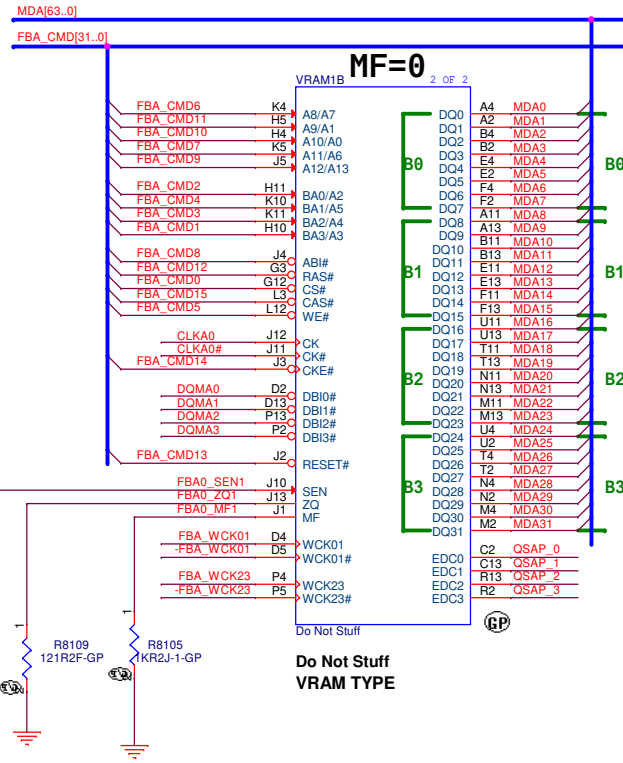
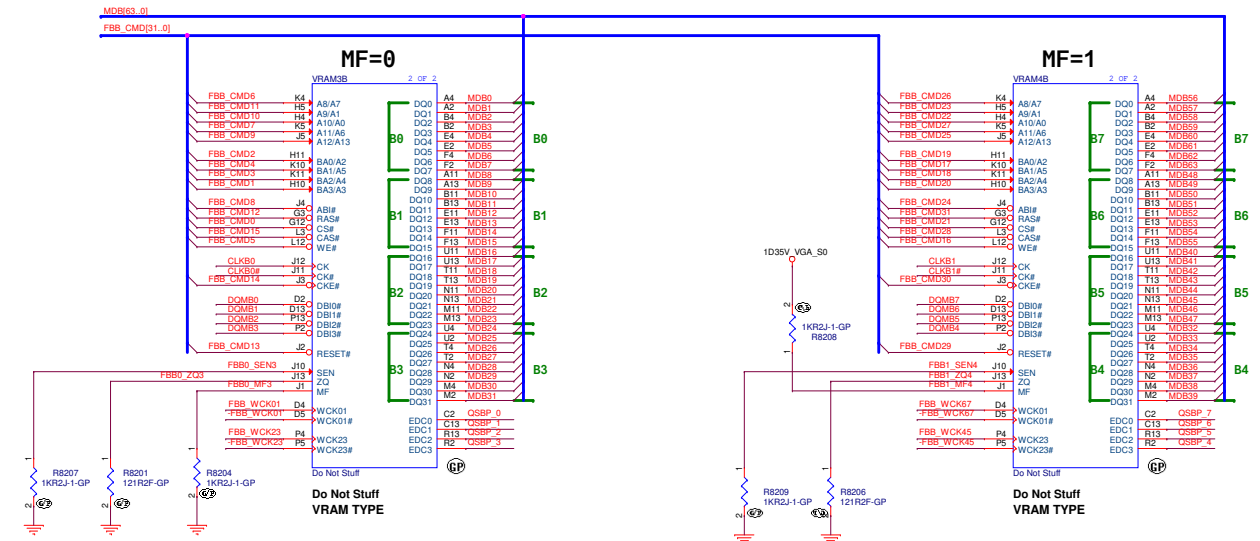


Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	ABI*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RAS*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CAS*

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Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	AB1*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RA5*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CAS*

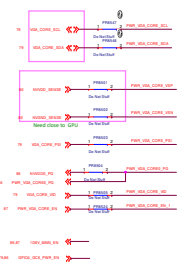


Table 7.8 PWM-VID Spec and Component Values

PWM-VID Specification		Unit	Config
Number of Voltage Levels N	level	160	
PWM Frequency F _{PWM}	MHz	675	
PWM Minimum Pulse Width T _{PWM}	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (Ω)	Ω	6.19	
R2 (Ω)	Ω	20.5	
R3 (Ω)	Ω	4.32	
R4 (Ω)	Ω	16.5	
R5 (Ω)	Ω	8.0	
C	μF	0.01	

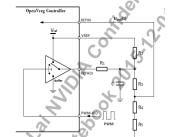
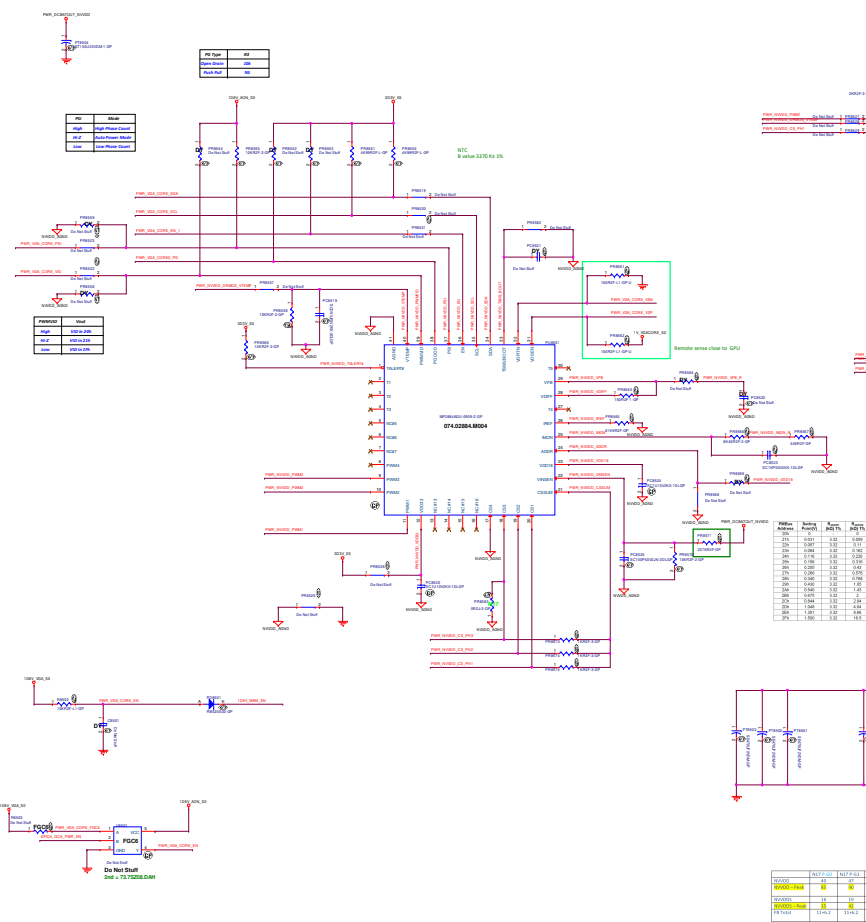


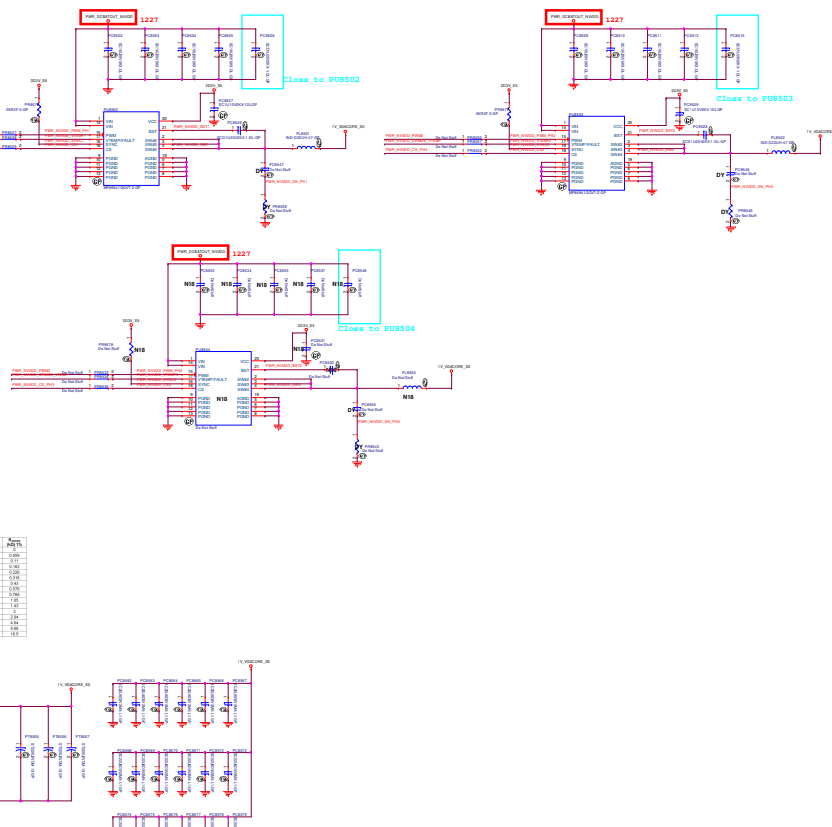
Table 7.9 PWM-VID Spec and Component Values

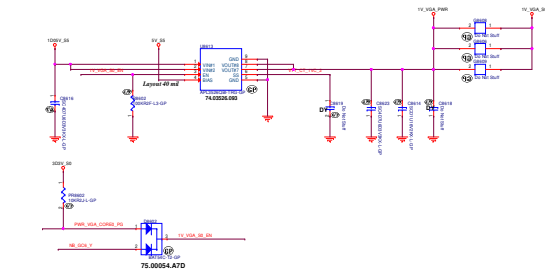
PWM-VID Specification		Unit	Config
V _{min}	V	0.3	
V _{max}	V	1.3	
V _{boot}	V	0.8	
Voltage Step Width	mV	6.25	
Number of Voltage Levels N	level	160	
PWM Frequency F _{PWM}	MHz	675	
PWM Minimum Pulse Width T _{PWM}	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (Ω)	Ω	6.19	
R2 (Ω)	Ω	20.5	
R3 (Ω)	Ω	4.32	
R4 (Ω)	Ω	16.5	
R5 (Ω)	Ω	8.0	
C	μF	0.01	



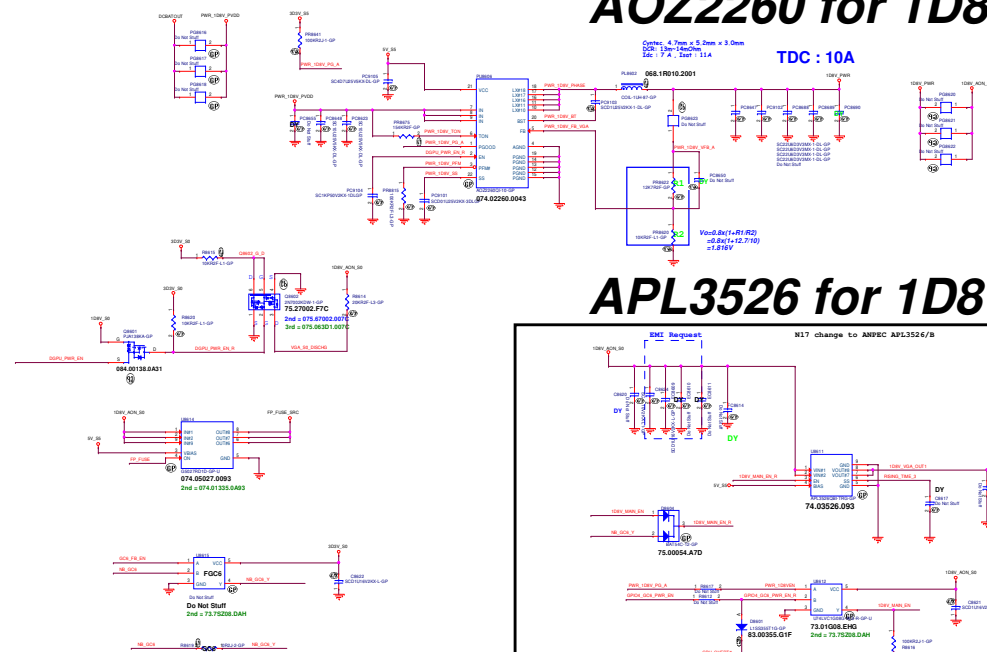
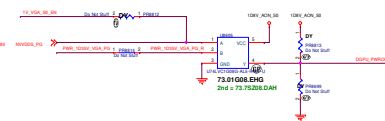
PWM-VID Spec and Component Values		Unit	Config
Number of Voltage Levels N	level	160	
PWM Frequency F _{PWM}	MHz	675	
PWM Minimum Pulse Width T _{PWM}	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (Ω)	Ω	6.19	
R2 (Ω)	Ω	20.5	
R3 (Ω)	Ω	4.32	
R4 (Ω)	Ω	16.5	
R5 (Ω)	Ω	8.0	
C	μF	0.01	

PWM-VID Spec and Component Values		Unit	Config
Number of Voltage Levels N	level	160	
PWM Frequency F _{PWM}	MHz	675	
PWM Minimum Pulse Width T _{PWM}	ns	1.5	
VID Transient Time T	us	1000	
Component Value			
R1 (Ω)	Ω	6.19	
R2 (Ω)	Ω	20.5	
R3 (Ω)	Ω	4.32	
R4 (Ω)	Ω	16.5	
R5 (Ω)	Ω	8.0	
C	μF	0.01	

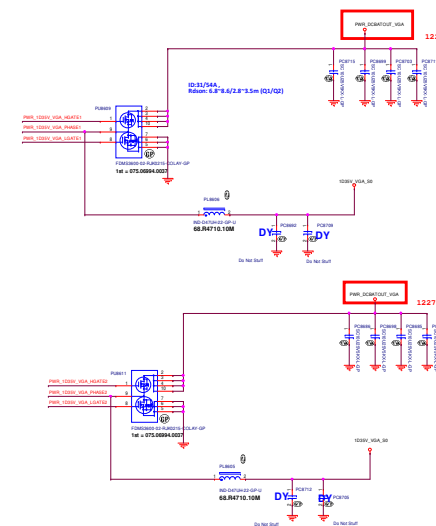
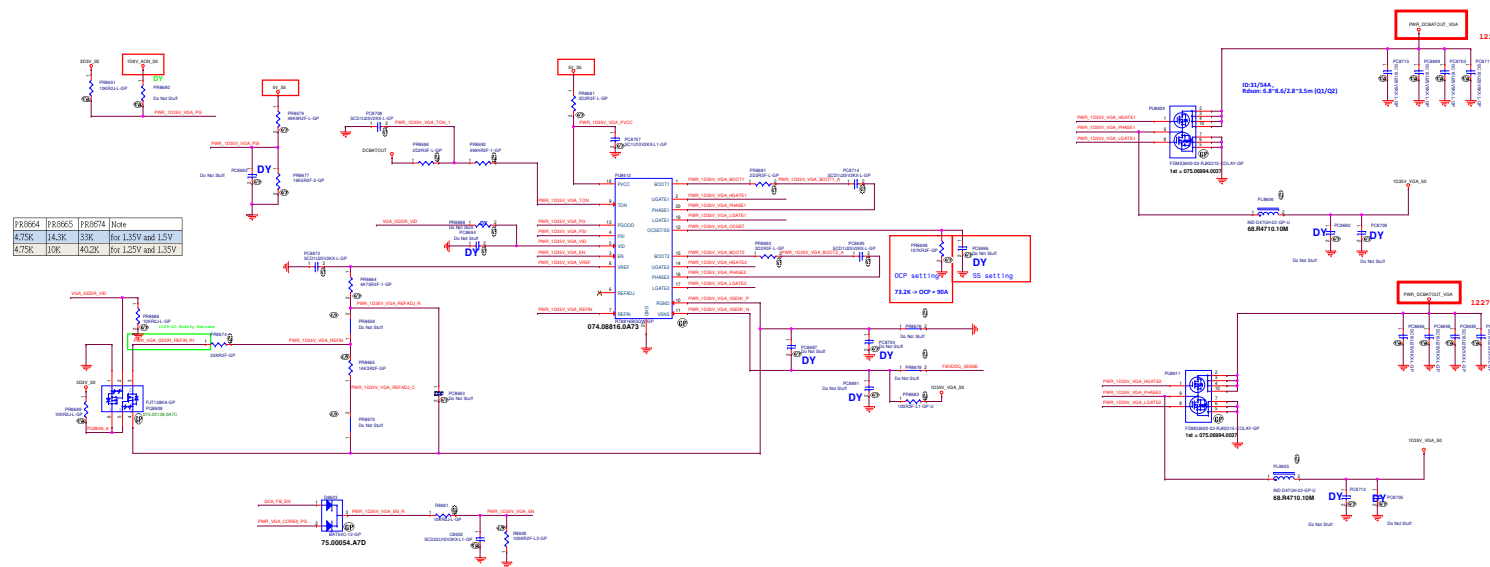
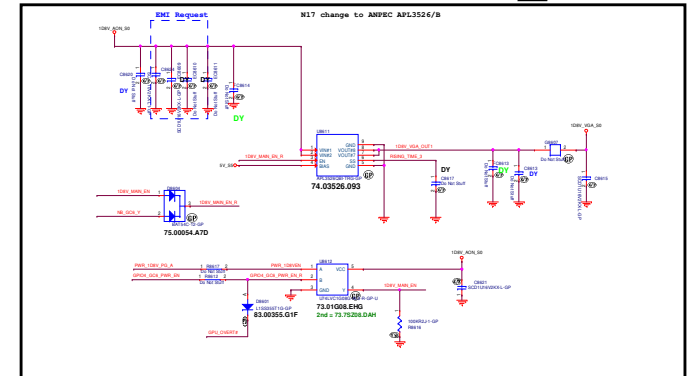




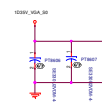
Operational Efficiency Reduction	PMI Mortgage Workout
Excess cash to the bank	0% to 0.5%
Excess cash to the CMA	0.75% to 0.88%
Excess cash to the CMA	1.00% to 1.20%
Excess cash to the CMA	1.25% to 1.50%



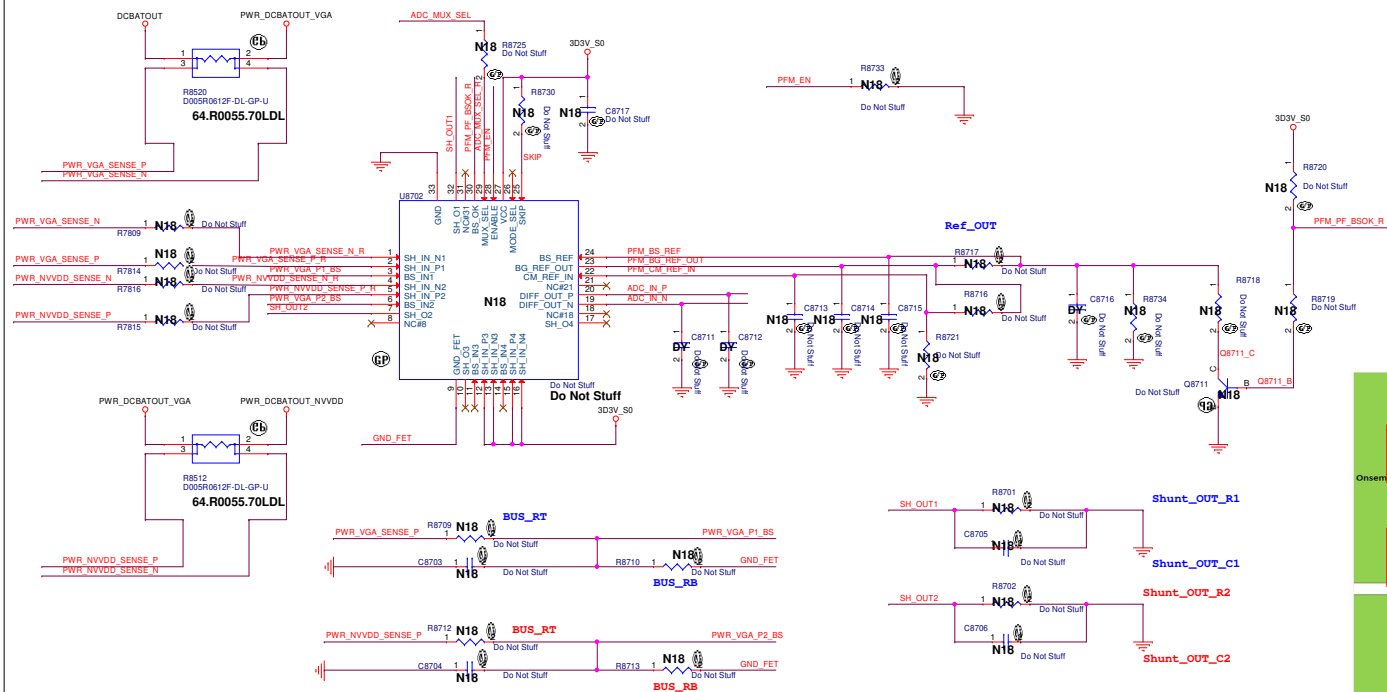
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APL3526 for 1D8V_MAIN

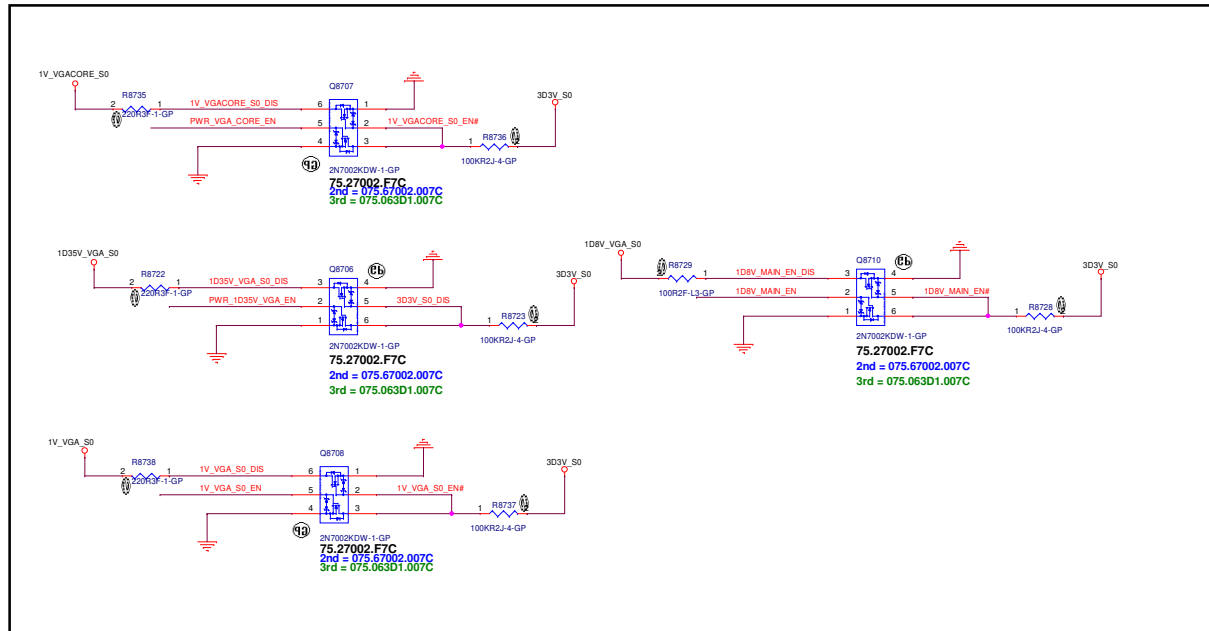
Design Current : 32.8A
OCP : 59.4A



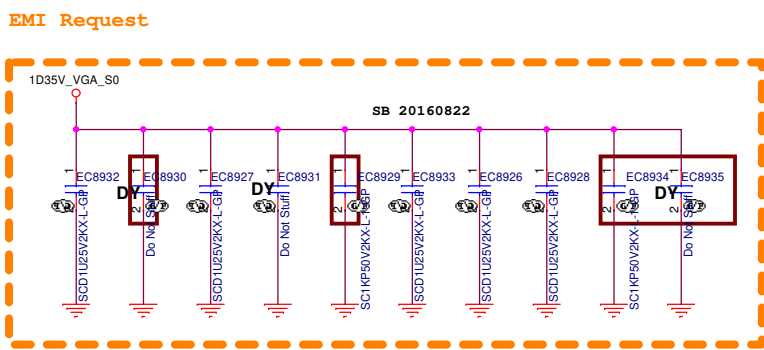
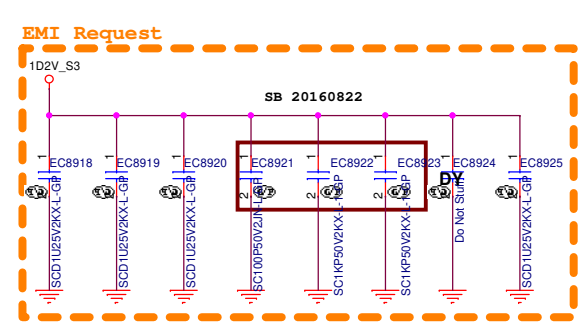
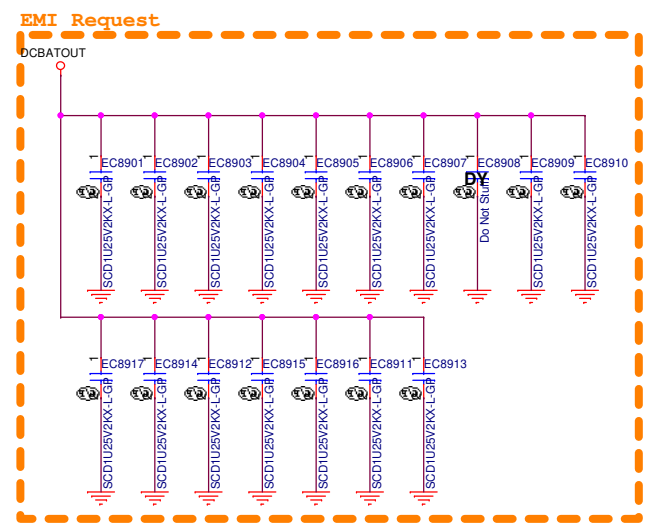
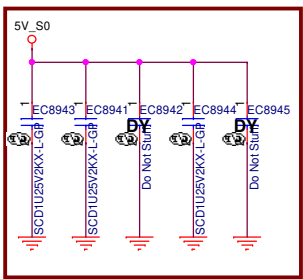
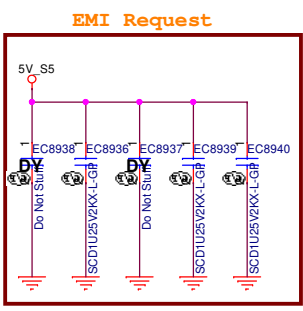
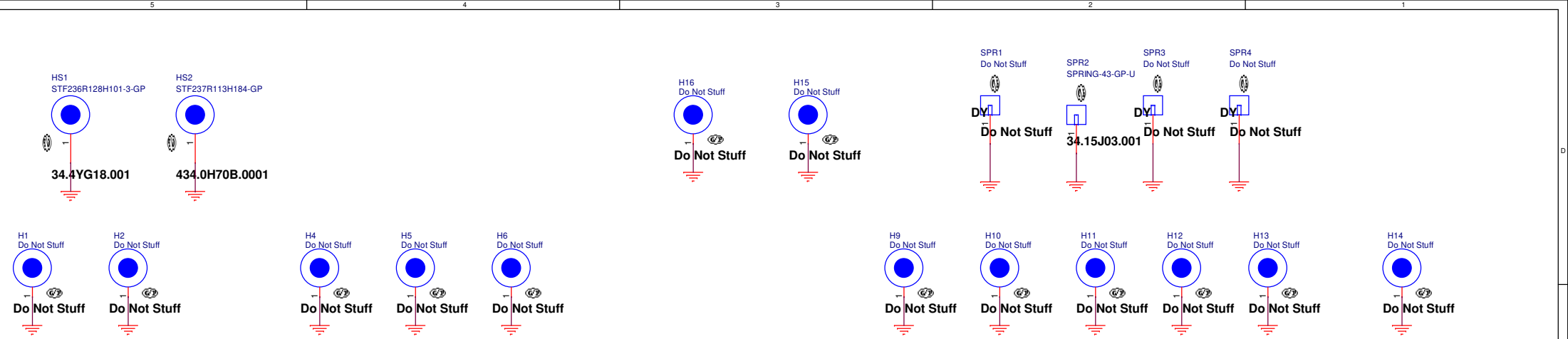
Power 1228



	TGP Current (GPU sku)	Rs1	Shunt in R1	Shunt out R1	Shunt out C1	Bus RT	Bus RB	Bus Cap	R Ref_out
Onsem	N18E-G3, N18E-G3 MAX-Q			169n					
	N18E-G2, N18E-G1, N18E-G1 MAX-Q			191n					
	N18E-G0, N18E-G0 MAX-Q	0.005a	100n	287n	15nF	750K	6.49K	100pF	
	NVDD Current	Rs2	Shunt in R2	Shunt out R2	Shunt out C2	Bus RT	Bus RB	Bus Cap	243K
	N18E-G3, N18E-G3 MAX-Q			169n					
	N18E-G2, N18E-G1, N18E-G1 MAX-Q			191n					
	N18E-G0, N18E-G0 MAX-Q	0.005a	100n	287n	15nF	750K	6.49K	100pF	
	NVDD Current	Rs2	Shunt in R2	Shunt out R2	Shunt out C2	Bus RT	Bus RB	Bus Cap	324K
	N18E-G3, N18E-G3 MAX-Q			127n					
	N18E-G2, N18E-G1, N18E-G1 MAX-Q			143n					
upi	N18E-G3, N18E-G3 MAX-Q			127n					
	N18E-G2, N18E-G1, N18E-G1 MAX-Q			143n					
	N18E-G0, N18E-G0 MAX-Q	0.005a	100n	215n	15nF	750K	4.87K	100pF	
	NVDD Current	Rs2	Shunt in R2	Shunt out R2	Shunt out C2	Bus RT	Bus RB	Bus Cap	324K
	N18E-G3, N18E-G3 MAX-Q			127n					
	N18E-G2, N18E-G1, N18E-G1 MAX-Q			143n					
	N18E-G0, N18E-G0 MAX-Q	0.005a	100n	215n	15nF	750K	4.87K	100pF	
	NVDD Current	Rs2	Shunt in R2	Shunt out R2	Shunt out C2	Bus RT	Bus RB	Bus Cap	324K
	N18E-G3, N18E-G3 MAX-Q			127n					
	N18E-G2, N18E-G1, N18E-G1 MAX-Q			143n					




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B				B
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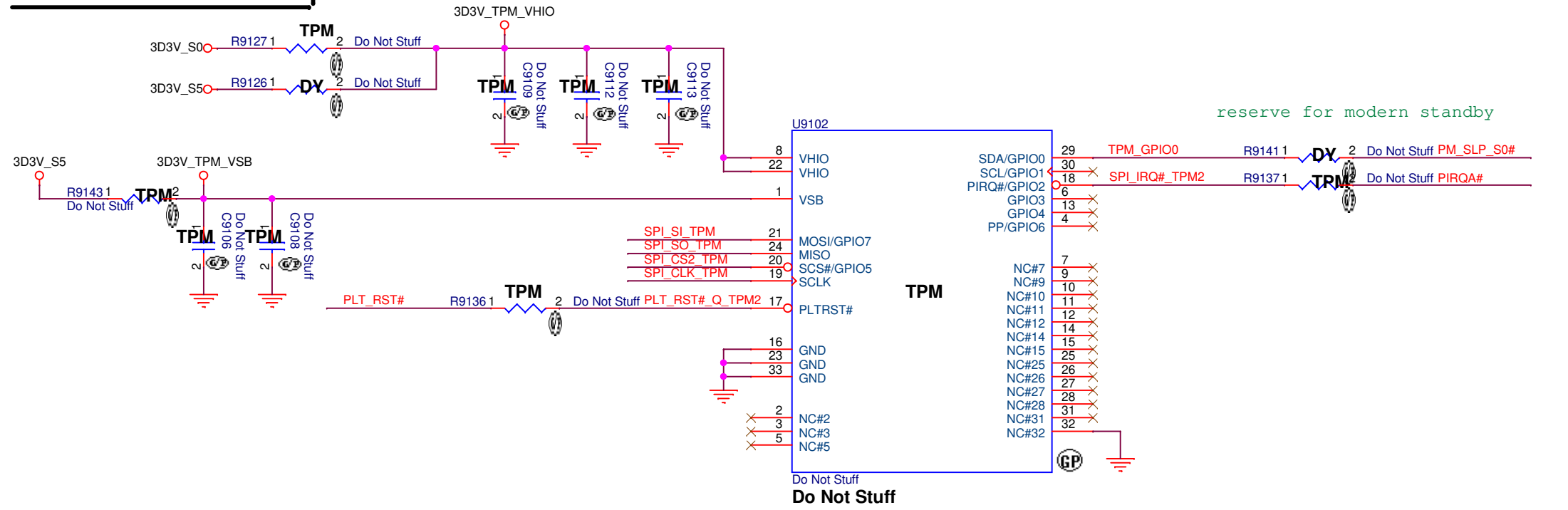
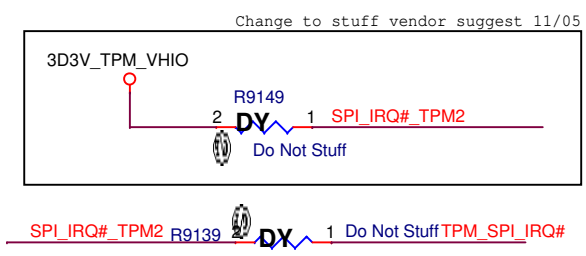
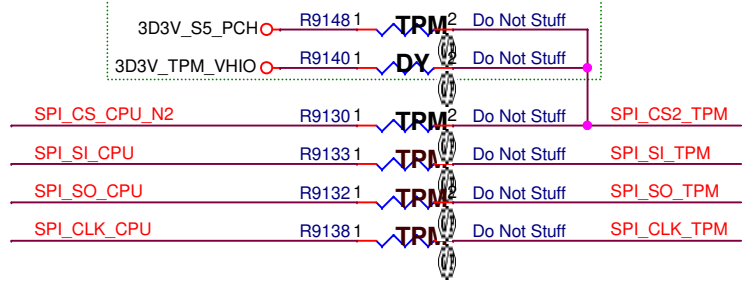
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SSID = TPM


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15	TPM_SPI_IRQ#	>>>	
31,61,63,79	PLT_RST#	>>>	
15,40	PM_SLP_S0#	>>>	
15	SPI_CS_CPU_N2	>>>	
15,21,25	SPI_SO_CPU	<<<	
15,21,25	SPI_SI_CPU	>>>	
15,25	SPI_CLK_CPU	>>>	

reserve RTC Gen 9 reset circuit_20170814
leakage issue



reserve for modern standby

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Title

TPM2.0

Size
A4

Document Number
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Rev
A00

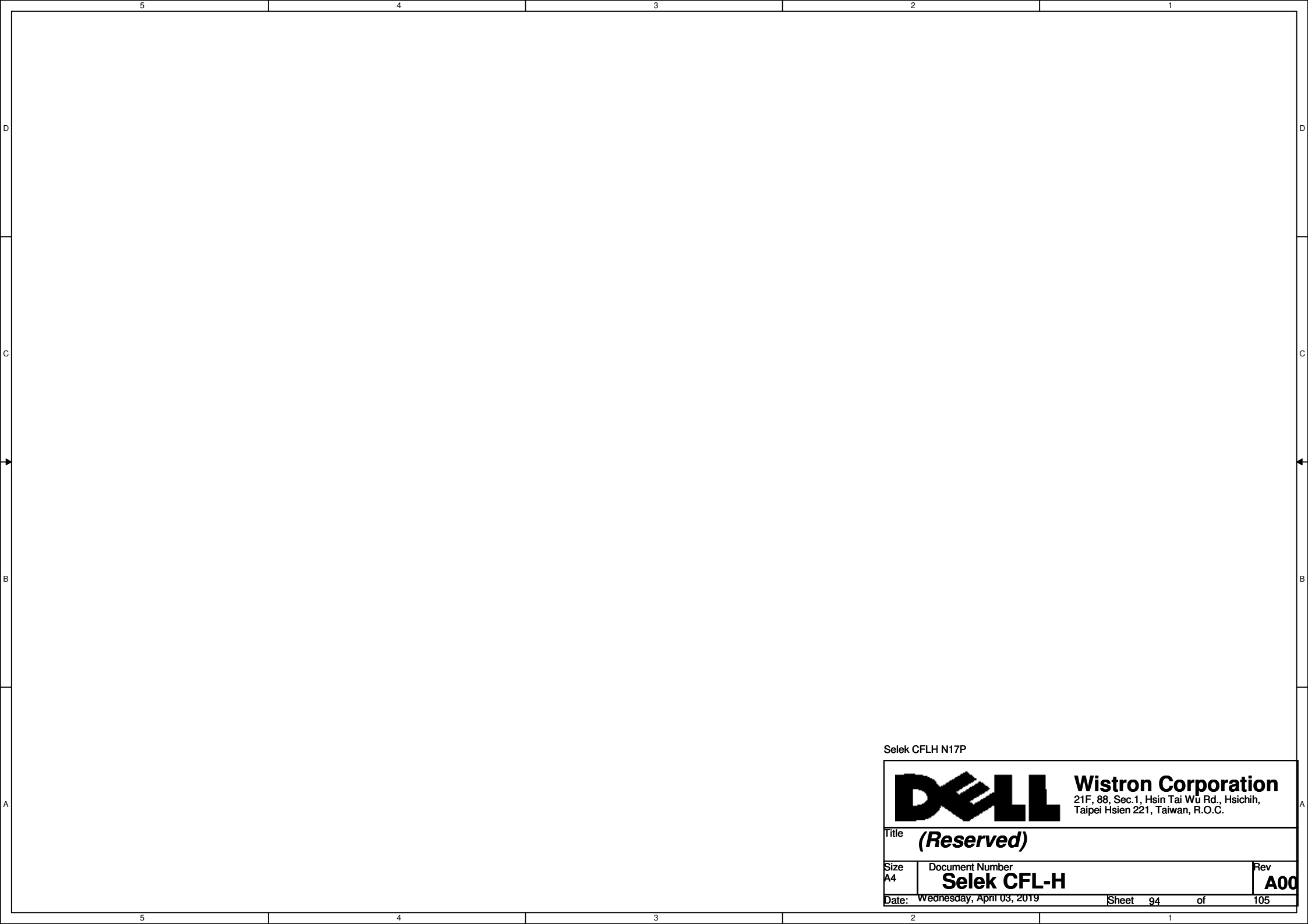
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Main Func = XDP

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Title CPU_XDP;PCH_XDP

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Title

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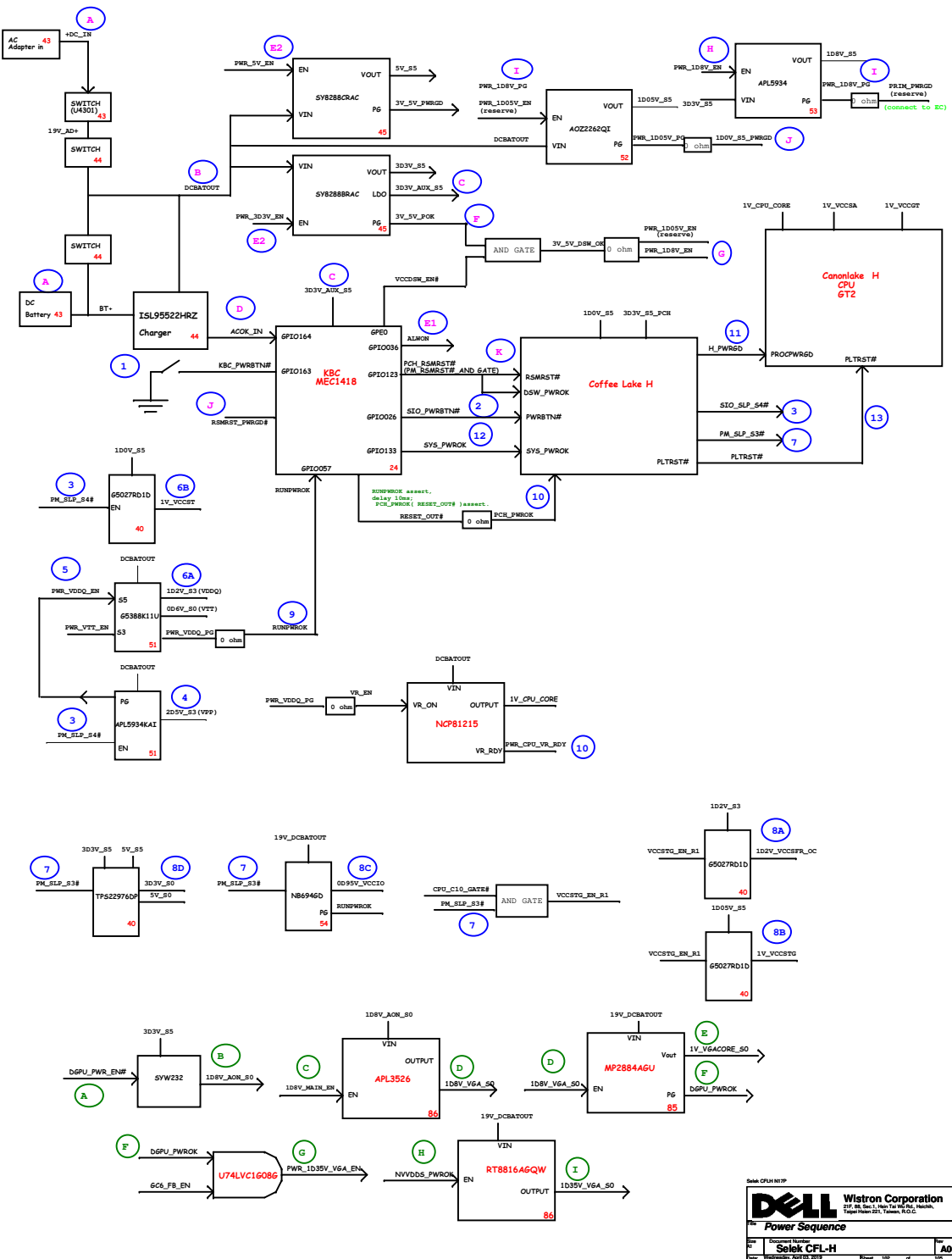
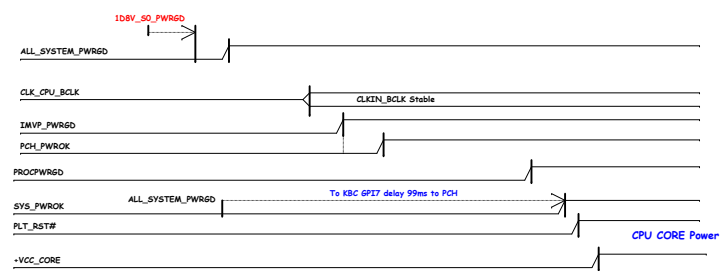
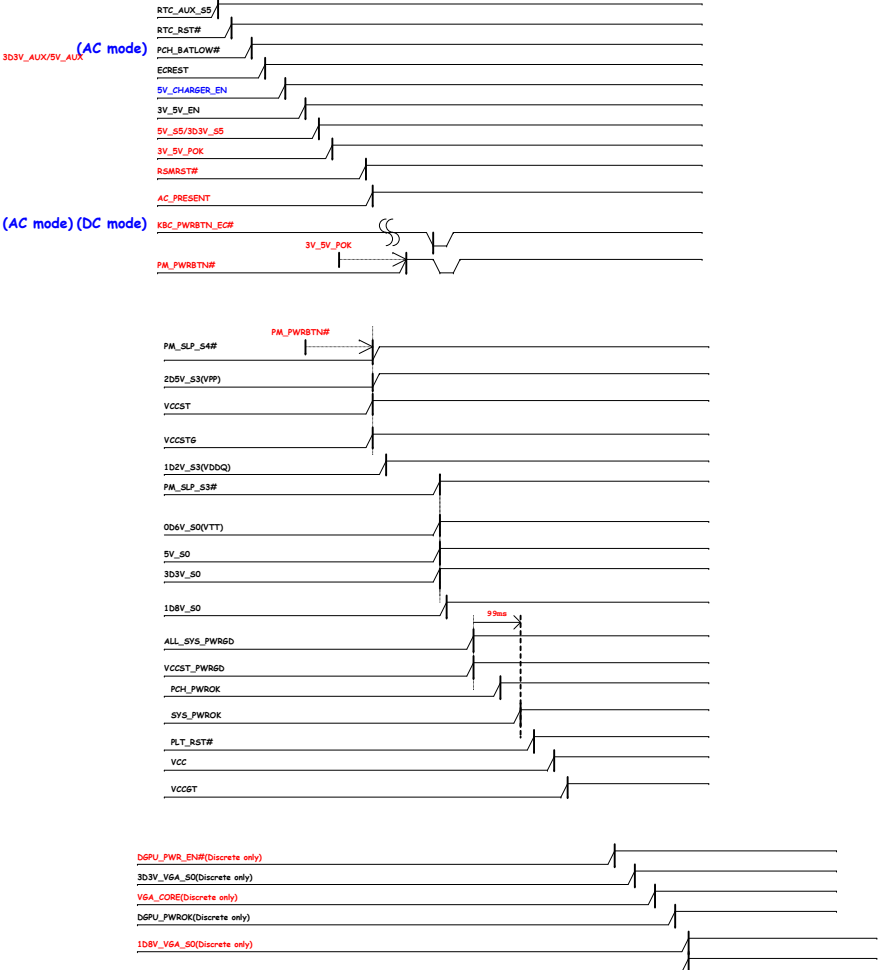
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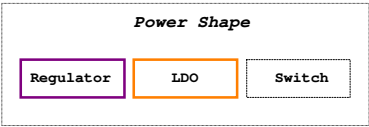
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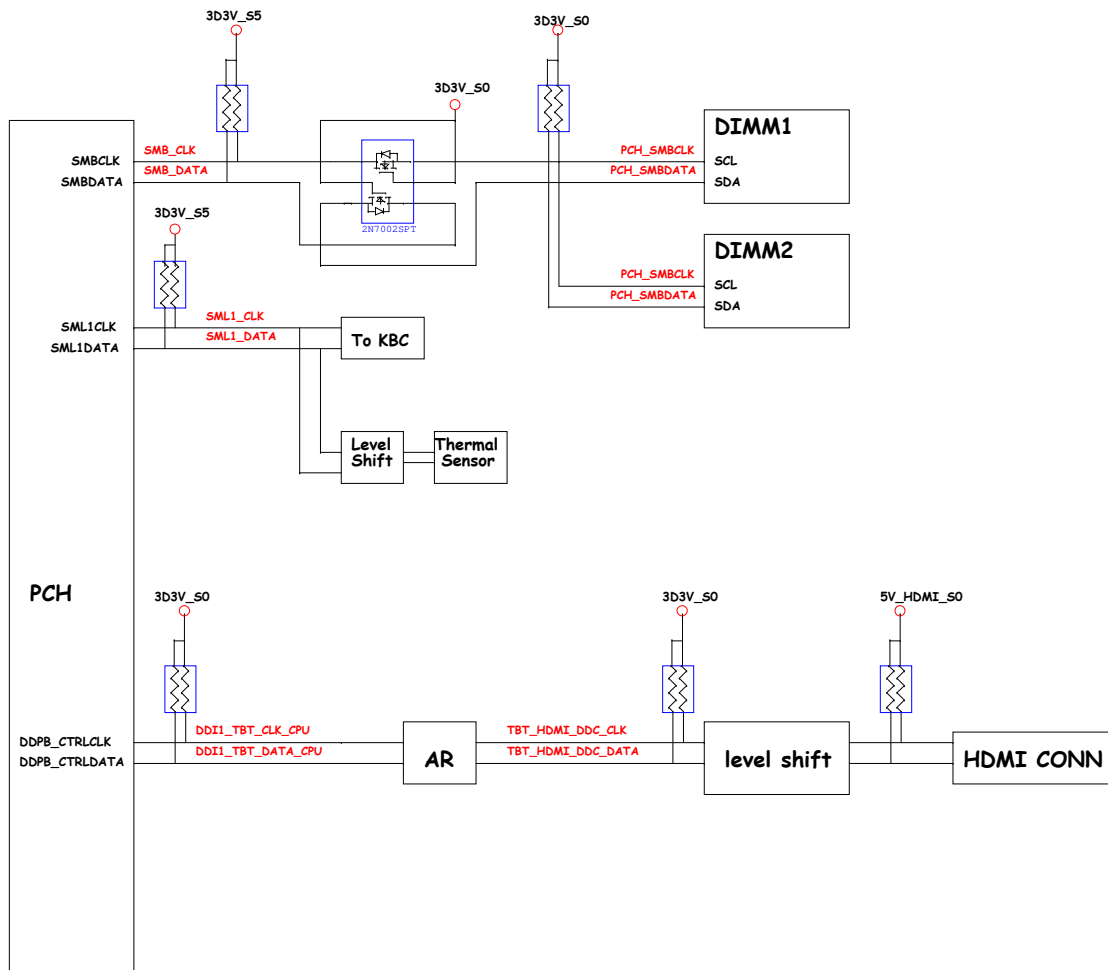
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Intel-Power Up Sequence

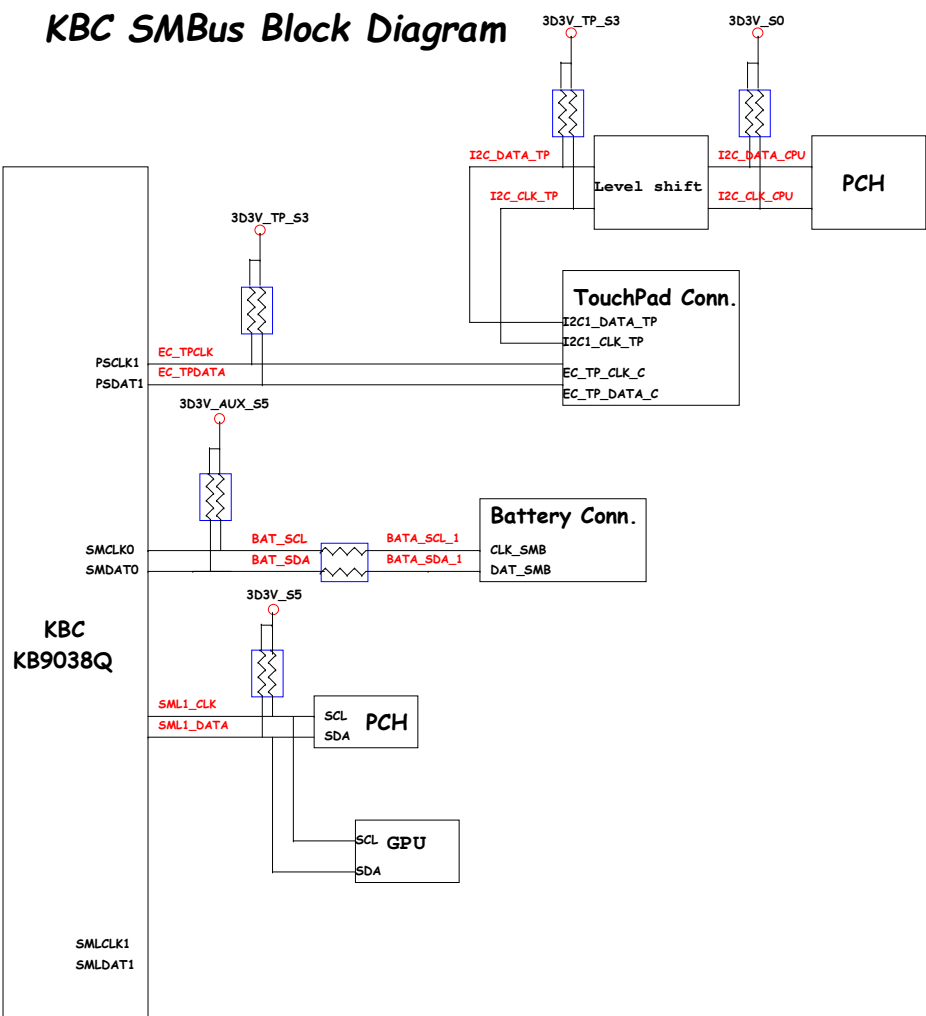




PCH SMBus Block Diagram



KBC SMBus Block Diagram



The schematic diagram illustrates the power and control connections for the KBC KB9028QA board. The main components and their connections are as follows:

- KBC KB9028QA:** The central component, with pins **VD_IN1** and **VD_OUT1** connected to external power sources. It also provides **FAN1_PWM** and **FAN2_PWM** signals to the fans.
- THEM Resistor:** Connected to **VD_IN1** and **VD_OUT1**.
- 2N7002:** A MOSFET used for fan control. Its gate (G) is connected to **VD_OUT1**. Its drain (D) is connected to **PURE_HW_SHUTDOWN#** and **IMVP_PWRGD**. Its source (S) is connected to **VR_RDY** and **3D3V_S0**.
- VR_RDY:** A signal line that is also connected to **3D3V_AUX_S5** and **3D3V_S0**.
- FAN1 and FAN2:** Two fans connected to the PWM signals from the KBC KB9028QA. They are powered by **5V_FAN1_S0** and **5V_FAN2_S0**.
- ECRST#:** A reset signal line connected to the KBC KB9028QA.

The diagram illustrates the connections for the **CODEC ALC299**. It shows the following components and their interconnections:

- CODEC ALC299** (Left side):
 - SPK-OUT-L- and SPK-OUT-L+ (connected to a **SPEAKER**)
 - SPK-OUT-R- and SPK-OUT-R+ (connected to a **SPEAKER**)
 - LINE2-L and LINE2-R (connected to the **AMP ALC1006**)
 - HPOUT-L/PORT-T-L and HPOUT-R/PORT-T-R (connected to a network of resistors and a capacitor, leading to the **HP OUT**)
 - LINE1-L and LINE1-R (connected to the same network of resistors and a capacitor, leading to the **HP OUT**)
 - SENSE_A (connected to the same network of resistors and a capacitor, leading to the **HP OUT**)
 - DMIC-CLK and DMIC-DATA (connected to a **DMIC**)
- AMP ALC1006** (Center):
 - OUT-L- and OUT-L+ (connected to a **SPEAKER**)
 - OUT-R- and OUT-R+ (connected to a **SPEAKER**)
- HP OUT** (Bottom right): Receives signals from the CODEC ALC299 through a network of resistors and a capacitor.
- DMIC** (Bottom right): Receives DMIC-CLK and DMIC-DATA signals from the CODEC ALC299.

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